

MDS-JE640

SERVICE MANUAL



Canadian Model
AEP Model
UK Model
E Model



Photo: SILVER

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Model Name Using Similar Mechanism	NEW
MD Mechanism Type	MDM-7A
Optical Pick-up Type	KMS-260B/J1N

SPECIFICATIONS

System	MiniDisc digital audio system
Disc	MiniDisc
Laser	Semiconductor laser ($\lambda = 780 \text{ nm}$) Emission duration: continuous
Laser output	MAX $44.6 \mu\text{W}^1$ <i>1) This output is the value measured at a distance of 200 mm from the objective lens surface on the Optical Pick-up Block with 7 mm aperture.</i>
Laser diode	Material: GaAlAs
Revolutions (CLV)	400 rpm to 900 rpm
Error correction	ACIRC (Advanced Cross Interleave Reed Solomon Code)
Sampling frequency	44.1 kHz
Coding	ATRAC (Adaptive TRansform Acoustic Coding)/ATRAC 3
Modulation system	EFM (Eight-to-Fourteen Modulation)
Number of channels	2 stereo channels
Frequency response	5 to 20,000 Hz $\pm 0.3 \text{ dB}$
Signal-to-noise ratio	Over 98 dB during play
Wow and flutter	Below measurable limit

Inputs	
ANALOG IN	Jack type: phono Impedance: $47 \text{ k}\Omega$ Rated input: 500 mVrms Minimum input: 125 mVrms
DIGITAL IN	Connector type: square optical Impedance: 660 nm (optical wave length)
DIGITAL OPTICAL IN (AEP, UK, CIS models)	Connector type: square optical Impedance: 660 nm (optical wave length)
DIGITAL COAXIAL IN (AEP, UK, CIS models)	Jack type: phono Impedance: 75Ω Rated input: 0.5 Vp-p, $\pm 20 \%$

Outputs	
PHONES (MDS-JE640 only)	Jack type: stereo phone Rated output: 28 mW Load impedance: 32Ω
ANALOG OUT	Jack type: phono Rated output: 2 Vrms (at 50 k Ω) Load impedance: over 10 k Ω

— Continued on next page —

MINIDISC DECK

SONY®

DIGITAL OUT	Connector type: square optical Rated output: -18 dBm Load impedance: 660 nm (optical wave length)	Power consumption Dimensions (approx.)	15 W 430 × 95 × 285 mm (17 × 3 3/4 × 11 1/4 in.) (w/h/d) incl. projecting parts and controls
DIGITAL OPTICAL OUT (AEP, UK, CIS models)	Connector type: square optical Rated output: -18 dBm Load impedance: 660 nm (optical wave length)	Mass (approx.)	3.1 kg (6 lbs 14 oz)

General

Power requirements

Where purchased	Power requirements
Canadian	120 V AC, 60 Hz
AEP, UK, CIS	220 – 230 V AC, 50/60 Hz
Singapore, Malaysia	110 – 120 or 220 – 240 V AC selectable, 50/60 Hz

Supplied accessories

- Audio connecting cords (2)
- Optical cable (1)
- Remote commander (remote) (1)
- R6 (size-AA) batteries (2)

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Design and specifications are subject to change without notice.

SELF-DIAGNOSIS FUNCTION

The self-diagnosis function consists of error codes for customers which are displayed automatically when errors occur, and error codes which show the error history in the test mode during servicing. For details on how to view error codes for the customer, refer to the following box in the instruction manual. For details on how to check error codes during servicing, refer to the following “Procedure for using the Self-Diagnosis Function (Error History Display Mode)”.

Self-diagnosis function

The deck’s self-diagnosis function automatically checks the condition of the MD deck when an error occurs, then issues a three- or five-digit code and an error message on the display. If the code and message alternate, find them in the following table and perform the indicated countermeasure. Should the problem persist, consult your nearest Sony dealer.

Three- or five-digit code/ Message	Cause/Remedy
C11/Protected	The inserted MD is record-protected. → Take out the MD and close the record-protect slot (page 14).
C12/Cannot Copy	You tried to record a CD with a format that the external device connected to the deck does not support, such as CD-ROM or video CD. → Remove the disc and insert a music CD.
C13/REC Error	The recording was not made properly. → Set the deck in a stable surface, and repeat the recording procedure.
	The inserted MD is dirty (with smudges, fingerprints, etc.), scratched, or substandard in quality. → Replace the disc and repeat the recording procedure.
C13/Read Error	The deck could not read the TOC on the MD properly. → Take out the MD and insert it again.

Three- or five-digit code/ Message	Cause/Remedy
C14/Toc Error	The deck could not read the TOC on the MD properly. → Insert another disc. → If possible, erase all the tracks on the MD (page 32).
C41/Cannot Copy	The sound source is a copy of commercially available music software, or you tried to record a CD-R (Recordable CD). → The Serial Copy Management System prevents making a digital copy (page 52). You cannot record a CD-R.
C71/Din Unlock	The sporadic appearance of this message is caused by the digital signal being recorded. This will not affect the recording.
E0001/ MEMORY NG	While recording from a digital component connected through the DIGITAL IN connector, the digital connecting cable was unplugged or the digital component turned off. → Connect the cable or turn the digital component back on.
E0101/ LASER NG	There is an error in the internal data that the deck needs in order to operate. → Consult your nearest Sony dealer.

Procedure for using the Self-Diagnosis Function (Error History Display Mode).

Note: Perform the self-diagnosis function in the “error history display mode” in the test mode. The following describes the least required procedure. Be careful not to enter other modes by mistake. If you set other modes accidentally, press the [MENU/NO] button to exit the mode.

1. While pressing the [AMS] knob and [] button, connect the power plug to the outlet, and release the [AMS] knob and [] button.
When the test mode is set, “[Check]” will be displayed.
2. Rotate the [AMS] knob and when “[Service]” is displayed, press the [YES] button.
3. Rotate the [AMS] knob and display “Err Display”.
4. Pressing the [YES] button sets the error history mode and displays “op rec tm”.
5. Select the contents to be displayed or executed using the [AMS] knob.
6. Pressing the [AMS] knob will display or execute the contents selected.
7. Pressing the [AMS] knob another time returns to step 4.
8. Pressing the [MENU/NO] button displays “Err Display” and exits the error history mode.
9. To exit the test mode, press the [REPEAT] button. The unit sets into the STANDBY state, the disc is ejected, and the test mode ends.

ITEMS OF ERROR HISTORY MODE ITEMS AND CONTENTS

Selecting the Test Mode

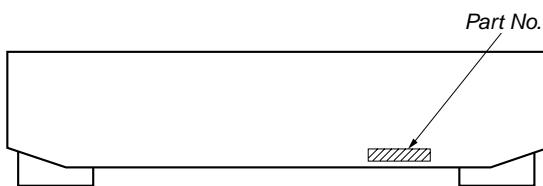
Display	History
op rec tm	Displays the total recording time. When the total recording time is more than 1 minute, displays the hour and minute When less than 1 minute, displays “Under 1 min” The display time is the time the laser is set to high power, which is about 1/4 of the actual recording time.
op play tm	Displays the total playback time. When the total playback time is more than 1 minute, displays the hour and minute When less than 1 minute, displays “Under 1 min”
spdl rp tm	Displays the total rotating time of the spindle motor. When the total rotating time is more than 1 minute, displays the hour and minute When less than 1 minute, displays “Under 1 min”
retry err	Displays the total number of retry errors during recording and playback Displays “r xx p yy”. xx is the number of errors during recording. yy is the number of errors during playback. This is displayed in hexadecimal from 00 to FF.
total err	Displays the total number of errors Displays “total xx”. This is displayed in hexadecimal from 00 to FF.
err history	Displays the past ten errors. Displays “0x ErrCd@@”. X is the history number. The younger the number, the more recent is the history (00 is the latest). @@ is the error code. Select the error history number using the AMS knob.
retry adrs	Displays the past five retry addresses. Displays “xx ADRS yyyy”, xx is the history number, yyyy is the cluster with the retry error. Select the error history number using the AMS knob.
er refresh	Mode for erasing the error and retry address histories Procedure 1. Press the AMS knob when displayed as “er refresh”. 2. Press the YES button when the display changes to “er refresh?”. When “complete!” is displayed, it means erasure has completed. Be sure to check the following after executing this mode. *Data has been erased. *Perform recording and playback, and check that the mechanism is normal.
op change	Mode for erasing the total time of op rec tm, op play tm. These histories are based on the time of replacement of the optical pickup. If the optical pick-up has been replaced, perform this procedure and erase the history. Procedure 1. Press the AMS knob when displayed as “op change”. 2. Press the YES button when the display changes to “op change?”. When “Complete!” is displayed, it means erasure has completed.
spdl change	Mode for erasing the total spdl rp tm time These histories are based on the time of replacement of the spindle motor. If the spindle motor has been replaced, perform this procedure and erase the history. Procedure 1. Press the AMS knob when displayed as “spdl change” 2. Press the YES button when the display changes to “spdl change?”. When “Complete!” is displayed, it means erasure has completed.

Table of Error Codes

Error Code	Description
10	Could not load
12	Loading switches combined incorrectly
20	Timed out without reading the top of PTOC
21	Could read top of PTOC, but detected error
22	Timed out without accessing UTOC
23	Timed out without reading UTOC
24	Error in UTOC
30	Could not start playback
31	Error in sector
40	Retry cause generated during normal recording
41	Retried in DRAM overflow
42	Retry occurred during TOC writing
43	Retry aborted during S.F editing
50	Other than access processing, and could not read address.
51	Focus NG occurred and overran.

MODEL IDENTIFICATION

— BACK PANEL —



MODEL	PARTS No.
AEP, UK, CIS models	4-228-638-0□
Canadian model	4-228-638-3□
SP, MY models	4-228-638-4□

- Abbreviation

SP	: Singapore model
MY	: Malaysia model

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SECTION 1

SERVICE NOTES

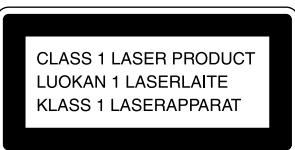
NOTES ON HANDLING THE OPTICAL PICK-UP BLOCK OR BASE UNIT

The laser diode in the optical pick-up block may suffer electrostatic break-down because of the potential difference generated by the charged electrostatic load, etc. on clothing and the human body. During repair, pay attention to electrostatic break-down and also use the procedure in the printed matter which is included in the repair parts. The flexible board is easily damaged and should be handled with care.

NOTES ON LASER DIODE EMISSION CHECK

Never look into the laser diode emission from right above when checking it for adjustment. It is feared that you will lose your sight.

Laser component in this product is capable of emitting radiation exceeding the limit for Class 1.



This appliance is classified as a CLASS 1 LASER product. The CLASS 1 LASER PRODUCT MARKING is located on the rear exterior.



This caution label is located inside the unit.

CAUTION
Use of controls or adjustments or performance of procedures other than those specified herein may result in hazardous radiation exposure.

Notes on chip component replacement

- Never reuse a disconnected chip component.
- Notice that the minus side of a tantalum capacitor may be damaged by heat.

Flexible Circuit Board Repairing

- Keep the temperature of soldering iron around 270°C during repairing.
- Do not touch the soldering iron on the same conductor of the circuit board (within 3 times).
- Be careful not to apply force on the conductor when soldering or unsoldering.

SAFETY-RELATED COMPONENT WARNING!!

COMPONENTS IDENTIFIED BY MARK △ OR DOTTED LINE WITH MARK △ ON THE SCHEMATIC DIAGRAMS AND IN THE PARTS LIST ARE CRITICAL TO SAFE OPERATION. REPLACE THESE COMPONENTS WITH SONY PARTS WHOSE PART NUMBERS APPEAR AS SHOWN IN THIS MANUAL OR IN SUPPLEMENTS PUBLISHED BY SONY.

ATTENTION AU COMPOSANT AYANT RAPPORT À LA SÉCURITÉ!

LES COMPOSANTS IDENTIFÉS PAR UNE MARQUE △ SUR LES DIAGRAMMES SCHÉMATIQUES ET LA LISTE DES PIÈCES SONT CRITIQUES POUR LA SÉCURITÉ DE FONCTIONNEMENT. NE REMPLACER CES COMPOSANTS QUE PAR DES PIÈCES SONY DONT LES NUMÉROS SONT DONNÉS DANS CE MANUEL OU DANS LES SUPPÉMENTS PUBLIÉS PAR SONY.

JIG FOR CHECKING BD BOARD WAVEFORM

The special jig (J-2501-196-A) is useful for checking the waveform of the BD board. The names of terminals and the checking items to be performed are shown as follows.

GND : Ground

I+3V : For measuring IOP (Check the deterioration of the optical pick-up laser)

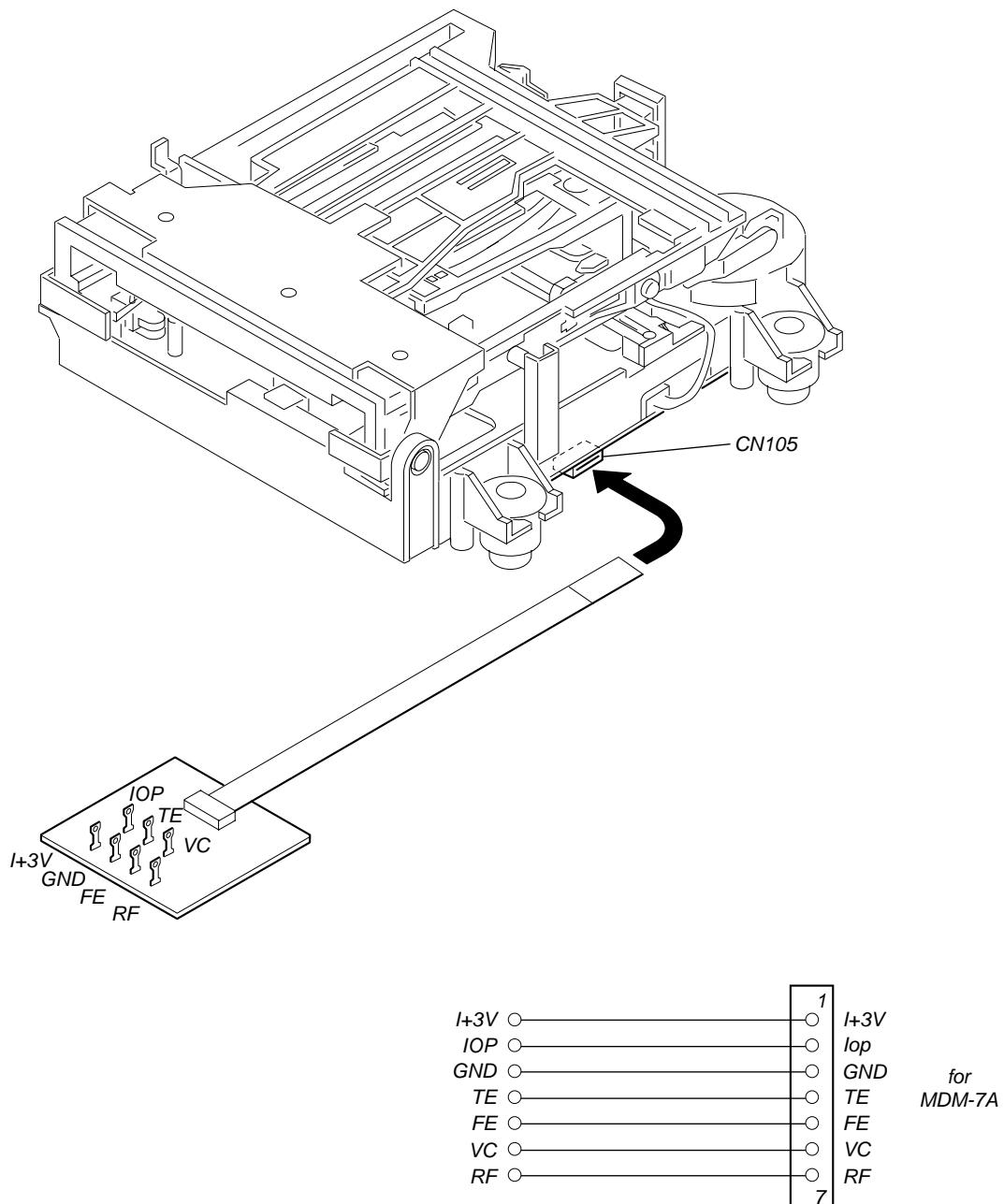
IOP : For measuring IOP (Check the deterioration of the optical pick-up laser)

TE : TRK error signal (Traverse adjustment)

VC : Reference level for checking the signal

RF : RF signal (Check jitter)

FE : Focus error signal



Iop DATA RECORDING AND DISPLAY WHEN OPTICAL PICK-UP AND NON-VOLATILE MEMORY (IC195 OF BD BOARD) ARE REPLACED

The Iop value labeled on the optical pick-up can be recorded in the non-volatile memory. By recording the value, it will eliminate the need to look at the value on the label of the optical pick-up. When replacing the optical pick-up or non-volatile memory (IC195 of BD board), record the Iop value on the optical pick-up according to the following procedure.

Record Procedure:

1. While pressing the **[◀◀ AMS ▶▶]** knob and **[■]** button, connect the power plug to the outlet, and release the **[◀◀ AMS ▶▶]** knob and **[■]** button.
2. Rotate the **[◀◀ AMS ▶▶]** knob to display “[Service]”, and press the **[YES]** button.
3. Rotate the **[◀◀ AMS ▶▶]** knob to display “Iop Write” (C05), and press the **[YES]** button.
4. The display becomes “Ref=@@.@” (@ is an arbitrary number) and the numbers which can be changed will blink.
5. Input the Iop value written on the optical pick-up.
To select the number : Rotate the **[◀◀ AMS ▶▶]** knob.
To select the digit : Press the **[◀◀ AMS ▶▶]** knob.
6. When the **[YES]** button is pressed, the display becomes “Measu=@@.@” (@ is an arbitrary number).
7. As the adjustment results are recorded for the 6 value. Leave it as it is and press the **[YES]** button.
8. “Complete!” will be displayed momentarily. The value will be recorded in the non-volatile memory and the display will become “Iop Write”.
9. Press the **[REPEAT]** button to complete.

Display Procedure:

1. While pressing the **[◀◀ AMS ▶▶]** knob and **[■]** button, connect the power plug to the outlet, and release the **[◀◀ AMS ▶▶]** knob and **[■]** button.
2. Rotate the **[◀◀ AMS ▶▶]** knob to display “[Service]”, and press the **[YES]** button.
3. Rotate the **[◀◀ AMS ▶▶]** knob to display “Iop Read” (C26).
4. “@@.@@/#.#” is displayed and the recorded contents are displayed.
@@.@@ : indicates the Iop value labeled on the pick-up.
#.#. : indicates the Iop value after adjustment
5. To end, press the **[◀◀ AMS ▶▶]** button or **[MENU/NO]** button to display “Iop Read”. Then press the **[REPEAT]** button.

CHECKS PRIOR TO PARTS REPLACEMENT AND ADJUSTMENTS

Before performing repairs, perform the following checks to determine the faulty locations up to a certain extent.
Details of the procedures are described in "5 Electrical Adjustments".

- 5-6-2. Laser power check (see page 23)
- 5-6-3. Iop Compare (see page 23)
- 5-6-4. Auto Check (see page 24)

Note:

The criteria for determination above is intended merely to determine if satisfactory or not, and does not serve as the specified value for adjustments.

When performing adjustments, use the specified values for adjustments.

FORCED RESET

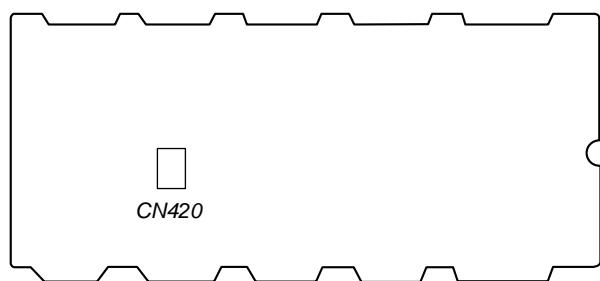
The system microprocessor can be reset in the following procedure.

Use these procedure when the unit cannot be operated normally due to the overrunning of the microprocessor, etc.

Procedure :

Remove the short-pin attached to CN420, and then attach it again.

[MAIN BOARD] (Component Side)



RETRY CAUSE DISPLAY MODE

- In this test mode, the causes for retry of the unit during recording can be displayed on the fluorescent indicator tube. During playback, the "track mode" for obtaining track information will be set.
This is useful for locating the faulty part of the unit.
- The following will be displayed :
During recording and stop : Retry cause, number of retries, and number of retry errors.
During playback : Information such as type of disc played, part played, copyright.
These are displayed in hexadecimal.

Procedure:

- Procedure 1: Press the [] button continuously for about 10 seconds.
- Procedure 2: Press the [LEVEL/DISPLAY/CHAR] button while pressing the [] button and [MENU/NO] button.
- When the mode is set, "RTs 00c 00e 000" is displayed.
- Press the [● REC] button to start recording. Then press the [II] button and start recording.
- To check the "track mode", press the [▷] button to start play.
- To exit the test mode, press the [VOL] button, and turn OFF the power. When "TOC" disappears, disconnect the power plug from the outlet.
If the test mode cannot be exited, refer to "Forced Reset" on page 8.

**Fig. 1 Reading the Test Mode Display
(During recording and stop)**

Fluorescent display tube display

RTs@#c##c***
#@ : Cause of retry
: Number of retries
*** : Number of retry errors

**Fig. 2 Reading the Test Mode Display
(During playback)**

Fluorescent display tube display

@@ : Parts No. (name of area named on TOC)
: Cluster
** : Sector } Address (Physical address on disc)
\$\$: Track mode (Track information such as copyright information of each part)

Reading the Retry Cause Display

Hexadecimal	Higher Bits				Lower Bits				Hexa-decimal	Cause of Retry	Occurring conditions
	8	4	2	1	8	4	2	1			
Bit	b7	b6	b5	b4	b3	b2	b1	b0			
Binary	0	0	0	0	0	0	0	1	01	shock	When track jump (shock) is detected
	0	0	0	0	0	0	1	0	02	ader5	When ADER was counted more than five times continuously
	0	0	0	0	0	1	0	0	04	Discontinuous address	When ADIP address is not continuous
	0	0	0	0	1	0	0	0	08	DIN unlock	When DIN unlock is detected
	0	0	0	1	0	0	0	0	10	FCS incorrect	When not in focus
	0	0	1	0	0	0	0	0	20	IVR rec error	When ABCD signal level exceeds the specified range
	0	1	0	0	0	0	0	0	40	CLV unlock	When CLV is unlocked
	1	0	0	0	0	0	0	0	80	Access fault	When access operation is not performed normally

Reading the Display:

Convert the hexadecimal display into binary display. If more than two causes, they will be added.

Example

When 42 is displayed:

Higher bit : 4 = 0100 → b6

Lower bit : 2 = 0010 → b1

In this case, the retry cause is combined of "CLV unlock" and "ader5".

When A2 is displayed:

Higher bit : A = 1010 → b7+b5

Lower bit : 2 = 0010 → b2

The retry cause in this case is combined of "access fault", "IVR rec error", and "ader5".

Reading the Track Mode Display

Hexadecimal	Higher Bits				Lower Bits				Hexa-decimal	Details	
	8	4	2	1	8	4	2	1		When 0	When 1
Bit	b7	b6	b5	b4	b3	b2	b1	b0			
Binary	0	0	0	0	0	0	0	1	01	Emphasis OFF	Emphasis ON
	0	0	0	0	0	0	1	0	02	Monaural	Stereo
	0	0	0	0	0	1	0	0	04	This is 2-bit display. Normally 01.	
	0	0	0	0	1	0	0	0	08	01:Normal audio. Others:Invalid	
	0	0	0	1	0	0	0	0	10	Audio (Normal)	Invalid
	0	0	1	0	0	0	0	0	20	Original	Digital copy
	0	1	0	0	0	0	0	0	40	Copyright	No copyright
	1	0	0	0	0	0	0	0	80	Write prohibited	Write allowed

Reading the Display:

Convert the hexadecimal display into binary display. If more than two causes, they will be added.

Example When 84 is displayed:

Higher bit : 8 = 1000 → b7

Lower bit : 4 = 0100 → b2

In this case, as b2 and b7 are 1 and others are 0, it can be determined that the retry cause is combined of “emphasis OFF”, “monaural”, “original”, “copyright exists”, and “write allowed”.

Example When 07 is displayed:

Higher bit : 0 = 1000 → All 0

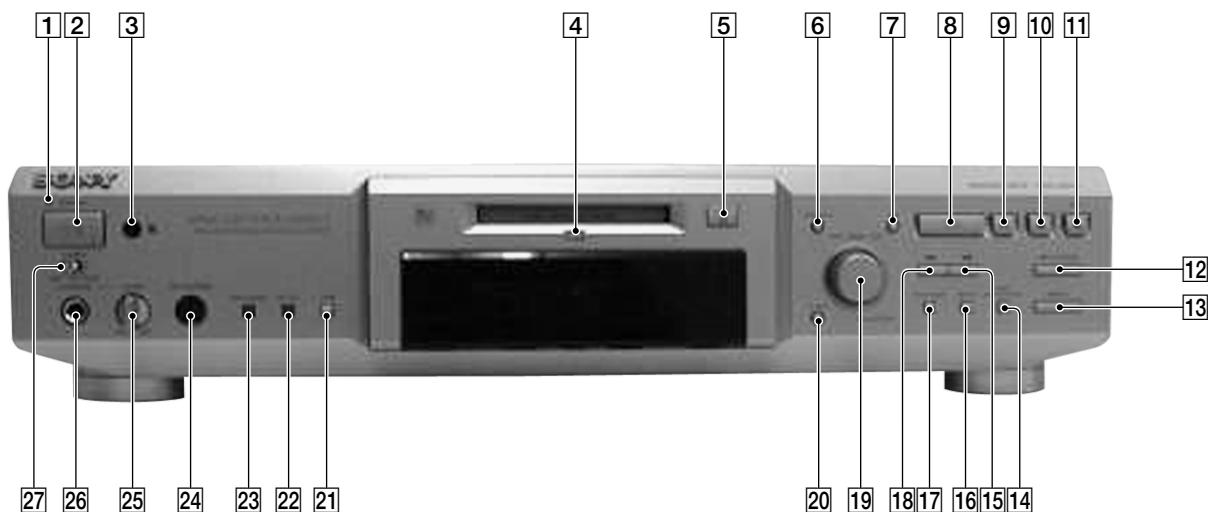
Lower bit : 7 = 0111 → b0+b1+b2

In this case, as b0, b1, and b2 are 1 and others are 0, it can be determined that the retry cause is combined of “emphasis ON”, “stereo”, “original”, “copyright exists”, and “write prohibited”.

Hexadecimal → Binary Conversion Table

Hexadecimal	Binary	Hexadecimal	Binary
0	0000	8	1000
1	0001	9	1001
2	0010	A	1010
3	0011	B	1011
4	0100	C	1100
5	0101	D	1101
6	0110	E	1110
7	0111	F	1111

SECTION 2 GENERAL

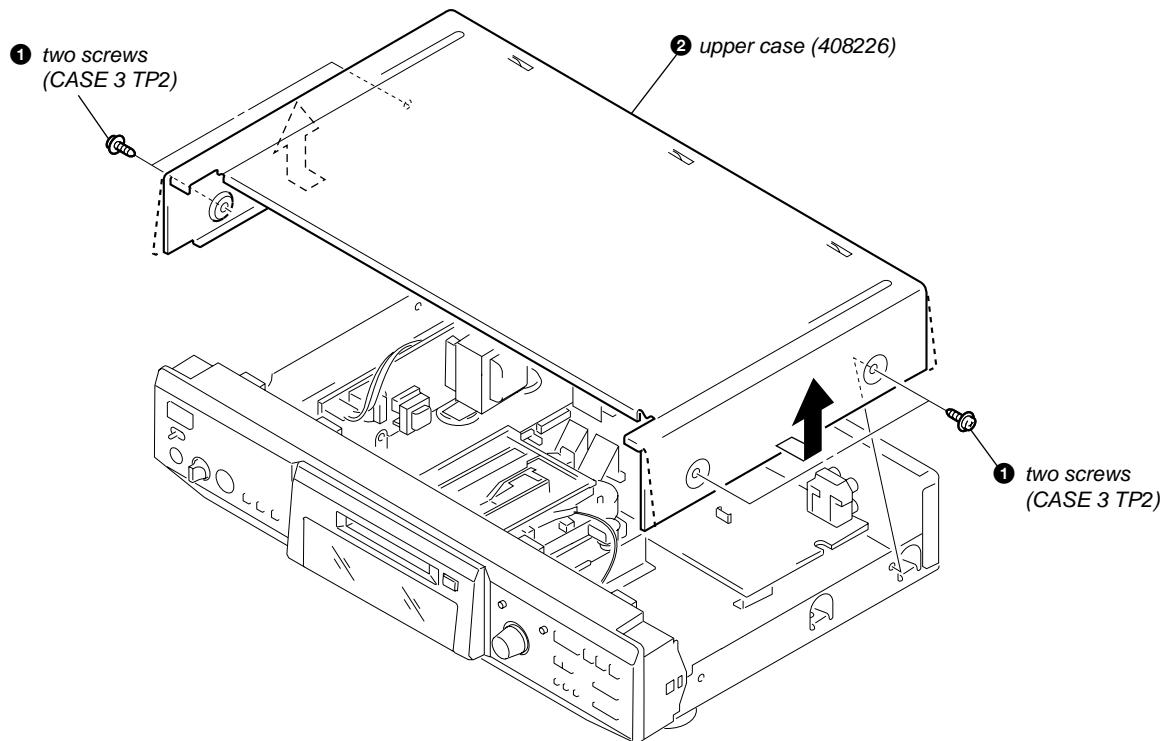


- | | | | |
|-------------|---------------------------|-------------|------------------------------------|
| [1] | STANDBY indicator | [15] | ▷▷ button |
| [2] | ■/□ (power) button | [16] | REPEAT button |
| [3] | Remote sensor | [17] | PLAY MODE button |
| [4] | MDLP indicator | [18] | ◀◀ button |
| [5] | ⏏ EJECT button | [19] | ◀◀ AMS ▷▷ /PUSH ENTER button |
| [6] | MENU/NO button | [20] | CLEAR button |
| [7] | YES button | [21] | TIME button |
| [8] | ▷ button | [22] | SF EDIT button and indicator |
| [9] | □ button | [23] | PITCH CONTROL button and indicator |
| [10] | □ button | [24] | KEYBOARD jack |
| [11] | ● REC button | [25] | LEVEL knob |
| [12] | REC MODE button | [26] | PHONES jack |
| [13] | INPUT button | [27] | TIMER knob |
| [14] | LEVEL/DISPLAY/CHAR button | | |

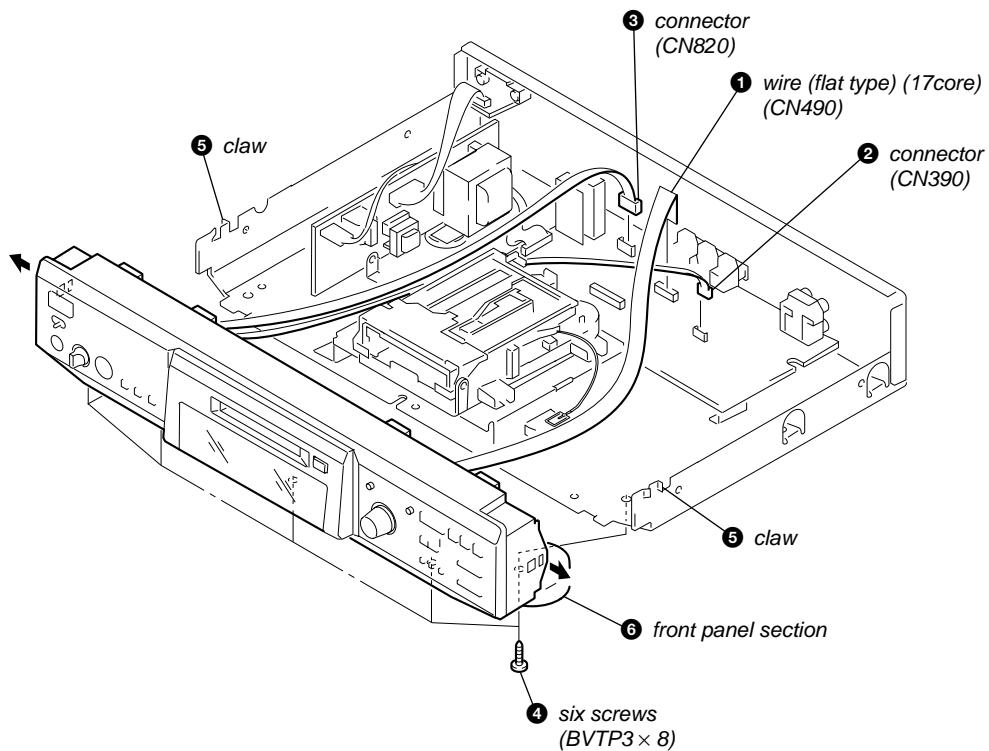
SECTION 3 DISASSEMBLY

Note : Follow the disassembly procedure in the numerical order given.

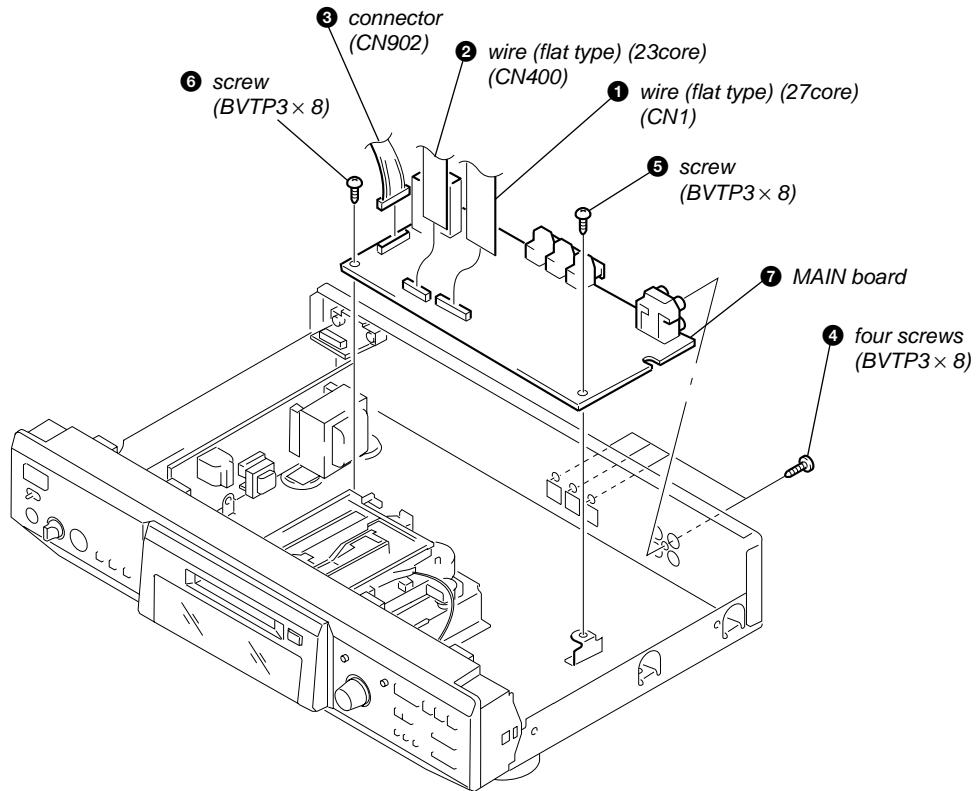
3-1. UPPER CASE (408226)



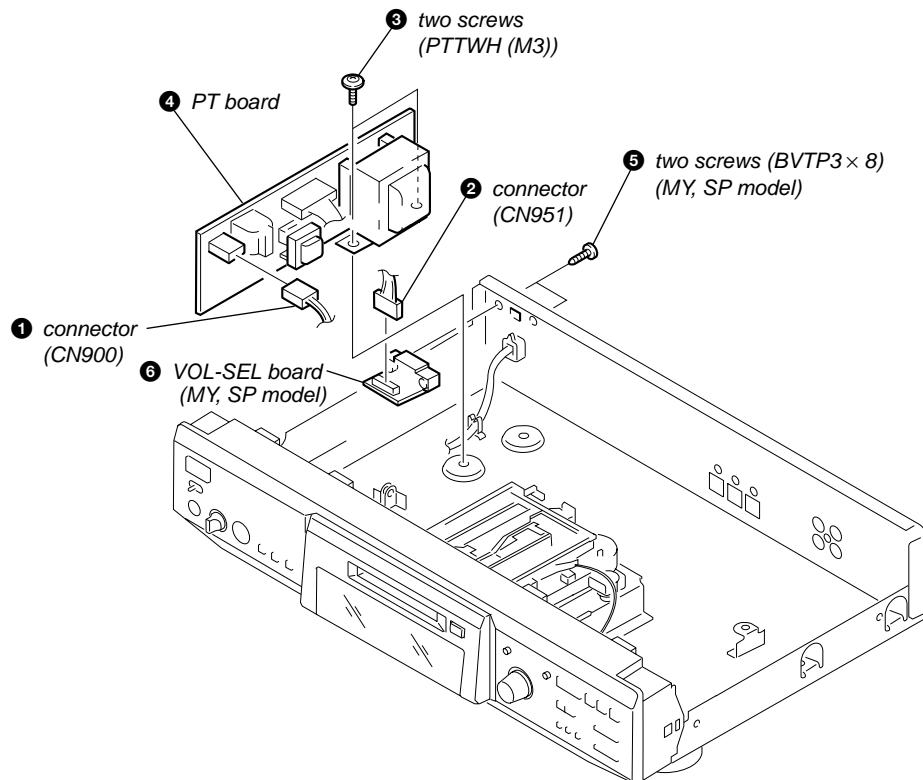
3-2. FRONT PANEL SECTION



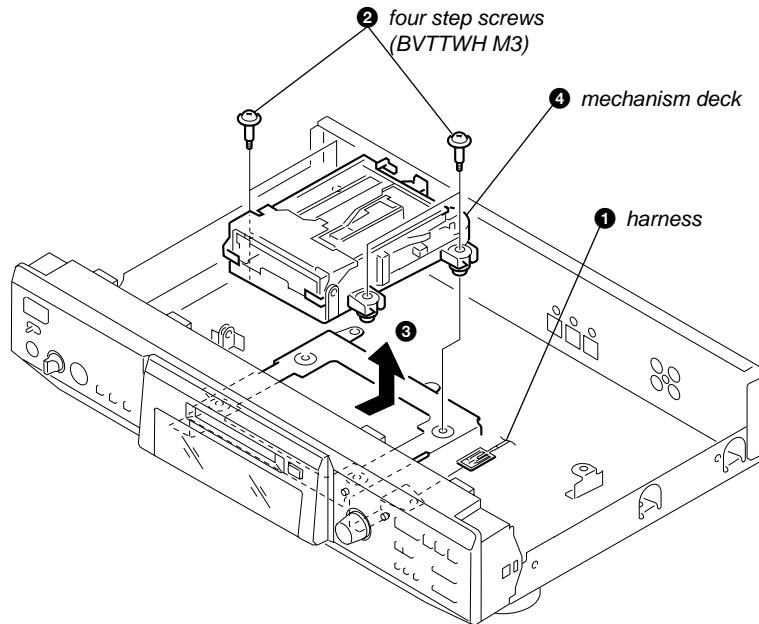
3-3. MAIN BOARD



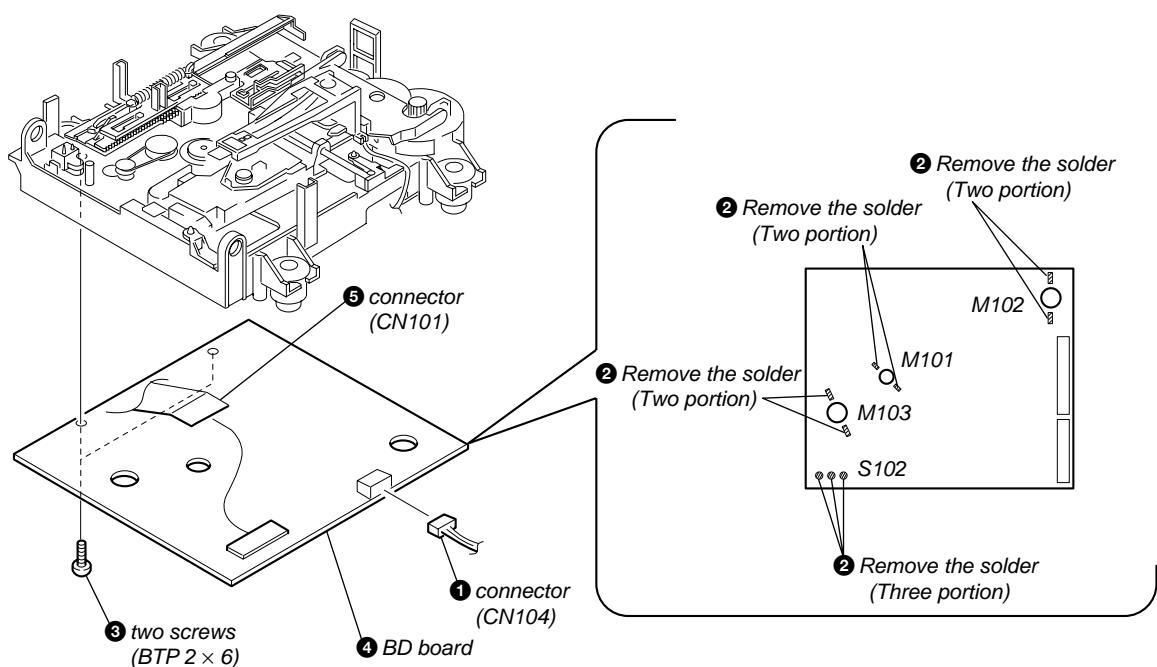
3-4. PT BOARD, VOL-SEL BOARD



3-5. MECHANISM DECK SECTION (MDM-7A)



3-6. BD BOARD



SECTION 4 TEST MODE

4-1. PRECAUTIONS FOR USE OF TEST MODE

- As loading related operations will be performed regardless of the test mode operations being performed, be sure to check that the disc is stopped before setting and removing it.
- Even if the [EJECT] button is pressed while the disc is rotating during continuous playback, continuous recording, etc., the disc will not stop rotating.
- Therefore, it will be ejected while rotating.

Be sure to press the [EJECT] button after pressing the [MENU/NO] button and the rotation of disc is stopped.

4-1-1. Recording laser emission mode and operating buttons

- Continuous recording mode (CREC 1MODE)
- Laser power check mode (LDPWR CHECK)
- Laser power adjustment mode (LDPWR ADJUS)
- Iop check (Iop Compare)
- Iop value nonvolatile writing (Iop NV Save)
- Traverse (MO) check (EF MO CHECK)
- Traverse (MO) adjustment (EF MO ADJUS)
- When pressing the [REC] button.

4-2. SETTING THE TEST MODE

The following are two methods of entering the test mode.

Procedure 1: While pressing the [AMS] knob and [] button, connect the power plug to an outlet, and release the [AMS] knob and [] button.
When the test mode is set, “[Check]” will be displayed. Rotating the [AMS] knob switches between the following three groups;
... ↔ Check ↔ Service ↔ Develop ↔ ...

Procedure 2: While pressing the [AMS] knob, connect the power plug to the outlet and release the [AMS] knob.

When the test mode is set, “TEMP CHECK” will be displayed. By setting the test mode using this method, only the “Check” group of method 1 can be executed.

NOTE: Do not use the test mode in the [Develop] group.

If used, the unit may not operate normally.

If the [Develop] group is set accidentally, press the [MENU/NO] button immediately to exit the [Develop] group.

4-3. EXITING THE TEST MODE

Press the [REPEAT] button. The disc is ejected when loaded, and “Standby” display blinks, and the STANDBY state is set.

4-4. BASIC OPERATIONS OF THE TEST MODE

All operations are performed using the [AMS] knob, [YES] button, and [MENU/NO] button.

The functions of these buttons are as follows.

Function name		Function
MENU/NO button		Cancel or move to top hierarchy
YES button		Set
AMS knob	Left or Right	Select
	Push	Set submenu

4-5. SELECTING THE TEST MODE

There are 25 types of test modes as shown below. The groups can be switched by rotating the [AMS] knob. After selecting the group to be used, press the [YES] button. After setting a certain group, rotating the [AMS] knob switches between these modes.

Refer to “Group” in the table for details selected.

All adjustments and checks during servicing can be performed in the test mode in the Service group.

NOTE: Do not use the test mode in the [Develop] group.

If used, the unit may not operate normally.

If the [Develop] group is set accidentally, press the [MENU/NO] button immediately to exit the [Develop] group.

Display	No.	Details	Mark	Group	
				Check	Service
AUTO CHECK	C01	Automatic self-diagnosis			<input type="radio"/>
Err Display	C02	Error history display, clear			<input type="radio"/>
TEMP ADJUS	C03	Temperature compensation offset adjustment			<input type="radio"/>
LDPWR ADJUS	C04	Laser power adjustment			<input type="radio"/>
Iop Write	C05	Iop data writing			<input type="radio"/>
Iop NV Save	C06	Writes current Iop value in read nonvolatile memory using microprocessor			<input type="radio"/>
EF MO ADJUS	C07	Traverse (MO) adjustment			<input type="radio"/>
EF CD ADJUS	C08	Traverse (CD) adjustment			<input type="radio"/>
FBIAS ADJUS	C09	Focus bias adjustment			<input type="radio"/>
AG Set (MO)	C10	Focus, tracking gain adjustment (MO)			<input type="radio"/>
AG Set (CD)	C11	Focus, tracking gain adjustment (CD)			<input type="radio"/>
TEMP CHECK	C12	Temperature compensation offset check		<input type="radio"/>	<input type="radio"/>
LDPWR CHECK	C13	Laser power check		<input type="radio"/>	<input type="radio"/>
EF MO CHECK	C14	Traverse (MO) check		<input type="radio"/>	<input type="radio"/>
EF CD CHECK	C15	Traverse (CD) check		<input type="radio"/>	<input type="radio"/>
FBIAS CHECK	C16	Focus bias check		<input type="radio"/>	<input type="radio"/>
ScurveCHECK	C17	S-curve check	X	<input type="radio"/>	
VERIFYMODE	C18	Nonvolatile memory check	X	<input type="radio"/>	
DETRK CHECK	C19	Detrack check	X	<input type="radio"/>	
0920 CHECK	C25	Most circumference check	X	<input type="radio"/>	
Iop Read	C26	Iop data display		<input type="radio"/>	<input type="radio"/>
Iop Compare	C27	Comparison with initial Iop value written in nonvolatile memory		<input type="radio"/>	<input type="radio"/>
ADJ CLEAR	C28	Initialization of nonvolatile memory for adjustment values			<input type="radio"/>
INFORMATION	C31	Display of microprocessor version, etc.		<input type="radio"/>	<input type="radio"/>
CPLAY1MODE	C34	Continuous playback mode		<input type="radio"/>	<input type="radio"/>
CREC 1MODE	C35	Continuous recording mode		<input type="radio"/>	<input type="radio"/>

- For details of each adjustment mode, refer to “5. Electrical Adjustments”.
For details of “Err Display”, refer to “Self-Diagnosis Function” on page 2.
- If a different mode has been selected by mistake, press the [MENU/NO] button to exit that mode.
- Modes with (X) in the Mark column are not used for servicing and therefore are not described in detail. If these modes are set accidentally, press the [MENU/NO] button to exit the mode immediately.

4-5-1. Operating the Continuous Playback Mode

1. Entering the continuous playback mode

- ① Set the disc in the unit. (Whichever recordable discs or discs for playback only are available.)
- ② Rotate the **[AMS]** knob and display “CPLAY1 MODE”(C34).
- ③ Press the **[YES]** button to change the display to “CPLAY1 MID”.
- ④ When access completes, the display changes to “C = 0000 AD = 00”.

Note : The numbers “0” displayed show you error rates and ADER.

2. Changing the parts to be played back

- ① Press the **[YES]** button during continuous playback to change the display as below.

“CPLAY1 MID” → “CPLAY1 OUT” → “CPLAY1 IN”
↑

When pressed another time, the parts to be played back can be moved.

- ② When access completes, the display changes to “C = 0000 AD = 00”.

Note : The numbers “0” displayed show you error rates and ADER.

3. Ending the continuous playback mode

- ① Press the **[MENU/NO]** button. The display will change to “CPLAY1 MODE”(C34).
- ② Press the **[EJECT]** button to remove the disc.

Note : The playback start addresses for IN, MID, and OUT are as follows.

IN 40h cluster

MID 300h cluster

OUT 700h cluster

4-5-2. Operating the Continuous Recording Mode (Use only when performing self-recording/palyback check.)

1. Entering the continuous recording mode

- ① Set a recordable disc in the unit.
- ② Rotate the **[AMS]** knob and display “CREC1 MODE” (C35).
- ③ Press the **[YES]** button to change the display to “CREC1 MID”.
- ④ When access completes, the display changes to “CREC1 (0000)” and **REC** lights up.

Note : The numbers “0” displayed shows you the recording position addresses.

2. Changing the parts to be recorded

- ① When the **[YES]** button is pressed during continuous recording, the display changes as below.

“CREC1 MID” → “CREC1 OUT” → “CREC1 IN”
↑

When pressed another time, the parts to be recorded can be changed. **REC** goes off.

- ② When access completes, the display changes to “CREC1 (0000)” and **REC** lights up.

Note : The numbers “0” displayed shows you the recording position addresses.

3. Ending the continuous recording mode

- ① Press the **[MENU/NO]** button. The display changes to “CREC1 MODE” (C35) and **REC** goes off.
- ② Press the **[EJECT]** button to remove the disc.

Note 1 : The recording start addresses for IN, MID, and OUT are as follows.

IN 40h cluster

MID 300h cluster

OUT 700h cluster

Note 2 : The **[MENU/NO]** button can be used to stop recording anytime.

Note 3 : Do not perform continuous recording for long periods of time above 5 minutes.

Note 4 : During continuous recording, be careful not to apply vibration.

4-6. FUNCTIONS OF OTHER BUTTONS

Function	Contents
▷	Sets continuous playback when pressed in the STOP state. When pressed during continuous playback, the tracking servo turns ON/OFF.
■	Stops continuous playback and continuous recording.
▶▶	The sled moves to the outer circumference only when this is pressed.
◀◀	The sled moves to the inner circumference only when this is pressed.
REC MODE	Switches between the pit and groove modes when pressed.
PLAY MODE	Switches the spindle servo mode (CLV S ↔ CLV A).
LEVEL/DISPLAY/CHAR	Switches the displayed contents each time the button is pressed.
⏏	Ejects the disc.
REPEAT	Exits the test mode.

4-7. TEST MODE DISPLAYS

Each time the [LEVEL/DISPLAY/CHAR] button is pressed, the display changes in the following order.

When CPLAY and CREC are started, the display will forcibly be switched to the error rate display as the initial mode.

1. Mode display

Displays “TEMP ADJUST”, “CPLAY1MODE”, etc.

2. Error rate display

Displays the error rate in the following way.

C1 = □□□□ AD = □□

C1 = Indicates the C1 error.

AD = Indicates ADER.

3. Address display

The address is displayed as follows. (MO:recordable disc, CD:playback only disc)

If the [LEVEL/DISPLAY/CHAR] button is pressed after pressing the

[PROGRAM] button, the display switches from groove to pit or vice versa.

h = □□□□ s = □□□□ (MO pit and CD)

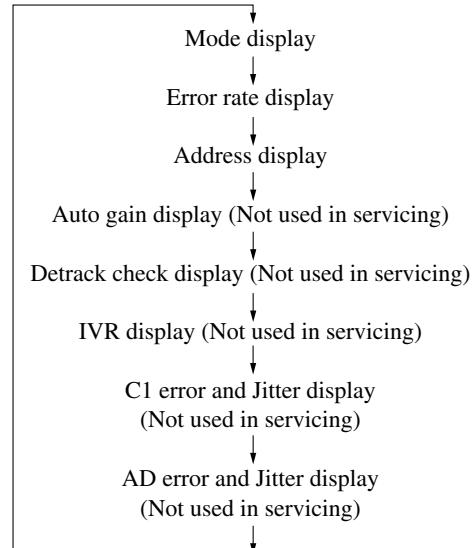
h = □□□□ a = □□□□ (MO groove)

h = Indicates the header address.

s = Indicates the SUBQ address.

a = Indicates the ADIP address.

Note: “–” is displayed when the address cannot be read.



4-8. MEANINGS OF OTHER DISPLAYS

Display	Contents	
	When Lit	When Off
▷	Servo ON	Servo OFF
II	Tracking servo OFF	Tracking servo ON
REC	Recording mode ON	Recording mode OFF
SYNC	CLV low speed mode	CLV normal mode
L.SYNC	ABCD adjustment completed	
OVER	Tracking offset cancel ON	Tracking offset cancel OFF
B/I	Tracking auto gain OK	
A/REP	Focus auto gain OK	
TRACK/(LP) 4/Calendar frame	Pit	Groove
DISC/LP2	High reflection	Low reflection
SLEEP/SHUF	CLV S	CLV A
MONO	CLV LOCK	CLV UNLOCK

4-9. AUTOMATIC SELF-DIAGNOSIS FUNCTION

This test mode performs CREC and CPLAY automatically for mainly checking the characteristics of the optical pick-up. To perform this test mode, the laser power must first be checked. Perform AUTO CHECK after the laser power check and Iop check.

Procedure

1. Press the YES button. If “LDPWR ミチェック” is displayed, it means that the laser power check has not been performed. In this case, perform the laser power check and Iop compare, and then repeat from step 1.
2. If a disc is in the mechanical deck, it will be ejected forcibly. “DISC IN” will be displayed in this case. Load a test disc (MDW-74/GA-1) which can be recorded.
3. If a disk is loaded at step 2, the check will start automatically.
4. When “XX CHECK” is displayed, the item corresponding to XX will be performed. When “06 CHECK” completes, the disc loaded at step 2 will be ejected. “DISC IN” will be displayed. Load the check disc (MD) TDYS-1.
5. When the disc is loaded in step 4, the check will automatically be resumed from “07 CHECK”.
6. After completing to test item 12, check OK or NG will be displayed. If all items are OK, “CHECK ALL OK” will be displayed. If any item is NG, it will be displayed as “NG:xxxx”.

When “CHECK ALL OK” is displayed, it means that the optical pick-up is normal. Check the operations of the other spindle motor, thread motor, etc.

When displayed as “NG:xxxx”, it means that the optical pick-up is faulty. In this case, replace the optical pick-up.

4-10. INFORMATION

Display the software version.

Procedure

1. If displayed as “INFORMATION”, press the YES button.
2. The software version will be displayed.
3. Press the MENW/NO button to end this mode.

4-11. WHEN MEMORY NG IS DISPLAYED

If the nonvolatile memory data is abnormal, “E001”/“MEMORY NG” will be displayed so that the MD deck does not continue operations. In this case, set the test mode promptly and perform the following procedure.

Procedure

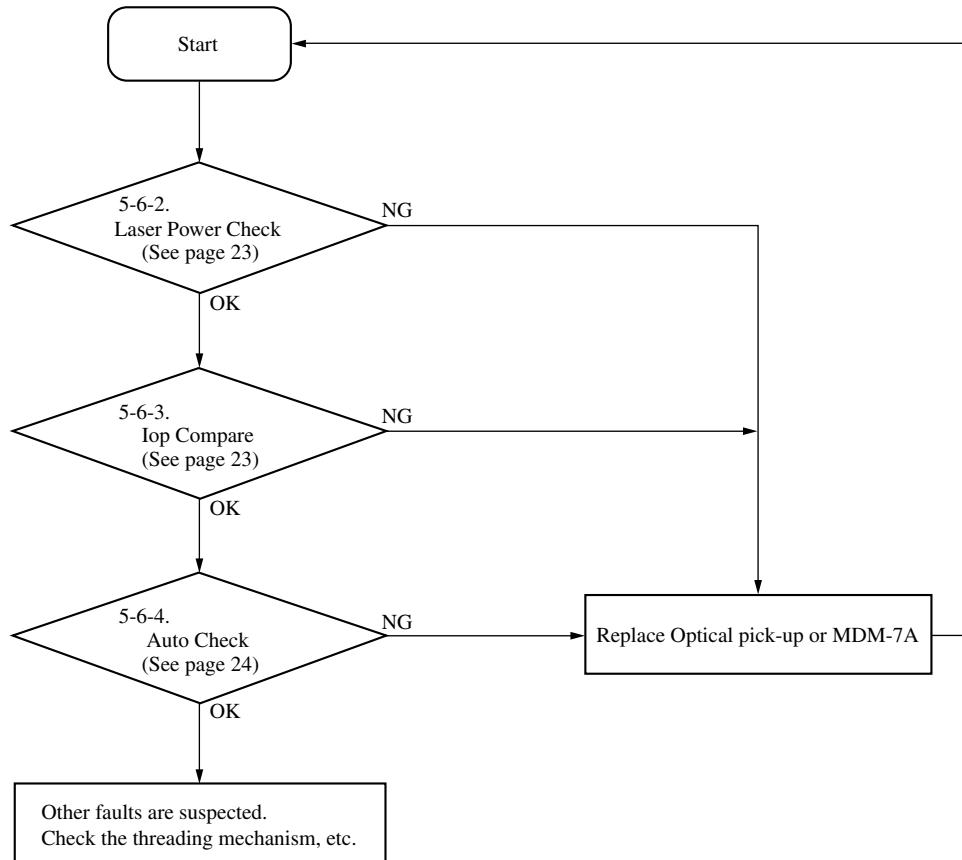
1. Set the test mode. (Refer to 4-2.)
2. Normally a message for selecting the test mode will be displayed. However if the nonvolatile memory is abnormal, the following will be displayed. “INIT EEP?”
3. Press the STOP button and EJECT button together.
4. Rotate the AMS knob and select MDM-7A.
5. Press the AMS knob. If the nonvolatile memory is successfully overwritten, the normal test mode will be set and a message to select the test mode will be displayed.

SECTION 5 ELECTRICAL ADJUSTMENTS

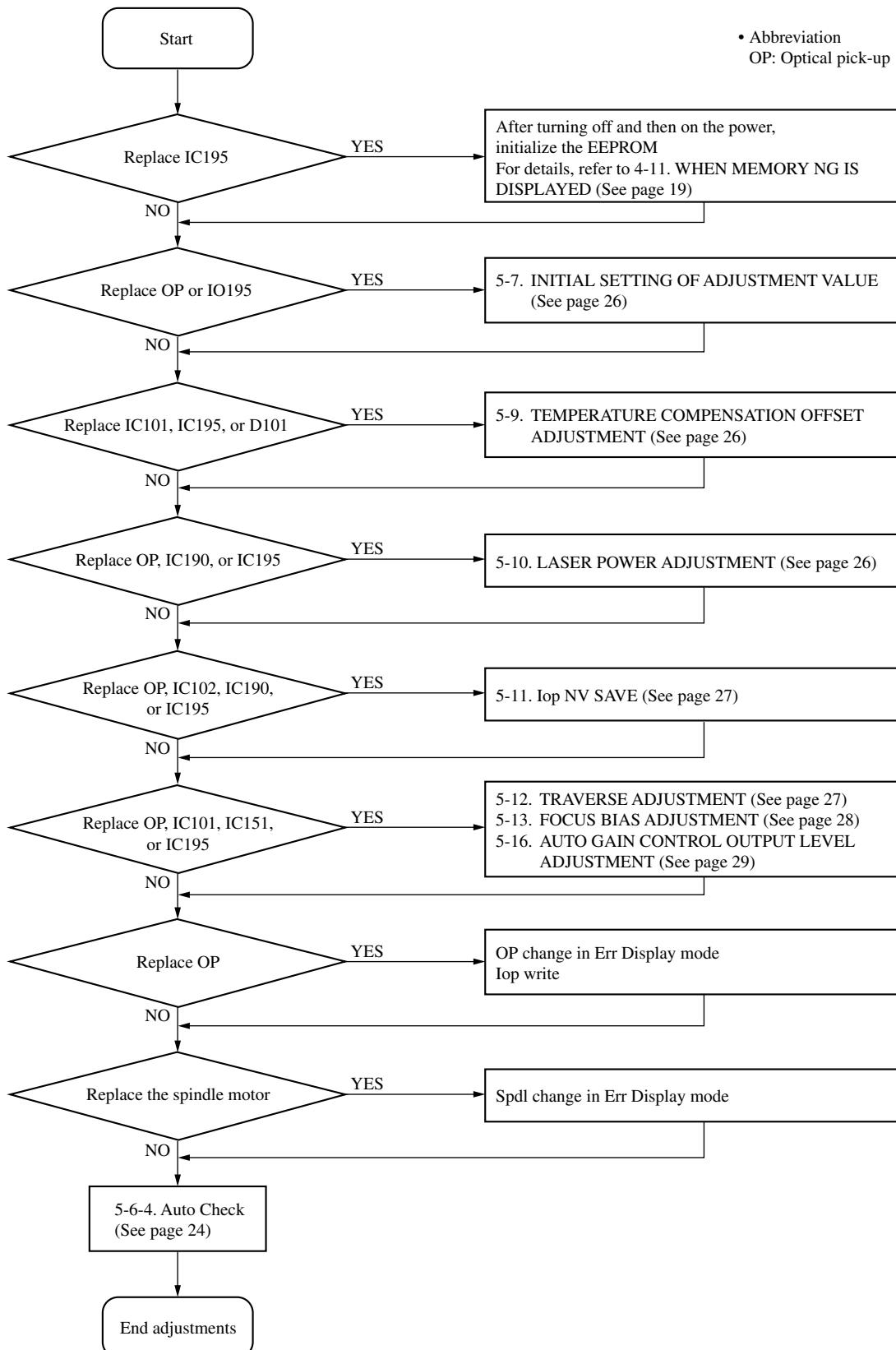
5-1. PARTS REPLACEMENT AND ADJUSTMENT

If malfunctions caused by Optical pick-up such as sound skipping are suspected, follow the following check.

Check before replacement



Adjustment flow

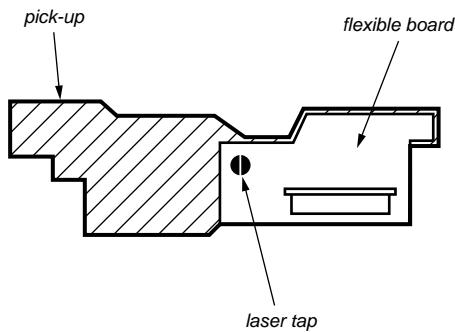


5-2. PRECAUTIONS FOR CHECKING LASER DIODE EMISSION

To check the emission of the laser diode during adjustments, never view directly from the top as this may lose your eye-sight.

5-3. PRECAUTIONS FOR USE OF OPTICAL PICK-UP (KMS-260B)

As the laser diode in the optical pick-up is easily damaged by static electricity, solder the laser tap of the flexible board when using it. Before disconnecting the connector, desolder first. Before connecting the connector, be careful not to remove the solder. Also take adequate measures to prevent damage by static electricity. Handle the flexible board with care as it breaks easily.



Optical pick-up flexible board

5-4. PRECAUTIONS FOR ADJUSTMENTS

- 1) When replacing the following parts, perform the adjustments and checks with in the order shown in the following table.
- 2) Set the test mode when performing adjustments.
After completing the adjustments, exit the test mode.
Perform the adjustments and checks in "group S" of the test mode.
- 3) Perform the adjustments to be needed in the order shown.
- 4) Use the following tools and measuring devices.
 - Check Disc (MD) TDYS-1
(Parts No. 4-963-646-01)
 - Test Disk (MDW-74/GA-1) (Parts No. 4-229-747-01)
 - Laser power meter LPM-8001 (Parts No. J-2501-046-A)
or
MD Laser power meter 8010S (Parts No. J-2501-145-A)
 - Oscilloscope (Measure after performing CAL of prove.)
 - Digital voltmeter
 - Thermometer
 - Jig for checking BD board waveform
(Parts No. : J-2501-196-A)

- 5) When observing several signals on the oscilloscope, etc., make sure that VC and ground do not connect inside the oscilloscope.
(VC and ground will become short-circuited.)
- 6) Using the above jig enables the waveform to be checked without the need to solder.
(Refer to Servicing Note on page 6.)
- 7) As the disc used will affect the adjustment results, make sure that no dusts nor fingerprints are attached to it.

Adjustment	Parts to be replaced						
	Optical Pick-up	IC101	IC102	IC151	IC190	IC195	D101
5-7. Initial setting of adjustment values	<input type="circle"/>	×	×	×	×	<input type="circle"/>	×
5-8. Recording of Iop information	<input type="circle"/>	×	×	×	×	<input type="circle"/>	×
5-9. TEMP ADJUST	<input type="circle"/>	<input type="circle"/>	×	×	×	<input type="circle"/>	<input type="circle"/>
5-10. Laser power adjustment	<input type="circle"/>	×	×	×	<input type="circle"/>	<input type="circle"/>	×
5-11. Iop NV Save	<input type="circle"/>	×	<input type="circle"/>	×	<input type="circle"/>	<input type="circle"/>	×
5-12. Traverse adjustment	<input type="circle"/>	<input type="circle"/>	×	<input type="circle"/>	×	<input type="circle"/>	×
5-13. Focus bias adjustment	<input type="circle"/>	<input type="circle"/>	×	<input type="circle"/>	×	<input type="circle"/>	×
5-16. Auto gain adjustment	<input type="circle"/>	<input type="circle"/>	×	<input type="circle"/>	×	<input type="circle"/>	×
5-6-4. AUTO CHECK	<input type="circle"/>	<input type="circle"/>	×	<input type="circle"/>	<input type="circle"/>	<input type="circle"/>	×

5-5. USING THE CONTINUOUSLY RECORDED DISC

- * This disc is used in focus bias adjustment and error rate check.
- The following describes how to create a continuous recording disc.
- 1. Insert a disc (blank disc) commercially available.
- 2. Rotate the [AMS] knob and display “CREC1 MODE”.
- 3. Press the [YES] button again to display “CREC1 MID”. Display “CREC (0300)” and start to recording.
- 4. Complete recording within 5 minutes.
- 5. Press the [MENU/NO] button and stop recording.
- 6. Press the [EJECT] button and remove the disc.

The above has been how to create a continuous recorded data for the focus bias adjustment and error rate check.

Note :

- Be careful not to apply vibration during continuous recording.

5-6. CHECKS PRIOR TO REPAIRS

These checks are performed before replacing parts according to “approximate specifications” to determine the faulty locations. For details, refer to “Checks Prior to Parts Replacement and Adjustments” (See page 8).

5-6-1. Temperature Compensation Offset Check

When performing adjustments, set the internal temperature and room temperature to 22 to 28°C.

Checks cannot be performed properly if performed after some time from power ON due to the rise in the temperature of the IC and diode, etc. So, perform the checks again after waiting some time.

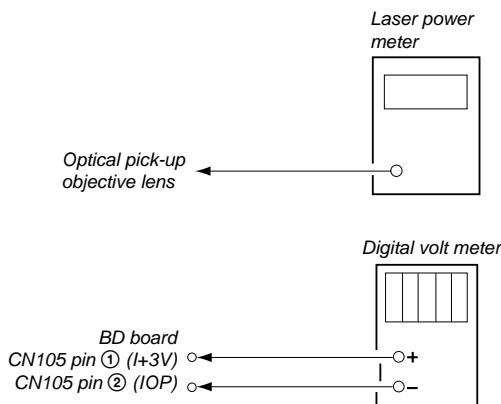
Checking Procedure:

1. Rotate the [AMS] knob to display “TEMP CHECK”.
2. Press the [YES] button.
3. “T=@@ (#) [OK]” should be displayed. If “T=@@ (#) [NG]” is displayed, it means that the results are bad. (@@ indicates the current value set, and ## indicates the value written in the non-volatile memory.)

5-6-2. Laser Power Check

Before checking, check the Iop value of the optical pick-up. (Refer to 5-8. Recording and Displaying Iop Information.)

Connection :



Checking Procedure:

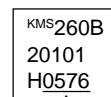
1. Set the laser power meter on the objective lens of the optical pick-up. (When it cannot be set properly, press the [◀] button or [▶] button to move the optical pick-up.) Connect the digital volt meter to CN105 pin ① (I+3V) and CN105 pin ② (IOP).
2. Then, rotate the [AMS] knob and display “LDPWR CHECK”.
3. Press the [YES] button once and display “LD 0.9 mW \$ 00”. Check that the reading of the laser power meter become 0.84 to 0.92 mW.
4. Press the [YES] button once more and display “LD 7.0 mW \$ 00”. Check that the reading the laser power meter and digital volt meter satisfy the specified value.

Specified Value :

Laser power meter reading : 7.0 ± 0.2 mW

Digital voltmeter reading : Optical pick-up displayed value $\pm 10\%$

(Optical pick-up label)



(For details of the method for checking this value, refer to “5-8. Recording and Displaying Iop Information.”)

- lop = 57.6 mA in this case
- lop (mA) = Digital voltmeter reading (mV)/1 (Ω)
5. Press the [MENU/NO] button and display “LDPWR CHECK” and stop the laser emission. (The [MENU/NO] button is effective at all times to stop the laser emission.)

Note 1: After step 4, each time the [YES] button is pressed, the display will be switched between “LD 0.7 mW \$ 00”, “LD 6.2 mW \$ 00”, and “LD Wp 未セイ \$ 00”. Nothing needs to be performed here.

5-6-3. Iop Compare

The current Iop value at laser power 7 mw output and reference Iop value (set at shipment) written in the nonvolatile memory are compared, and the rate of increase/decrease will be displayed in percentage.

Note: Perform this function with the optical pick-up set at room temperature.

Procedure

1. Rotate the [AMS] knob to display “Iop Compare”.
2. Press the [YES] button and start measurements.
3. When measurements complete, the display changes to “±xx%yy”.
- xx is the percentage of increase/decrease, and OK or NG is displayed at yy to indicate whether the percentage of increase/decrease is within the allowable range.
4. Press the [MENU/NO] button to end.

5-6-4. Auto Check

This test mode performs C-REC and C-PLAY automatically for mainly checking the characteristics of the optical pick-up. To perform this test mode, the laser power must first be checked. Perform Auto Check after the laser power check and Iop compare.

Procedure

1. Press the [YES] button. If “LDPWR minicheck” is displayed, it means that the laser power check has not been performed. In this case, perform the laser power check and Iop compare, and then repeat from step 1.
2. If a disc is in the mechanical deck, it will be ejected forcibly. “DISC IN” will be displayed in this case. Load a test disc (MDW-74/GA-1) which can be recorded.
3. If a disk is loaded at step 2, the check will start automatically.
4. When “XX CHECK” is displayed, the item corresponding to XX will be performed. When “06 CHECK” completes, the disc loaded at step 2 will be ejected. “DISC IN” will be displayed. Load the check disc (MD) TDYS-1.
5. When the disc is loaded, the check will automatically be resumed from “07 CHECK”.
6. After completing to test item 12, check OK or NG will be displayed. If all items are OK, “CHECK ALL OK” will be displayed. If any item is NG, it will be displayed as “NG:xxxx”.

When “CHECK ALL OK” is displayed, it means that the optical pick-up is normal. Check the operations of the other spindle motor, thread motor, etc.

When displayed as “NG:xxxx”, it means that the optical pick-up is faulty. In this case, replace the optical pick-up.

5-6-5. Other Checks

All the following checks are performed by the Auto Check mode. They therefore need not be performed in normal operation.

5-6-6. Traverse Check

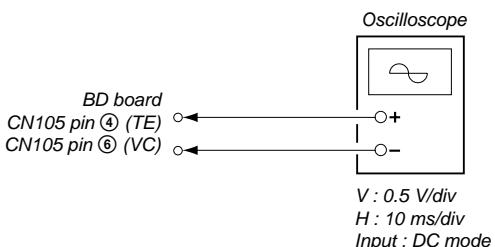
5-6-7. Focus Bias Check

5-6-8. C PLAY Check

5-6-9. Self-Recording/Playback Check

5-6-6. Traverse Check

Connection :

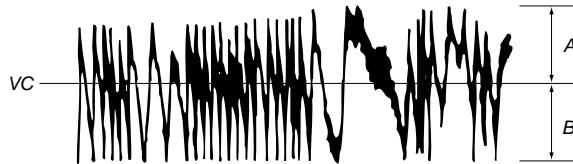


Checking Procedure:

1. Connect an oscilloscope to CN105 pin ④ (TE) and CN105 pin ⑥ (VC) of the BD board.
2. Load a test disc (MDW-74/GA-1). (Refer to Note 1.)
3. Press the [▶] button and move the optical pick-up outside the pit.
4. Rotate the [AMS] knob and display “EF MO CHECK”.
5. Press the [YES] button and display “EFB = ☰ MO-R”. (Laser power READ power/Focus servo ON/tracking servo OFF/spindle (S) servo ON)

6. Observe the waveform of the oscilloscope, and check that the specified value is satisfied. Do not rotate the [AMS] knob. (Read power traverse checking)

(Traverse Waveform)

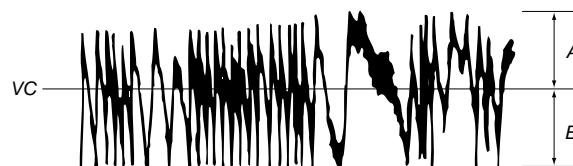


Specified value : Below 10% offset value

$$\text{Offset value (\%)} = \frac{|A - B|}{2(A + B)} \times 100$$

7. Press the [YES] button and display “EFB = ☰ MO-W”.
8. Observe the waveform of the oscilloscope, and check that the specified value is satisfied. Do not rotate the [AMS] knob. (Write power traverse checking)

(Traverse Waveform)

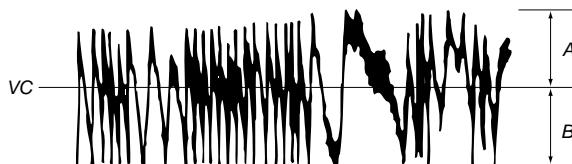


Specified value : Below 10% offset value

$$\text{Offset value (\%)} = \frac{|A - B|}{2(A + B)} \times 100$$

9. Press the [YES] button display “EFB = ☰ MO-P”. Then, the optical pick-up moves to the pit area automatically and servo is imposed.
10. Observe the waveform of the oscilloscope, and check that the specified value is satisfied. Do not rotate the [AMS] knob.

(Traverse Waveform)



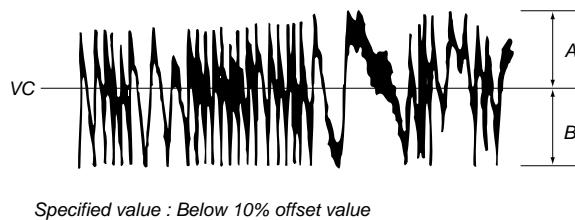
Specified value : Below 10% offset value

$$\text{Offset value (\%)} = \frac{|A - B|}{2(A + B)} \times 100$$

11. Press the [YES] button display “EF MO CHECK”
The disc stops rotating automatically.
12. Press the [△] button and remove the disc.
13. Load the check disc (MD) TDYS-1.
14. Rotate the [AMS] knob and display “EF CD CHECK” (C04).
15. Press the [YES] button and display “EFB = ☰ CD”. Servo is imposed automatically.

16. Observe the waveform of the oscilloscope, and check that the specified value is satisfied. Do not rotate the [AMS] knob.

(Traverse Waveform)

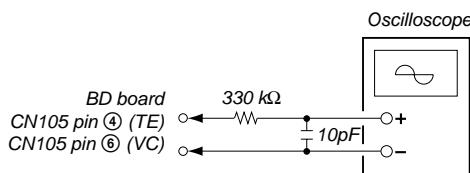


$$\text{Offset value (\%)} = \frac{|A - B|}{2(A + B)} \times 100$$

17. Press the [YES] button and display “EF CD CHECK”.
18. Press the [STOP] button and remove the check disc (MD) TDYS-1.

Note 1 : MO reading data will be erased during if a recorded disc is used in this adjustment.

Note 2 : If the traverse waveform is not clear, connect the oscilloscope as shown in the following figure so that it can be seen more clearly.



5-6-7. Focus Bias Check

Change the focus bias and check the focus tolerance amount.

Checking Procedure :

1. Load a continuously recorded test disc (MDW-74/GA-1). (Refer to “5-5. Using the Continuously Recorded Disc”.)
2. Rotate the [AMS] knob and display “CPLAY1 MODE”.
3. Press the [YES] button and display “CPLAY1 MID”.
4. Press the [MENU/NO] button when “C = 0000 AD = 00” is displayed.
5. Rotate the [AMS] knob and display “FBIAS CHECK”.
6. Press the [YES] button and display “0000/00 b = 00”.

The first four digits indicate the C1 error rate, the two digits after [/] indicate ADER, and the 2 digits after [b =] indicate the focus bias value.

Check that the C1 error is below 20 and ADER is below 2.

7. Press the [YES] button and display “0000/00 b = 00”.
8. Check that the C1 error is below 100 and ADER is below 2.
9. Press the [YES] button and display “0000/00 a = 00”.
10. Check that the C1 error is below 100 and ADER is below 2.
11. Press the [MENU/NO] button, next press the [STOP] button, and remove the test disc.

5-6-8. C PLAY Check

MO Error Rate Check

Checking Procedure :

1. Load a continuously recorded test disc (MDW-74/GA-1). (Refer to “5-5. Using the Continuously Recorded Disc”.)
2. Rotate the [AMS] knob and display “CPLAY1 MODE”.
3. Press the [YES] button and display “CPLAY1 MID”.
4. The display changes to “C1 = 0000 AD = 00”.
5. If the C1 error rate is below 20, check that ADER is 00.
6. Press the [MENU/NO] button, stop playback, press the [STOP] button, and test disc.

CD Error Rate Check

Checking Procedure :

1. Load a check disc (MD) TDYS-1.
2. Rotate the [AMS] knob and display “CPLAY1 MODE”.
3. Press the [YES] button twice and display “CPLAY1 MID”.
4. The display changes to “C1 = 0000 AD = 00”.
5. Check that the C1 error rate is below 20.
6. Press the [MENU/NO] button, stop playback, press the [STOP] button, and the test disc.

5-6-9. Self-Recording/playback Check

Prepare a continuous recording disc using the unit to be repaired and check the error rate.

Checking Procedure :

1. Insert a recordable test disc (MDW-74/GA-1) into the unit.
2. Rotate the [AMS] knob to display “CREC1 MODE”.
3. Press the [YES] button to display the “CREC1 MID”.
4. When recording starts, “REC” is displayed, this becomes “CREC (@@@@)” (@@@@ is the address), and recording starts.
5. About 1 minute later, press the [MENU/NO] button to stop continuous recording.
6. Rotate the [AMS] knob to display “C PLAY1 MODE”.
7. Press the [YES] button to display “C PLAY1 MID”.
8. “C1 = 0000 AD = 00” will be displayed.
9. Check that the C1 error becomes below 20 and the AD error below 2.
10. Press the [MENU/NO] button to stop playback, and press the [STOP] button and remove the disc.

5-7. INITIAL SETTING OF ADJUSTMENT VALUE

Note:

Mode which sets the adjustment results recorded in the non-volatile memory to the initial setting value. However the results of the temperature compensation offset adjustment will not change to the initial setting value.

If initial setting is performed, perform all adjustments again excluding the temperature compensation offset adjustment.

For details of the initial setting, refer to "5-4. Precautions on Adjustments" and execute the initial setting before the adjustment as required.

Setting Procedure :

1. Rotate the [AMS] knob to display "ADJ CLEAR".
2. Press the [YES] button. "Complete!" will be displayed momentarily and initial setting will be executed, after which "ADJ CLEAR" will be displayed.

5-8. RECORDING AND DISPLAYING THE IOP INFORMATION

The IOP data can be recorded in the non-volatile memory. The Iop value on the label of the optical pick-up and the Iop value after the adjustment will be recorded. Recording these data eliminates the need to read the label on the optical pick-up.

Recording Procedure :

1. While pressing the [AMS] knob and [] button, connect the power plug to the outlet, and release the [AMS] knob and [] button.
2. Rotate the [AMS] knob to display "[Service]", and press the [YES] button.
3. Rotate the [AMS] knob to display "Iop.Write", and press the [YES] button.
4. The display becomes Ref=@@@.@(@ is an arbitrary number) and the numbers which can be changed will blink.
5. Input the Iop value written on the optical pick-up.
To select the number : Rotate the [AMS] knob.
To select the digit : Press the [AMS] knob
6. When the [YES] button is pressed, the display becomes "Measu=@@@.@" (@ is an arbitrary number).
7. As the adjustment results are recorded for the 6 value. Leave it as it is and press the [YES] button.
8. "Complete!" will be displayed momentarily. The value will be recorded in the non-volatile memory and the display will become "Iop Write".

Display Procedure :

1. Rotate the [AMS] knob to display "Iop.Read".
2. "@@.@@/#.#" is displayed and the recorded contents are displayed.
@@.@@ indicates the Iop value labeled on the pick-up.
##.# indicates the Iop value after adjustment
3. To end, press the [AMS] button or [MENU/NO] button to display "Iop Read".

5-9. TEMPERATURE COMPENSATION OFFSET ADJUSTMENT

Save the temperature data at that time in the non-volatile memory as 25 °C reference data.

Note :

1. Usually, do not perform this adjustment.
2. Perform this adjustment in an ambient temperature of 22 °C to 28 °C. Perform it immediately after the power is turned on when the internal temperature of the unit is the same as the ambient temperature of 22 °C to 28 °C.
3. When D101 has been replaced, perform this adjustment after the temperature of this part has become the ambient temperature.

Adjusting Procedure :

1. Rotate the [AMS] knob and display "TEMP ADJUST".
2. Press the [YES] button and select the "TEMP ADJUST" mode.
3. "TEMP = 00 [OK]" and the current temperature data will be displayed.
4. To save the data, press the [YES] button.
When not saving the data, press the [MENU/NO] button.
5. When the [YES] button is pressed, "TEMP = 00 SAVE" will be displayed and turned back to "TEMP ADJUST" display then.
When the [MENU/NO] button is pressed, "TEMP ADJUST" will be displayed immediately.

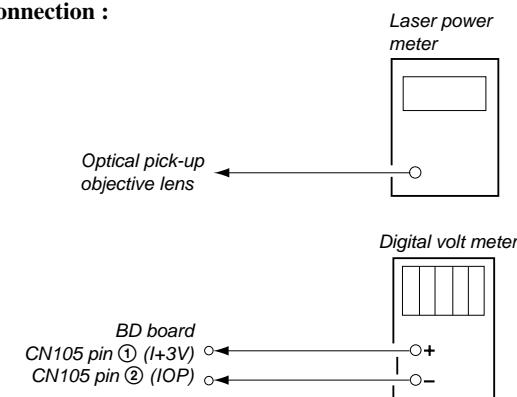
Specified Value :

The "TEMP = 00" should be within "E0 - EF", "F0 - FF", "00 - 0F", "10 - 1F" and "20 - 2F".

5-10. LASER POWER ADJUSTMENT

Check the Iop value of the optical pick-up before adjustments.
(Refer to 5-8. Recording and Displaying Iop Information.)

Connection :



Adjusting Procedure :

1. Set the laser power meter on the objective lens of the optical pick-up. (When it cannot be set properly, press the [◀] button or [▶] button to move the optical pick-up.)
Connect the digital volt meter to CN105 pin ① (I+3V) and CN105 pin ② (IOP).
2. Rotate the [AMS] knob and display "LDPWR ADJUST".
(Laser power : For adjustment)
3. Press the [YES] button once and display "LD 0.9 mW \$ 00".
4. Rotate the [AMS] knob so that the reading of the laser power meter becomes 0.85 to 0.91 mW. Press the [YES] button after setting the range knob of the laser power meter, and save the adjustment results. ("LD SAVE \$ 00" will be displayed for a moment.)
5. Then "LD 7.0 mW \$ 00" will be displayed.
6. Rotate the [AMS] knob so that the reading of the laser power meter becomes 6.9 to 7.1 mW, press the [YES] button and save it.

Note : Do not perform the emission with 7.0 mW more than 15 seconds continuously.

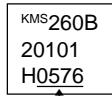
7. Then, rotate the [AMS] knob and display “LDPWR CHECK”.
8. Press the [YES] button once and display “LD 0.9 mW \$ 00”. Check that the reading of the laser power meter become 0.85 to 0.91 mW.
9. Press the [YES] button once more and display “LD 7.0 mW \$ 00”. Check that the reading the laser power meter and digital volt meter satisfy the specified value.
- Note down the digital voltmeter reading value.

Specified Value :

Laser power meter reading : 7.0 ± 0.2 mW

Digital voltmeter reading : Optical pick-up displayed value $\pm 10\%$

(Optical pick-up label)



(For details of the method for checking this value, refer to “5-8. Recording and Displaying IOP Information”.)

*Iop = 57.6 mA in this case
Iop (mA) = Digital voltmeter reading (mV)/1 (Ω)*

10. Press the [MENU/NO] button and display “LDPWR CHECK” and stop the laser emission.
(The [MENU/NO] button is effective at all times to stop the laser emission.)
11. Rotate the [AMS] knob to display “Iop.Write”.
12. Press the [YES] button. When the display becomes Ref=@@.@(@ is an arbitrary number), press the [YES] button to display “Measu=@@.@(@ is an arbitrary number).
13. The numbers which can be changed will blink. Input the Iop value noted down at step 9.
To select the number : Rotate the [AMS] knob.
To select the digit : Press the [AMS] knob
14. When the [YES] button is pressed, “Complete!” will be displayed momentarily. The value will be recorded in the non-volatile memory and the display will become “Iop Write”.

Note 1: After step 4, each time the [YES] button is pressed, the display will be switched between “LD 0.7 mW \$ 00”, “LD 6.2 mW \$ 00”, and “LD Wp 木セイ \$ 00”. Nothing needs to be performed here.

5-11. Iop NV SAVE

Write the reference values in the nonvolatile memory to perform “Iop compare”. As this involves rewriting the reference values, do not perform this procedure except when adjusting the laser power during replacement of the Optical pick-up and when replacing the IC102. Otherwise the Optical pick-up check may deteriorate.

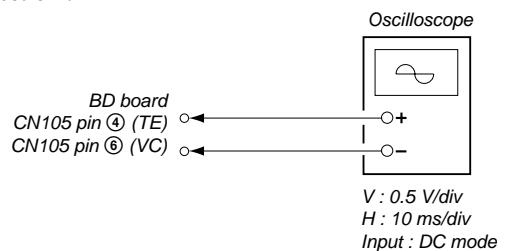
Note: Perform this function with the optical pick-up set at room temperature.

Procedure

1. Rotate the [AMS] knob to display “Iop NV Save” (C06).
2. Press the [YES] button and display “Iop [stop]”.
3. After the display changes to “Iop =xxsave?”, press the [YES] button.
4. After “Complete!” is displayed momentarily, the display changes to “Iop 7.0 mW”.
5. After the display changes to “Iop=yysave?”, press the [YES] button.
6. When “Complete!” is displayed, it means that Iop NV saving has been completed.

5-12. TRAVERSE ADJUSTMENT

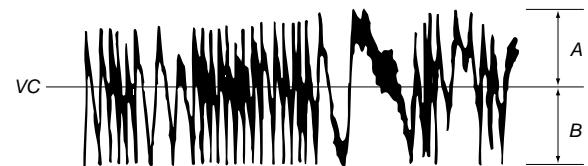
Connection :



Adjusting Procedure :

1. Connect an oscilloscope to CN105 pin ④ (TE) and CN105 pin ⑥ (VC) of the BD board.
2. Load a test disc (MDW-74/GA-1). (Refer to Note 1.)
3. Press the [▶▶] button and move the optical pick-up outside the pit.
4. Rotate the [AMS] knob and display “EF MO ADJUST”.
5. Press the [YES] button and display “EFB = 00 MO-R”.
(Laser power READ power/Focus servo ON/tracking servo OFF/spindle (S) servo ON)
6. Rotate the [AMS] knob so that the waveform of the oscilloscope becomes the specified value.
(When the [AMS] knob is rotated, the 00 of “EFB= 00” changes and the waveform changes.) In this adjustment, waveform varies at intervals of approx. 2%. Adjust the waveform so that the specified value is satisfied as much as possible.
(Read power traverse adjustment)

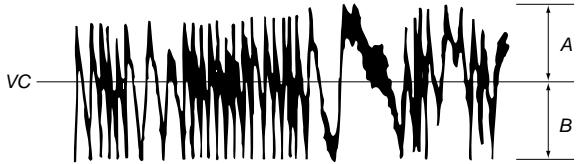
(Traverse Waveform)



Specification A = B

7. Press the [YES] button and save the result of adjustment to the non-volatile memory (“EFB = 00 SAVE” will be displayed for a moment. Then “EFB = 00 MO-W” will be displayed).
8. Rotate the [AMS] knob so that the waveform of the oscilloscope becomes the specified value.
(When the [AMS] knob is rotated, the 00 of “EFB- 00 MO-W” changes and the waveform changes.) In this adjustment, waveform varies at intervals of approx. 2%. Adjust the waveform so that the specified value is satisfied as much as possible.
(Write power traverse adjustment)

(Traverse Waveform)



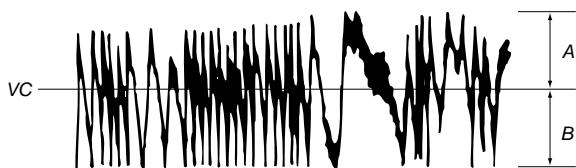
Specification A = B

9. Press the [YES] button, and save the adjustment results in the non-volatile memory. (“EFB = 00 SAVE” will be displayed for a moment.)
10. “EFB = 00 MO-P”. will be displayed.
The optical pick-up moves to the pit area automatically and servo is imposed.

11. Rotate the [AMS] knob until the waveform of the oscilloscope moves closer to the specified value.

In this adjustment, waveform varies at intervals of approx. 2%. Adjust the waveform so that the specified value is satisfied as much as possible.

(Traverse Waveform)



Specification A = B

12. Press the [YES] button, and save the adjustment results in the non-volatile memory. ("EFB = 00 SAVE" will be displayed for a moment.)

Next "EF MO ADJUS" is displayed. The disc stops rotating automatically.

13. Press the \triangle button and remove the disc.

14. Load the check disc (MD) TDYS-1.

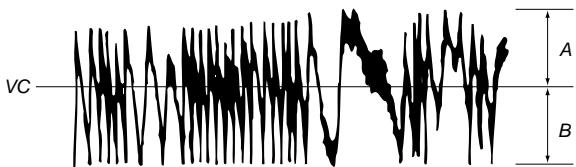
15. Roteto [AMS] knob and display "EF CD ADJUS".

16. Press the [YES] button and display "EFB = 00 CD". Servo is imposed automatically.

17. Rotate the [AMS] knob so that the waveform of the oscilloscope moves closer to the specified value.

In this adjustment, waveform varies at intervals of approx. 2%. Adjust the waveform so that the specified value is satisfied as much as possible.

(Traverse Waveform)



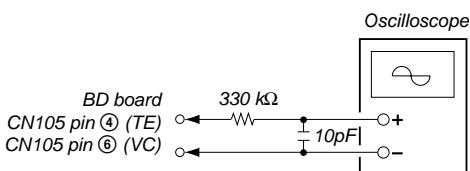
Specification A = B

18. Press the [YES] button, display "EFB = 00 SAVE" for a moment and save the adjustment results in the non-volatile memory. Next "EF CD ADJUST" will be displayed.

19. Press the \triangle button and remove the check disc (MD) TDYS-1.

Note 1 : MO reading data will be erased during if a recorded disc is used in this adjustment.

Note 2 : If the traverse waveform is not clear, connect the oscilloscope as shown in the following figure so that it can be seen more clearly.



5-13. FOCUS BIAS ADJUSTMENT

Adjusting Procedure :

1. Load a test disk (MDW-74/GA-1).
2. Rotate the [AMS] knob and display "CPLAY1 MODE".
3. Press the [YES] button and display "CPLAY1 MID".
4. Press the [MENU/NO] button when "C1 = 0000 AD = 00" is displayed.

5. Rotate the [AMS] knob and display "FBIAS ADJUST".

6. Press the [YES] button and display "0000/00 a = 00".

The first four digits indicate the C1 error rate, the two digits after [/] indicate ADER, and the 2 digits after [a =] indicate the focus bias value.

7. Rotate the [AMS] knob in the clockwise direction and find the focus bias value at which the C1 error rate becomes 220 (Refer to Note 2).

8. Press the [YES] button and display "0000/00 b = 00".

9. Rotate the [AMS] knob in the counterclockwise direction and find the focus bias value at which the C1 error rate becomes 220.

10. Press the [YES] button and display "0000/00 c = 00".

11. Check that the C1 error rate is below 20 and ADER is 00. Then press the [YES] button.

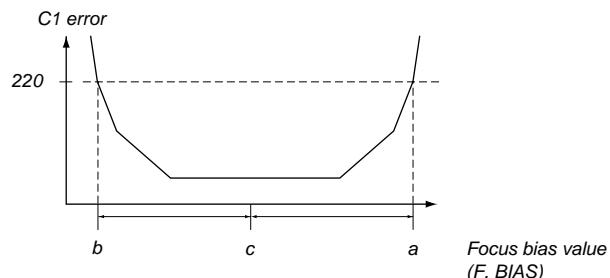
12. If the "(00)" in "00 - 00 - 00 (00)" is above 20, press the [YES] button.

If below 20, press the [MENU/NO] button and repeat the adjustment from step 2.

13. Press the \triangle button to remove the test disc.

Note 1 : The relation between the C1 error and focus bias is as shown in the following figure. Find points a and b in the following figure using the above adjustment. The focal point position C is automatically calculated from points a and b.

Note 2 : As the C1 error rate changes, perform the adjustment using the average vale.



5-14. ERROR RATE CHECK

5-14-1. CD Error Rate Check

Checking Procedure :

1. Load a check disc (MD) TDYS-1.
2. Rotate the [AMS] knob and display “CPLAY1 MODE”.
3. Press the [YES] button twice and display “CPLAY1 MID”.
4. The display changes to “C1 = 0000 AD = 00”.
5. Check that the C1 error rate is below 20.
6. Press the [MENU/NO] button, stop playback, press the [H] button, and remove the test disc.

5-14-2. MO Error Rate Check

Checking Procedure :

1. Load a continuously recorded test disc (MDW-74/GA-1). (Refer to “5-5. Using the Continuously Recorded Disc”).
2. Rotate the [AMS] knob and display “CPLAY1 MODE”.
3. Press the [YES] button and display “CPLAY1 MID”.
4. The display changes to “C1 = 0000 AD = 00”.
5. If the C1 error rate is below 20, check that ADER is 00.
6. Press the [MENU/NO] button, stop playback, press the [H] button, and remove the test disc.

5-15. FOCUS BIAS CHECK

Change the focus bias and check the focus tolerance amount.

Checking Procedure :

1. Load a continuously recorded test disc (MDW-74/GA-1). (Refer to “5-5. Using the Continuously Recorded Disc”).
2. Rotate the [AMS] knob and display “CPLAY1 MODE”.
3. Press the [YES] button twice and display “CPLAY1 MID”.
4. Press the [MENU/NO] button when “C1 = 0000 AD = 00” is displayed.
5. Rotate the [AMS] knob and display “FBIAS CHECK”.
6. Press the [YES] button and display “0000/00 c = 00”.

The first four digits indicate the C1 error rate, the two digits after [/] indicate ADR, and the 2 digits after [c =] indicate the focus bias value.

Check that the C1 error is below 20 and ADER is below 2.

7. Press the [YES] button and display “0000/00 b = 00”.
- Check that the C1 error is below 100 and ADER is below 2.
8. Press the [YES] button and display “0000/00 a = 00”.
- Check that the C1 error is below 100 and ADER is below 2
9. Press the [MENU/NO] button, next press the [H] button, and remove the continuously recorded disc.

Note 1 : If the C1 error and ADER are above other than the specified value at points a (step 8. in the above) or b (step 7. in the above), the focus bias adjustment may not have been carried out properly. Adjust perform the beginning again.

5-16. AUTO GAIN CONTROL OUTPUT LEVEL ADJUSTMENT

Be sure to perform this adjustment when the Optical pick-up is replaced.

If the adjustment results becomes “Adjust NG!”, the Optical pick-up may be faulty or the servo system circuits may be abnormal.

5-16-1. CD Auto Gain Control Output Level Adjustment

Adjusting Procedure :

1. Insert the check disc (MD) TDYS-1.
2. Rotate the [AMS] knob to display “AG Set (CD)”.
3. When the [YES] button is pressed, the adjustment will be performed automatically.
“Complete!!” will then be displayed momentarily when the value is recorded in the non-volatile memory, after which the display changes to “AG Set (CD)”.
4. Press the [H] button to remove the disc.

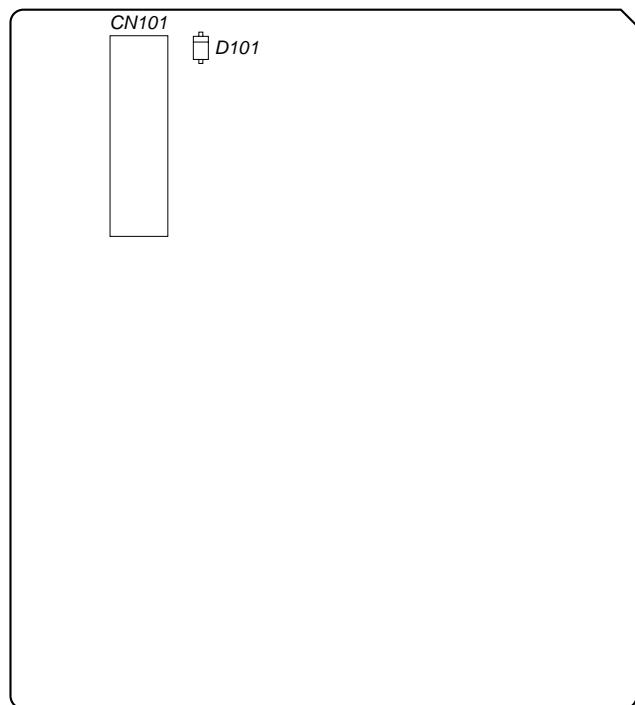
5-16-2. MO Auto Gain Control Output Level Adjustment

Adjusting Procedure :

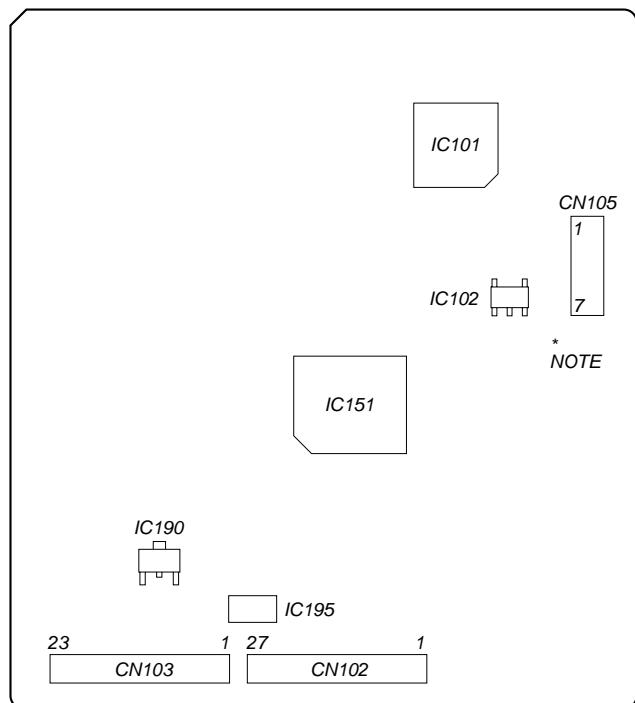
1. Insert the reference disc (MDW-74/GA-1) for recording.
2. Rotate the [AMS] knob to display “AG Set (MO)”.
3. When the [YES] button is pressed, the adjustment will be performed automatically.
“Complete!!” will then be displayed momentarily when the value is recorded in the non-volatile memory, after which the display changes to “AG Set (MO)”.
4. Press the [H] button to remove the disc.

5-17. ADJUSTING POINTS AND CONNECTING POINTS

[BD BOARD] (SIDE A)



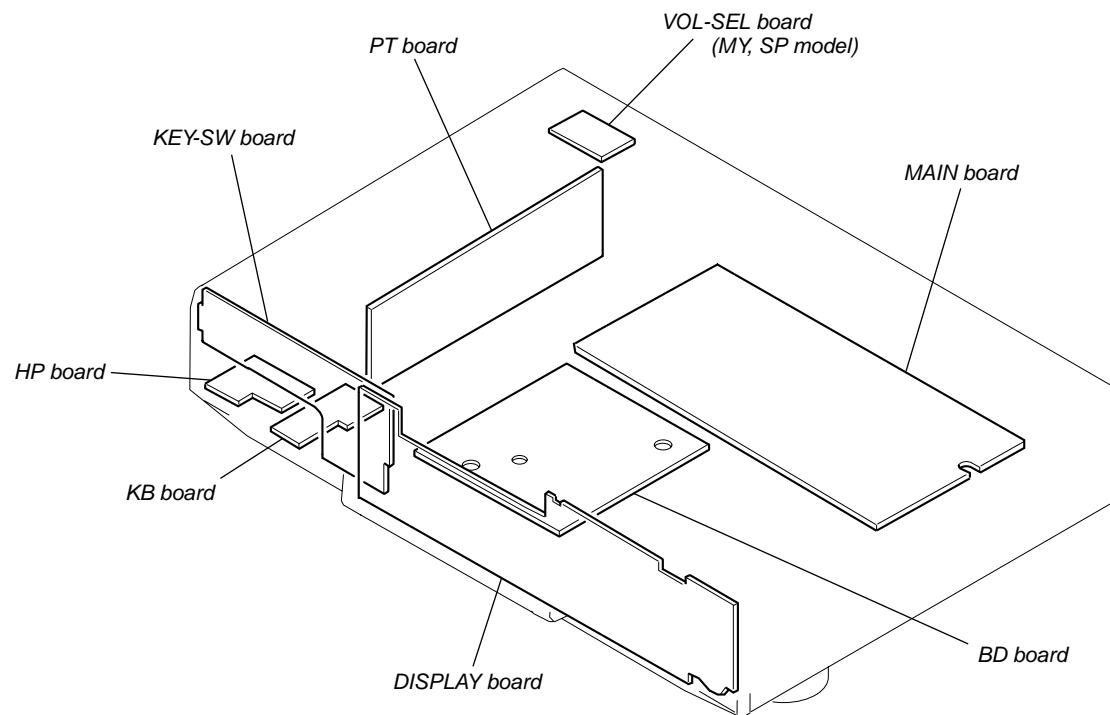
[BD BOARD] (SIDE B)



NOTE:It is useful to use the jig. for checking the waveform. (Refer to Servicing Note on page 6.)

SECTION 6 DIAGRAMS

6-1. CIRCUIT BOARDS LOCATION



**THIS NOTE IS COMMON FOR PRINTED WIRING
BOARDS AND SCHEMATIC DIAGRAMS.**

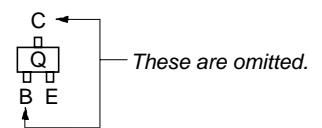
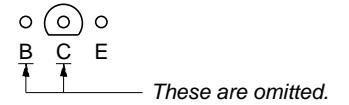
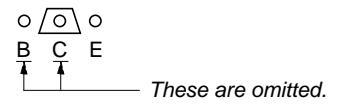
(In addition to this, the necessary note is printed
in each block.)

For schematic diagrams.

Note:

- All capacitors are in μF unless otherwise noted. pF : $\mu\mu\text{F}$ 50 VV or less are not indicated except for electrolytics and tantalums.
- All resistors are in Ω and $1/4 \text{W}$ or less unless otherwise specified.
 - \triangle : internal component.
 - \square : nonflammable resistor.
 - \square : fusible resistor.
 - \square : panel designation.

• Indication of transistor



Note:

The components identified by mark \triangle or dotted line with mark \triangle are critical for safety.
Replace only with part number specified.

Note:

Les composants identifiés par une marque \triangle sont critiques pour la sécurité.
Ne les remplacer que par une pièce portant le numéro spécifié.

- $\square +$: B+ Line.
- $\square -$: B- Line.
- \square : adjustment for repair.
- Voltages and waveforms are dc with respect to ground under no-signal (detuned) conditions.
- Voltages are taken with a VOM (Input impedance $10 \text{ M}\Omega$). Voltage variations may be noted due to normal production tolerances.
- Waveforms are taken with an oscilloscope.
Voltage variations may be noted due to normal production tolerances.
- Circled numbers refer to waveforms.
- Signal path.
 Σ : PB
 \blacktriangleright : REC
 $\Sigma \gg$: PB (DIGITAL OUT)
 $\gg \blacktriangleright$: REC (DIGITAL IN)
- Abbreviation
CND : Canadian model
SP : Singapore model
MY : Malaysia model

For printed wiring boards.

Note:

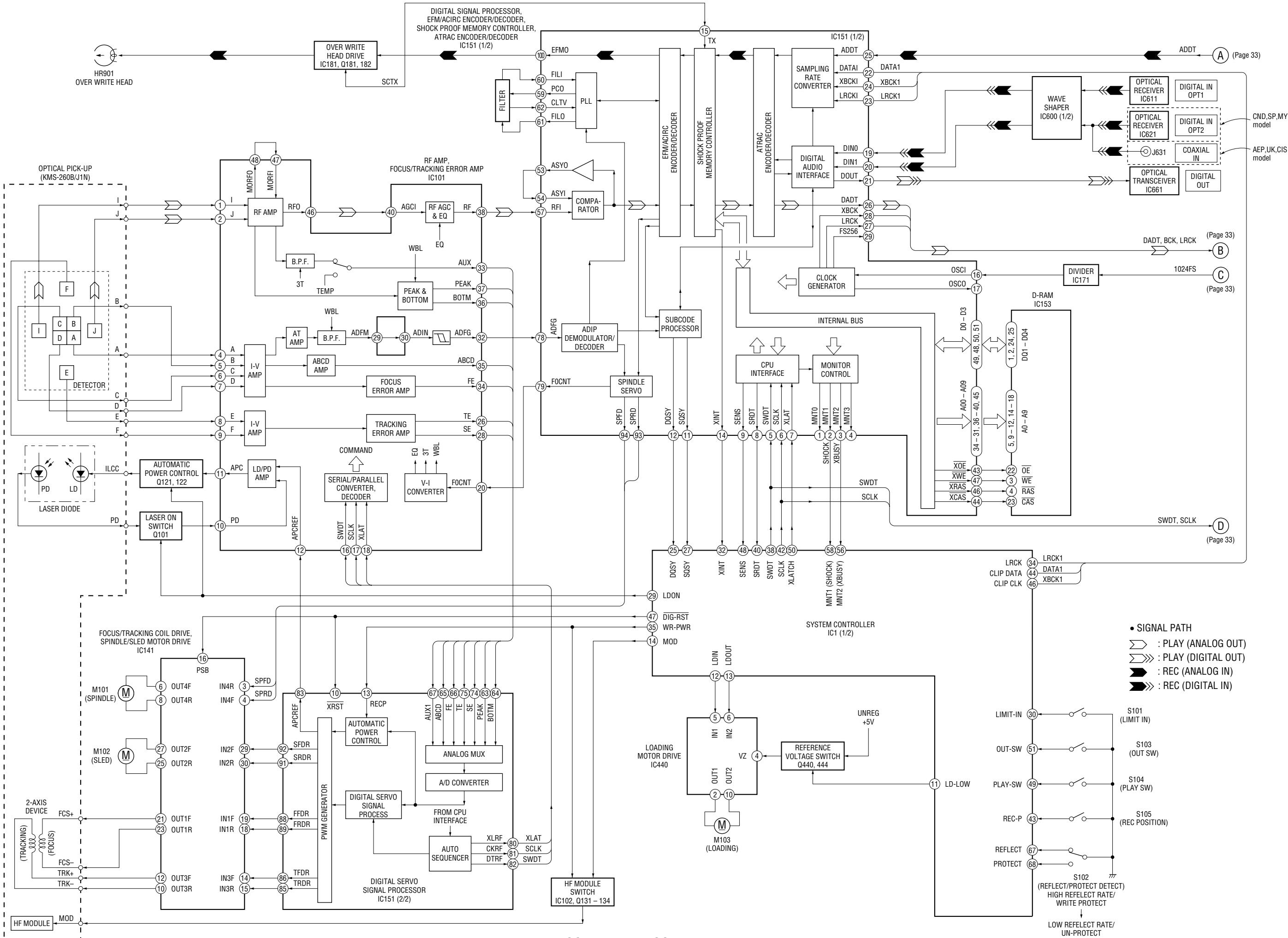
- \square : parts extracted from the component side.
- \square : parts extracted from the conductor side.
- \circ : Through hole.
- \square : Pattern from the side which enables seeing.
(The other layers' patterns are not indicated.)

Caution:

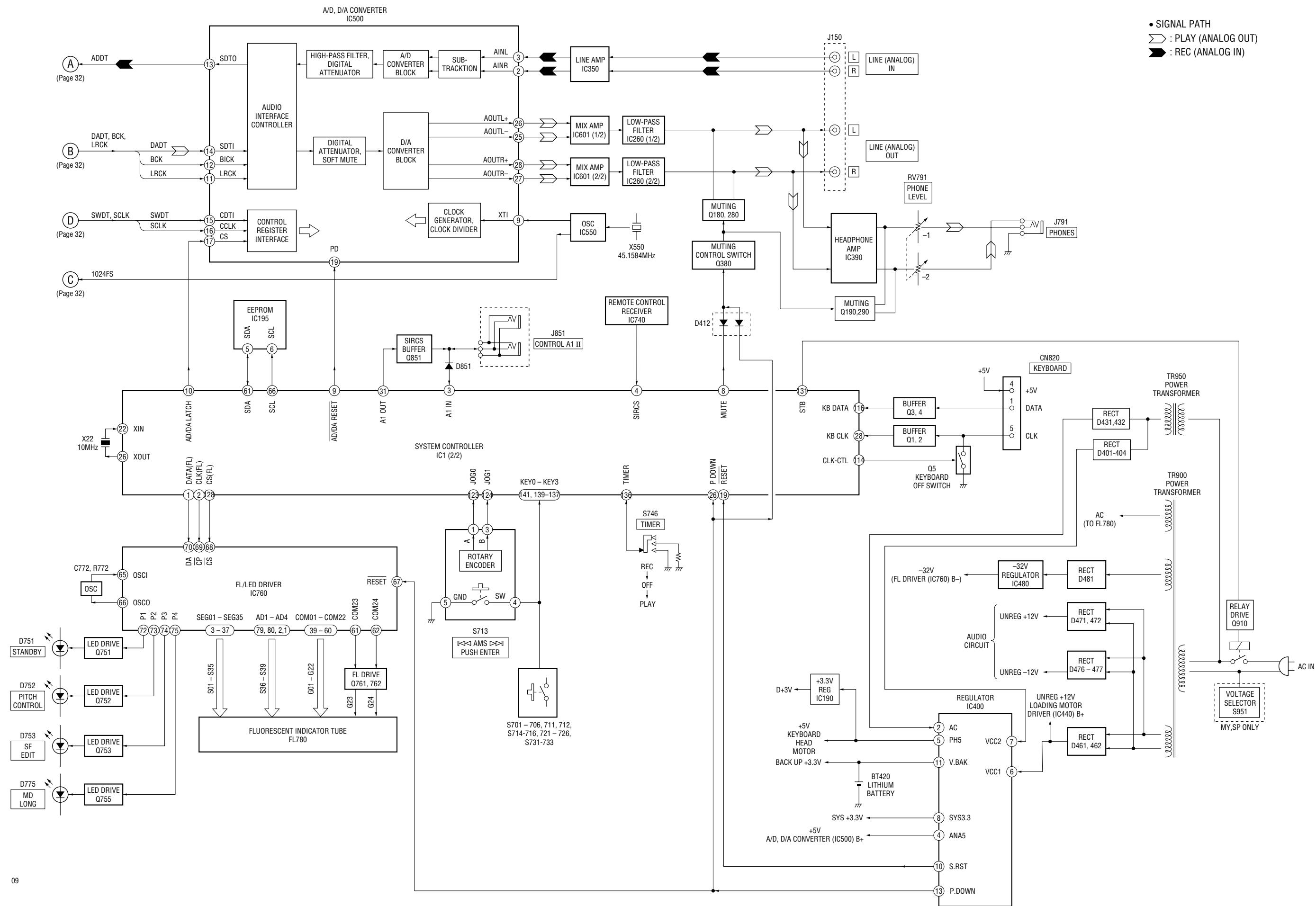
Pattern face side: Parts on the pattern face side seen from the (Side B) pattern face are indicated.

Parts face side: Parts on the parts face side seen from the (Side A) parts face are indicated.

6-2. BLOCK DIAGRAMS – BD SECTION –

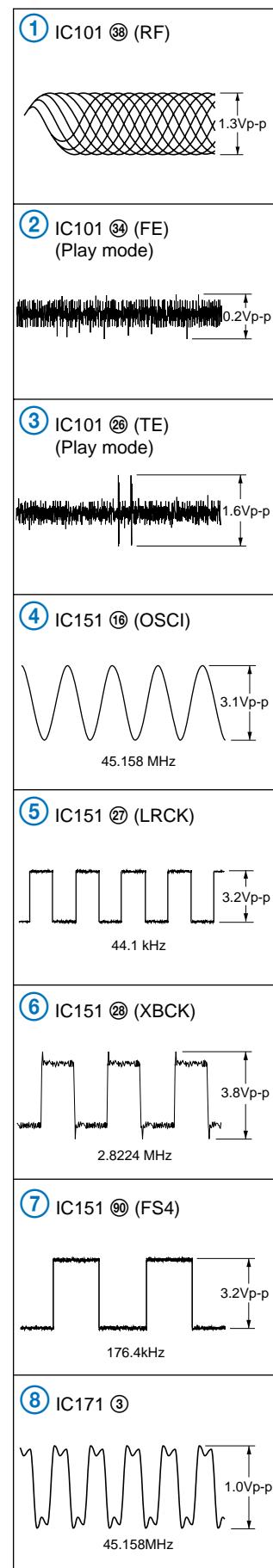


- MAIN SECTION -

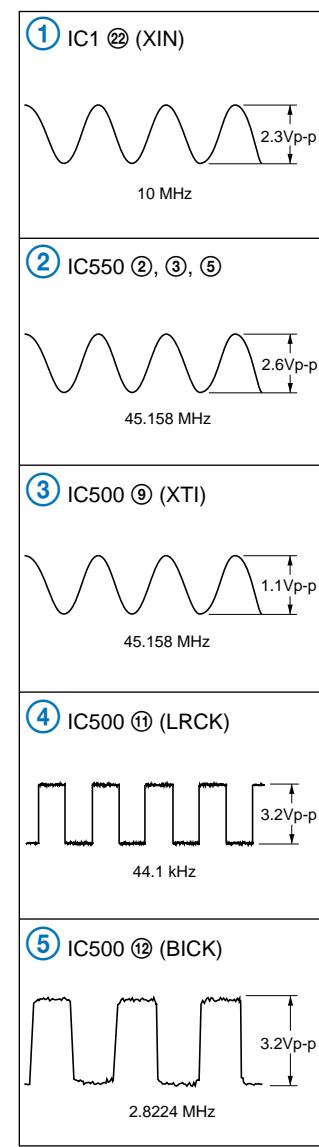


• WAVEFORMS

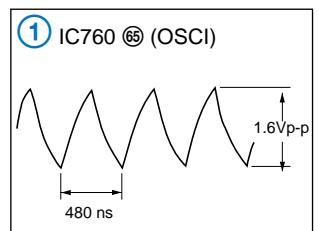
– BD Board –



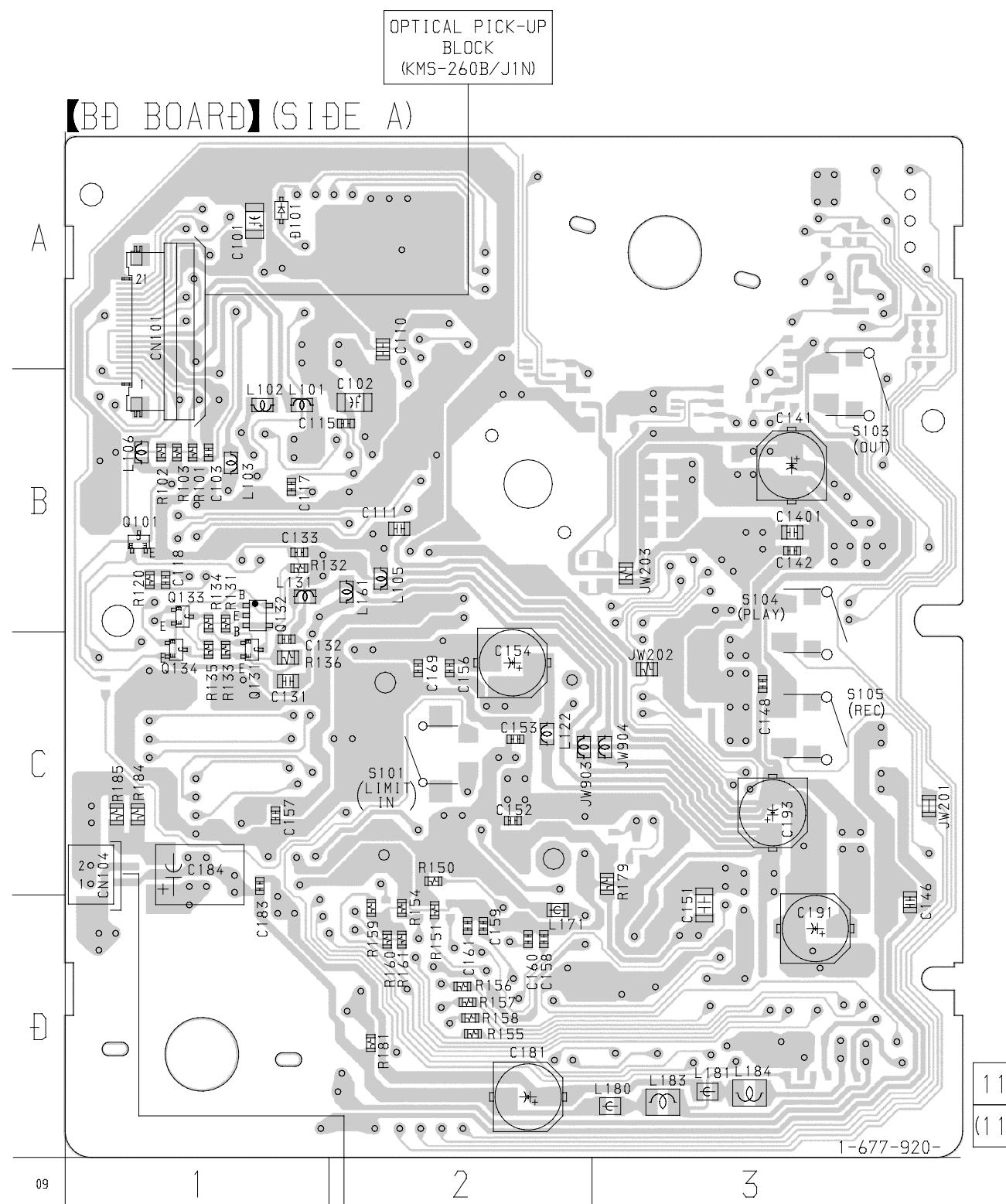
– MAIN Board –



– DISPLAY Board –

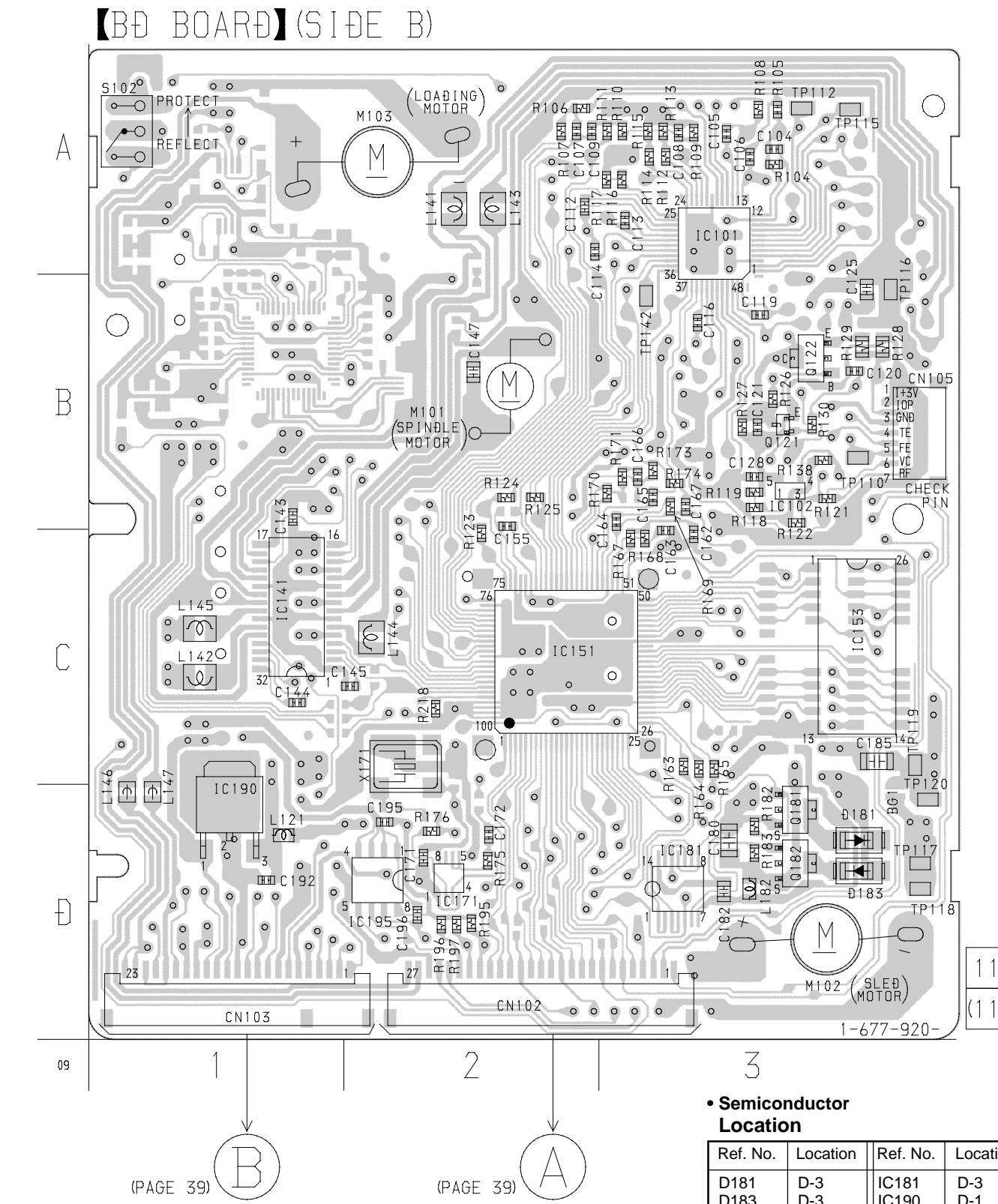


6-3. PRINTED WIRING BOARD - BD SECTION -


• Semiconductor Location

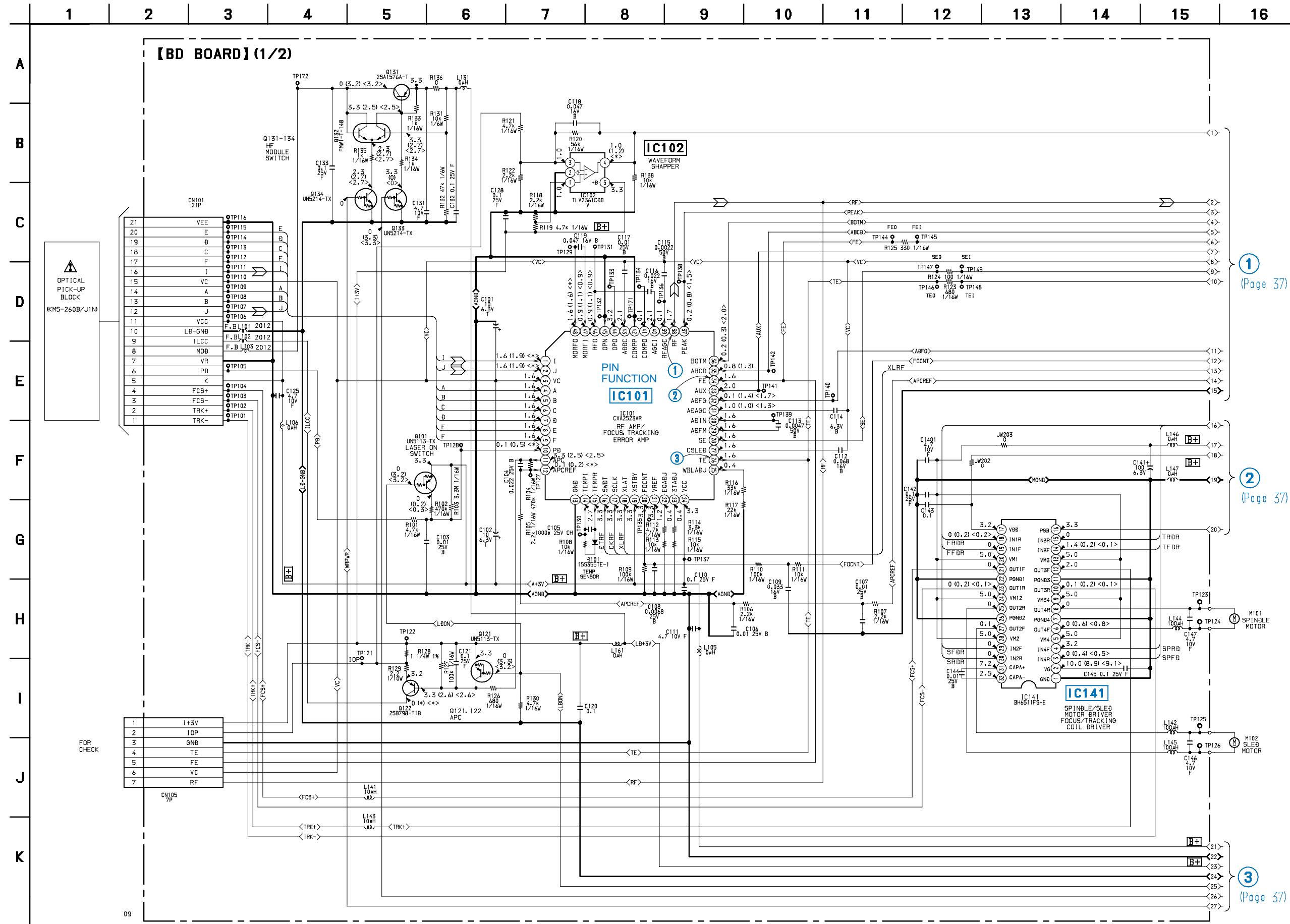
Ref. No.	Location
D101	A-1
Q101	B-1
Q131	C-1
Q132	B-1
Q133	B-1
Q134	C-1

HR901
OVER
WRITE HEAD


• Semiconductor Location

Ref. No.	Location	Ref. No.	Location
D181	D-3	IC181	D-3
D183	D-3	IC190	D-1
IC101	A-3	IC195	D-2
IC102	B-3	Q121	B-3
IC141	C-1	Q122	B-3
IC151	C-2	Q181	D-3
IC153	C-3	Q182	D-3
IC171	D-2		

6-4. SCHEMATIC DIAGRAM – BD SECTION (1/2) • See page 34 for Waveforms. • See page 46 for IC Block Diagrams. • See page 48 for IC Pin Functions. • See page 35 for Printed Wiring Board.



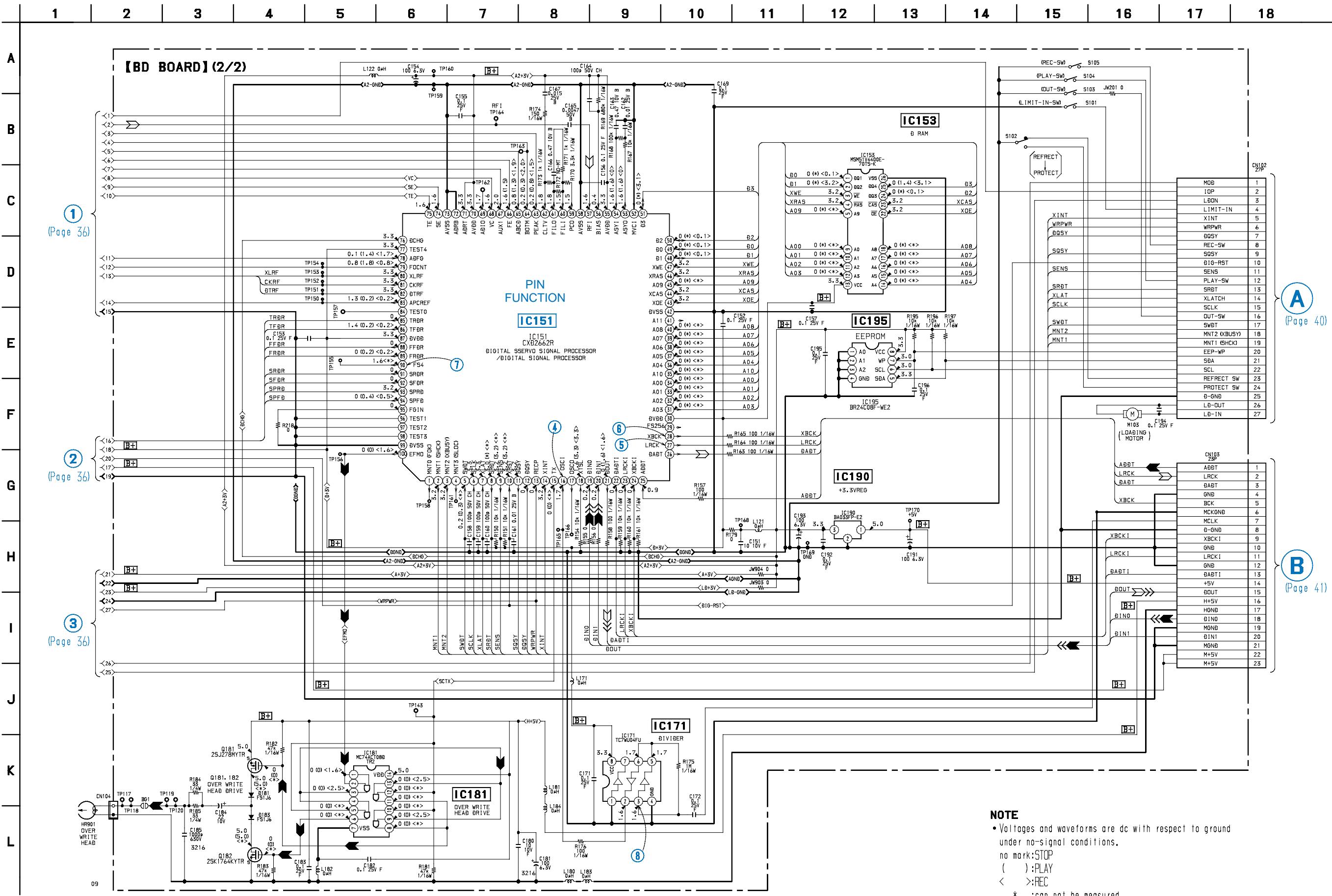
Note: The components identified by mark or dotted line with mark are critical for safety. Replace only with part number specified.

Note: Les composants identifiés par une marque sont critiques pour la sécurité. Ne les remplacer que par une pièce portant le numéro spécifié.

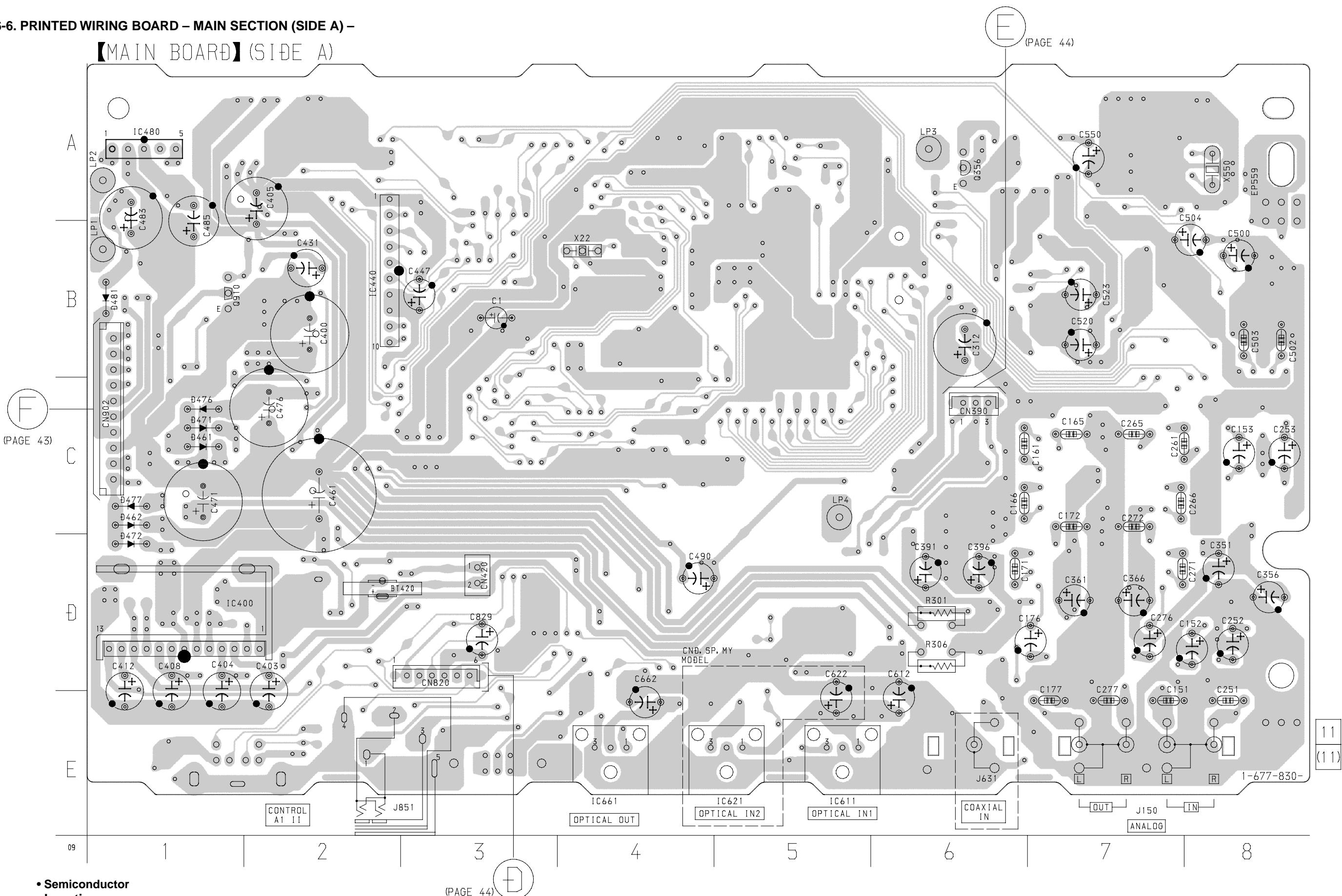
NOTE
• Voltages and waveforms are dc with respect to ground under no-signal conditions.

no mark: STOP
() : PLAY
< > : REC
* : can not be measured.

6-5. SCHEMATIC DIAGRAM – BD SECTION (2/2) • See page 34 for Waveforms. • See page 46 for IC Block Diagrams. • See page 49 for IC Pin Functions. • See page 35 for Printed Wiring Board.



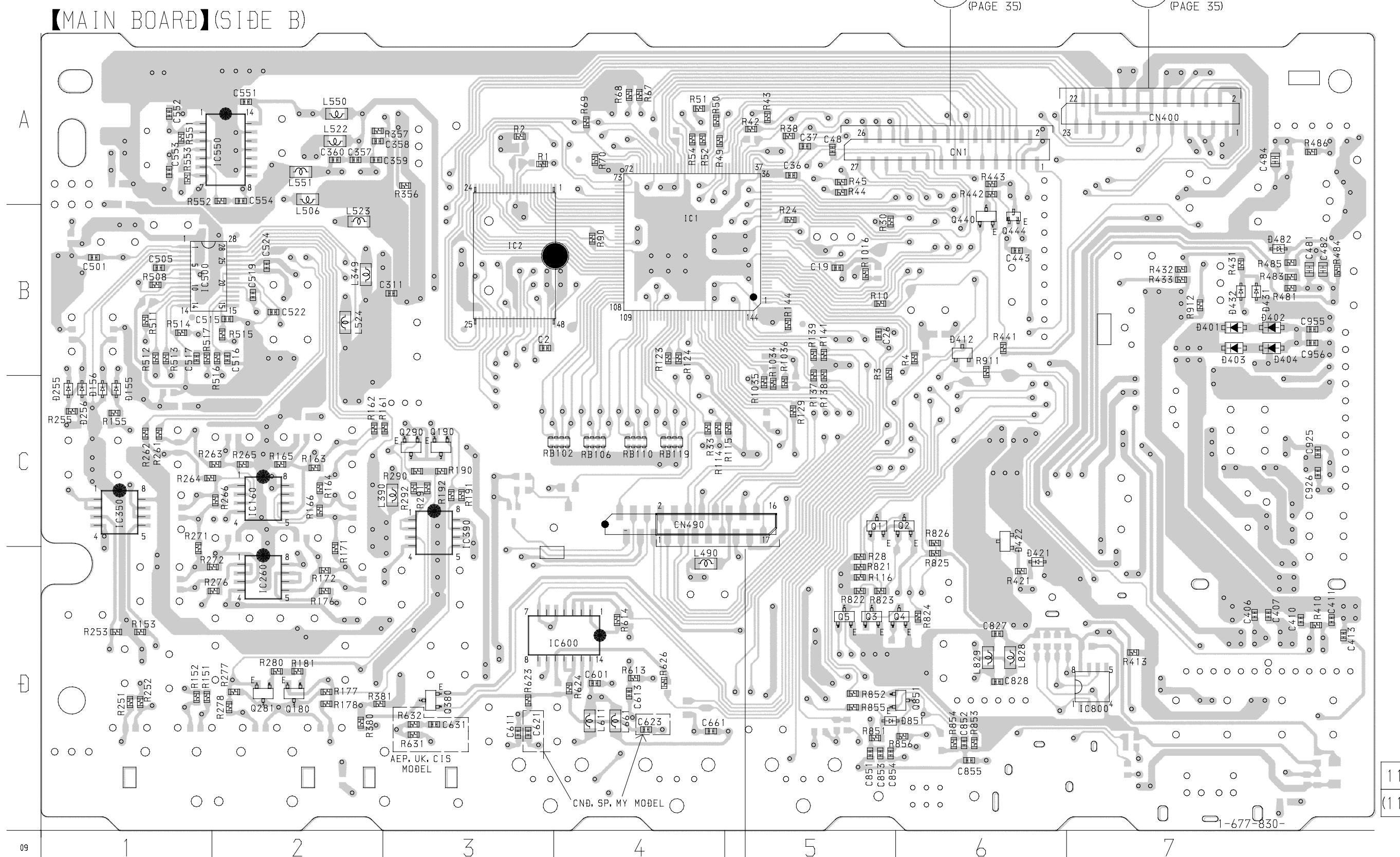
6-6. PRINTED WIRING BOARD - MAIN SECTION (SIDE A) -



• Semiconductor Location

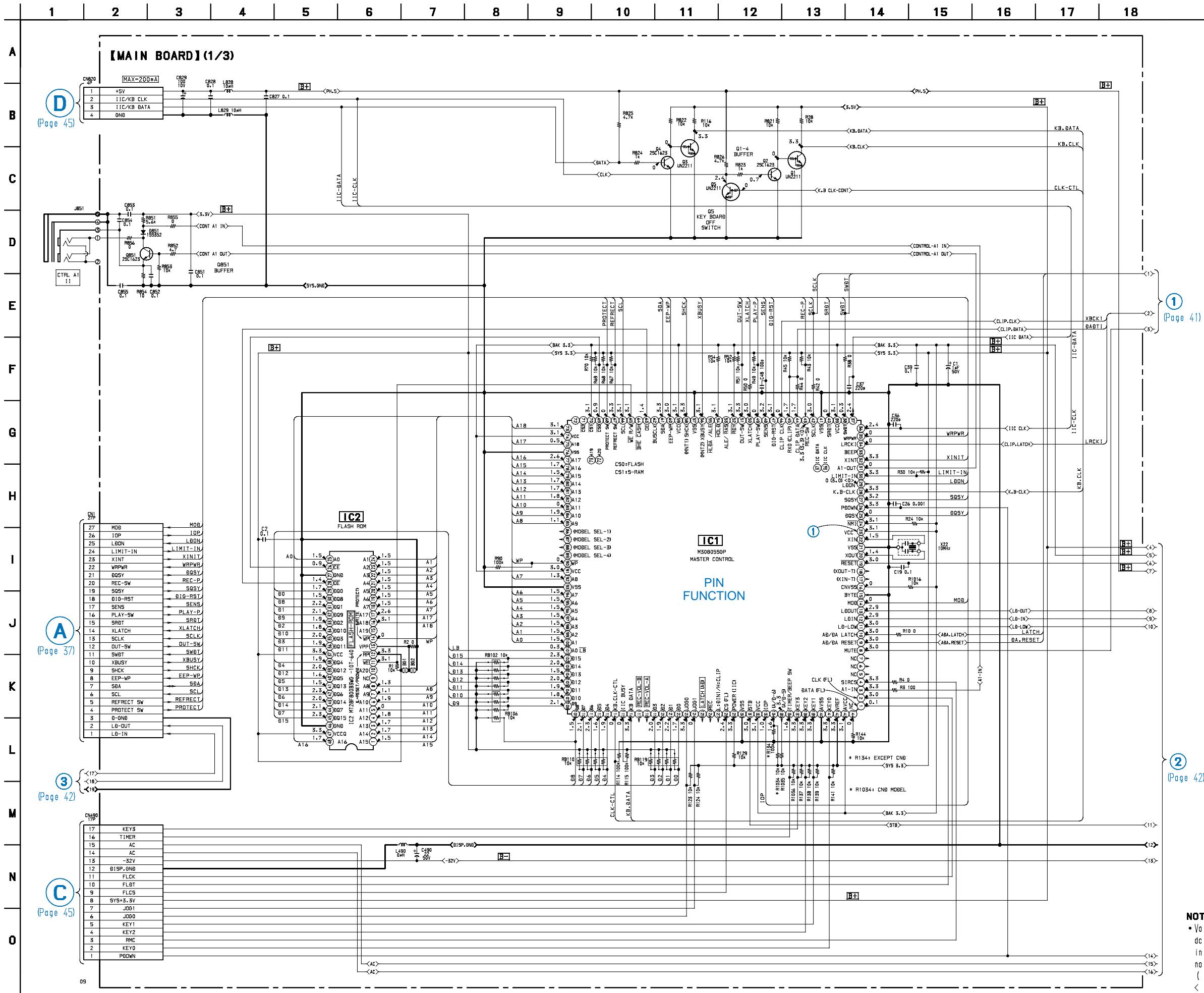
Ref. No.	Location	Ref. No.	Location
D461	C-1	IC440	B-2
D462	C-1	IC480	A-1
D471	C-1	IC611	E-5
D472	D-1	IC621	E-5
D476	C-1	IC661	E-4
D477	C-1	Q356	A-6
D481	B-1	Q910	B-1
IC400	D-1		

6-7. PRINTED WIRING BOARD – MAIN SECTION (SIDE B) –


• Semiconductor Location

Ref. No.	Location						
D155	C-1	D422	C-6	IC390	C-3	Q190	C-3
D156	C-1	D431	B-7	IC500	B-2	Q281	D-2
D255	C-1	D432	B-7	IC550	A-2	Q290	C-3
D256	C-1	D482	B-7	IC600	D-4	Q380	D-3
D401	B-7	D851	D-6	Q1	C-5	Q440	B-6
D402	B-7	IC1	B-4	Q2	C-6	Q444	B-6
D403	B-7	IC2	B-3	Q3	C-5	Q851	D-6
D404	B-7	IC160	C-2	Q4	C-6		
D412	B-6	IC260	D-2	Q5	C-5		
D421	C-6	IC350	C-1	Q180	D-2		

6-8. SCHEMATIC DIAGRAM – MAIN SECTION (1/3) – • See page 34 for Waveforms. • See page 52 for IC Pin Functions

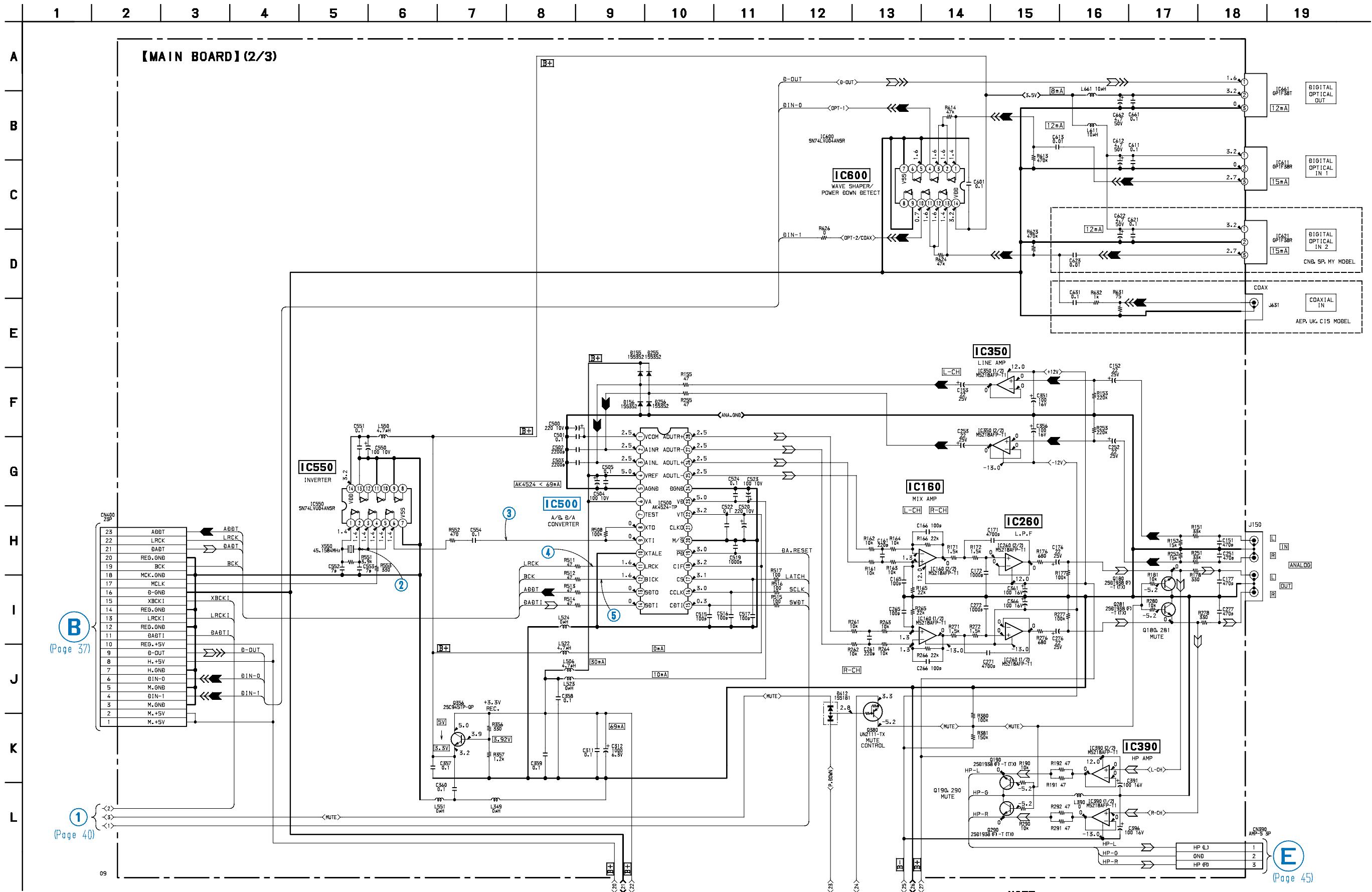


NOTE

- Voltages and waveforms are dc with respect to ground in service mode.

no mark:STOP
 () :PLAY
 < >:REC

6-9. SCHEMATIC DIAGRAM – MAIN SECTION (2/3) – • See page 34 for Waveforms. • See page 47 for IC Block Diagrams



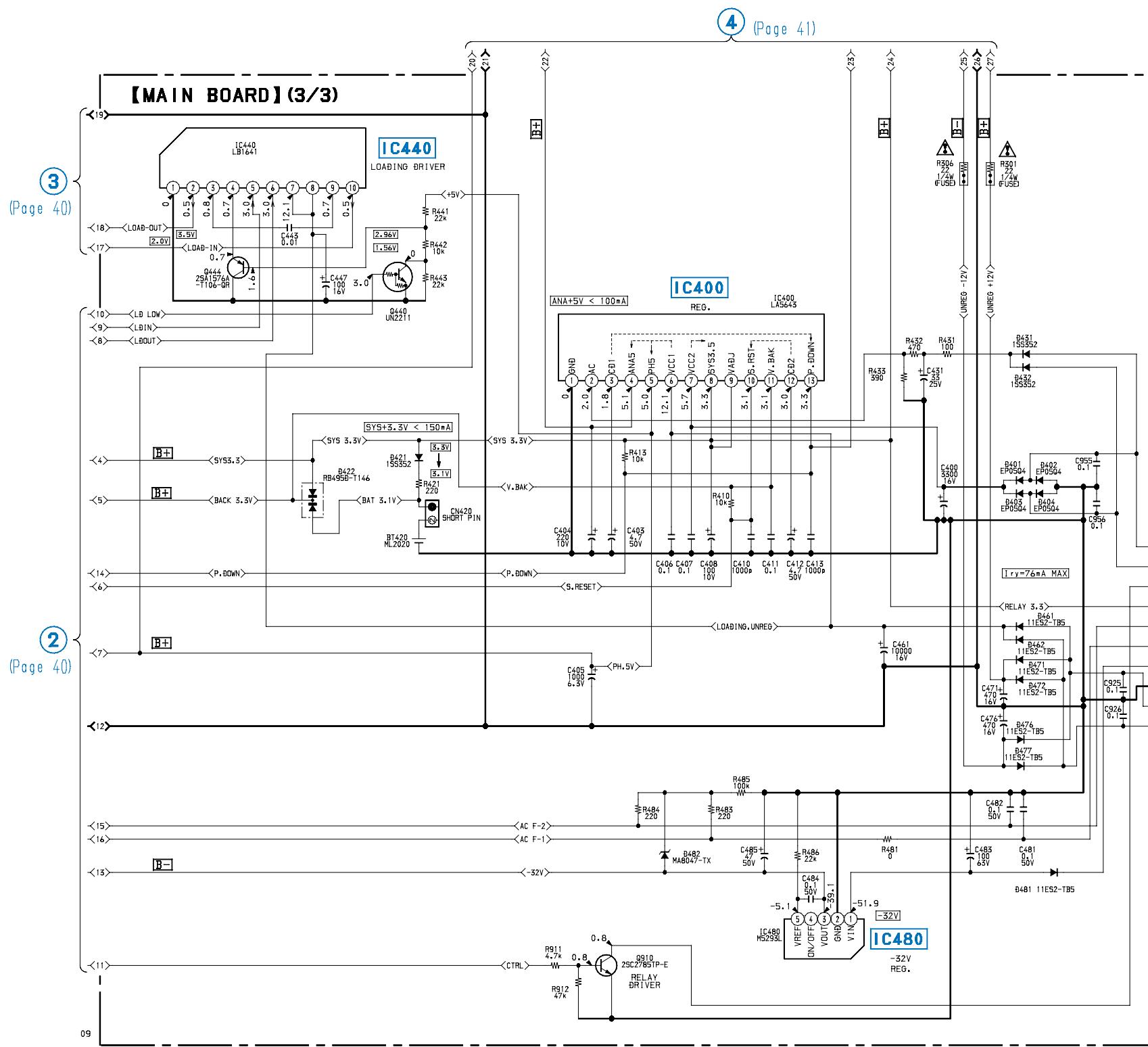
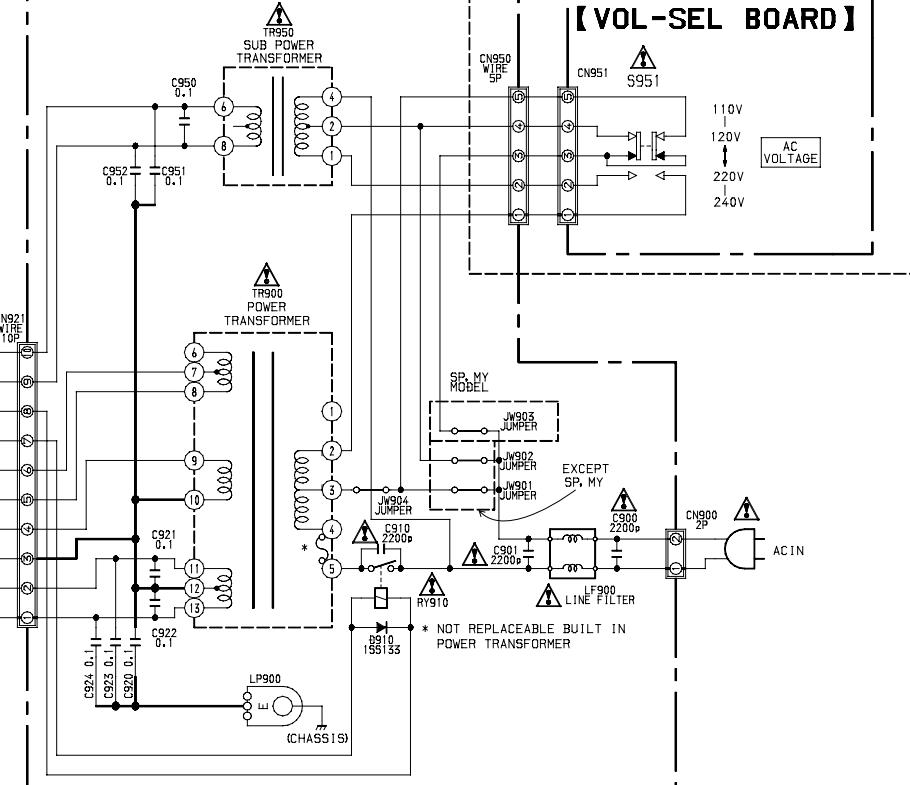
NOTE

- Voltages and waveforms are dc with respect to ground in service mode.
no mark:STOP

6-10. SCHEMATIC DIAGRAM – MAIN SECTION (3/3) – • See page 47 for IC Block Diagrams.

1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17

A

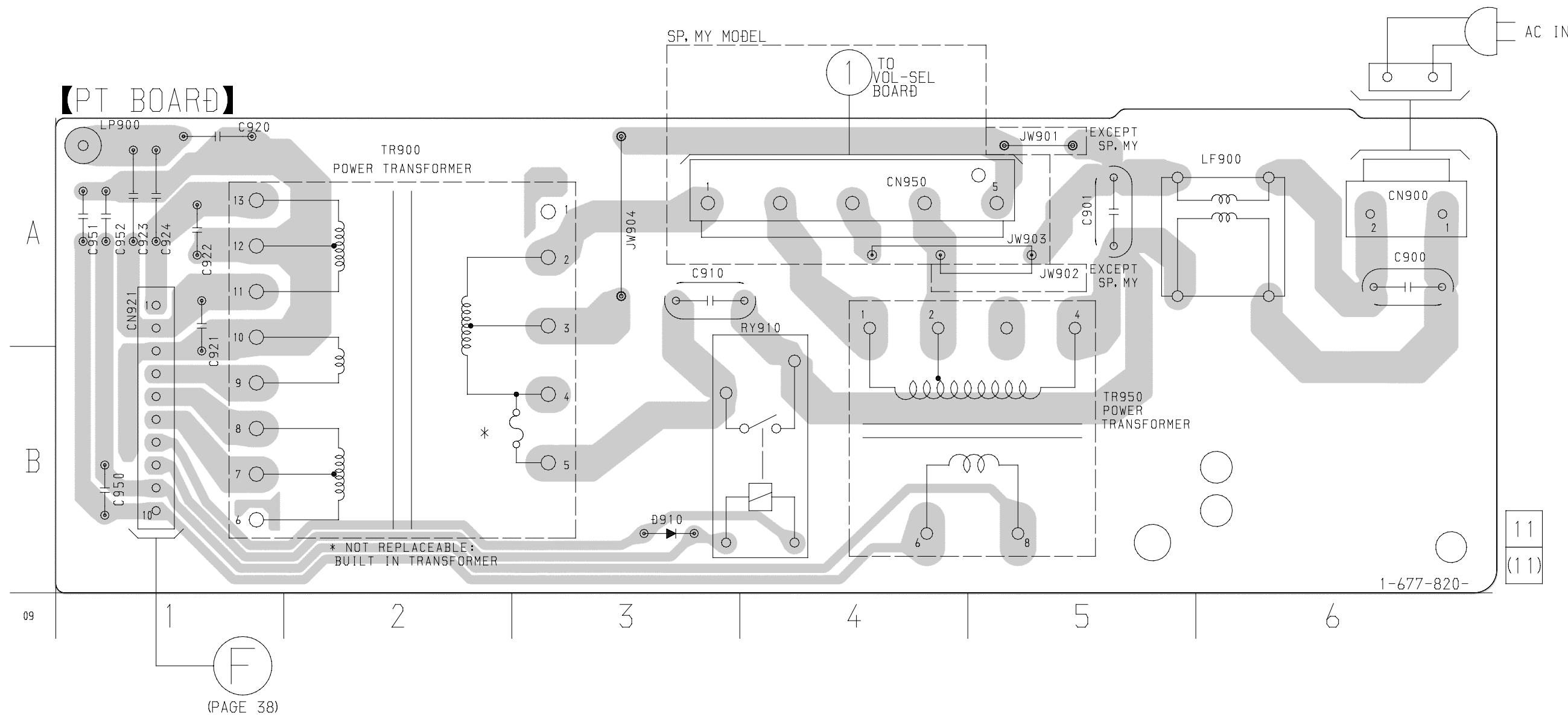
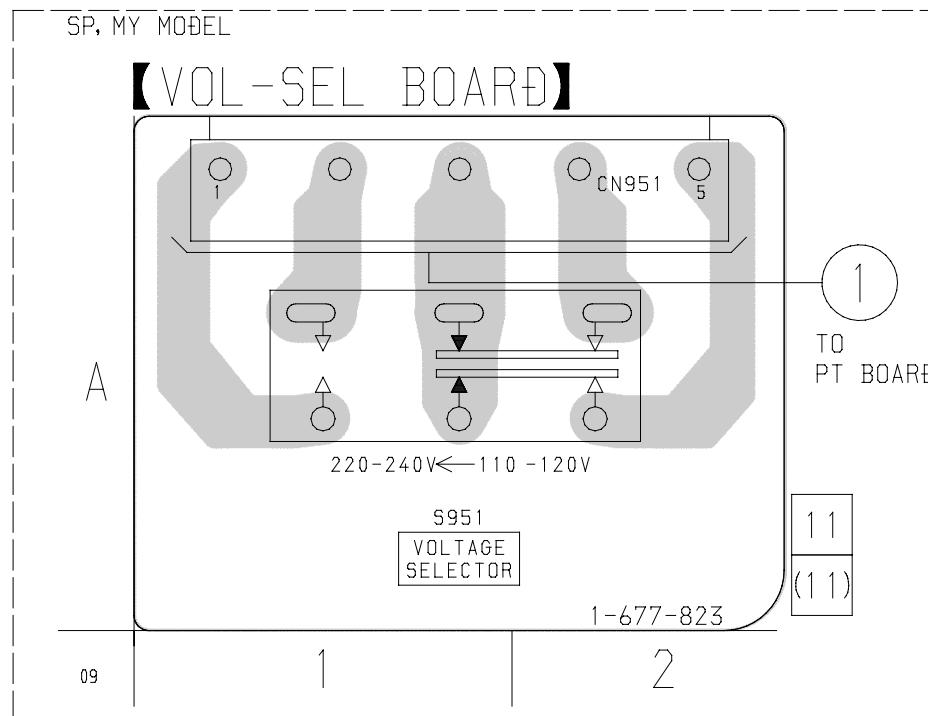
**[PT BOARD]****NOTE**

- Voltages and waveforms are dc with respect to ground in service mode.
- no mark:

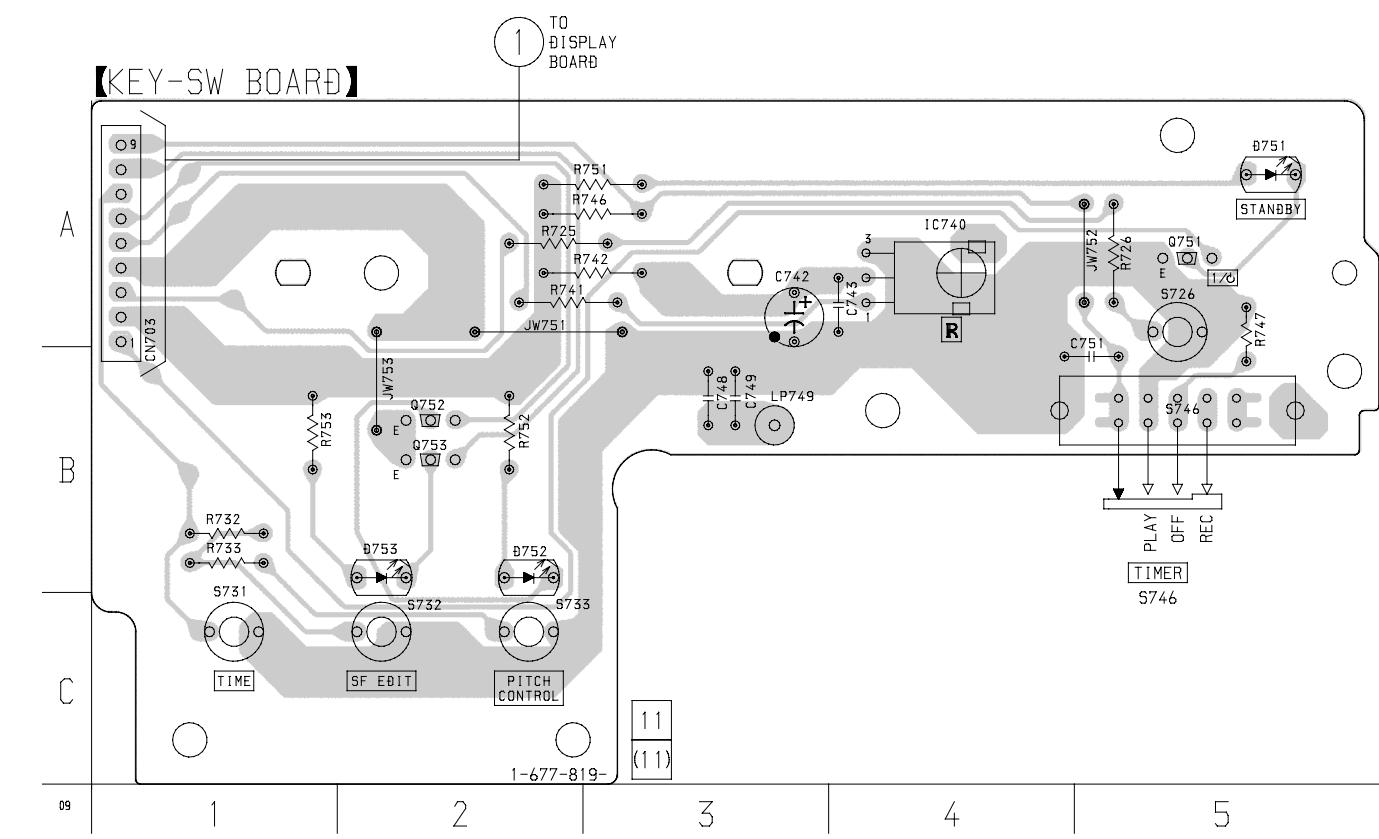
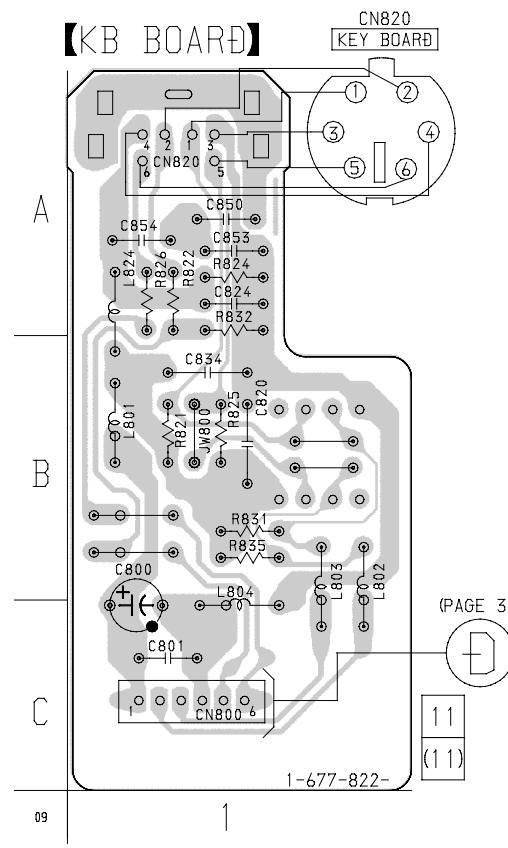
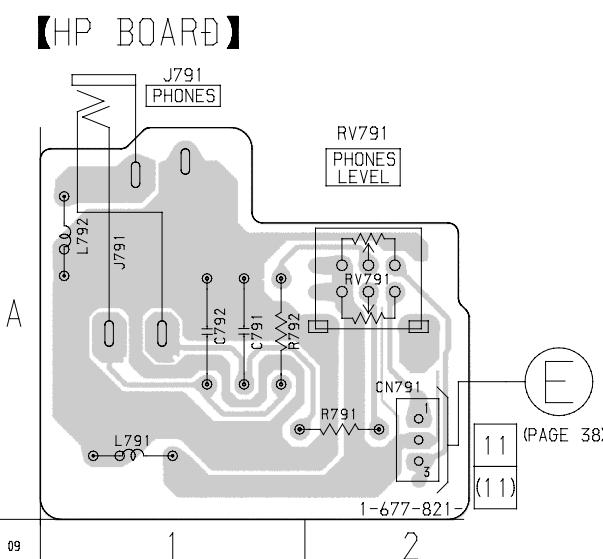
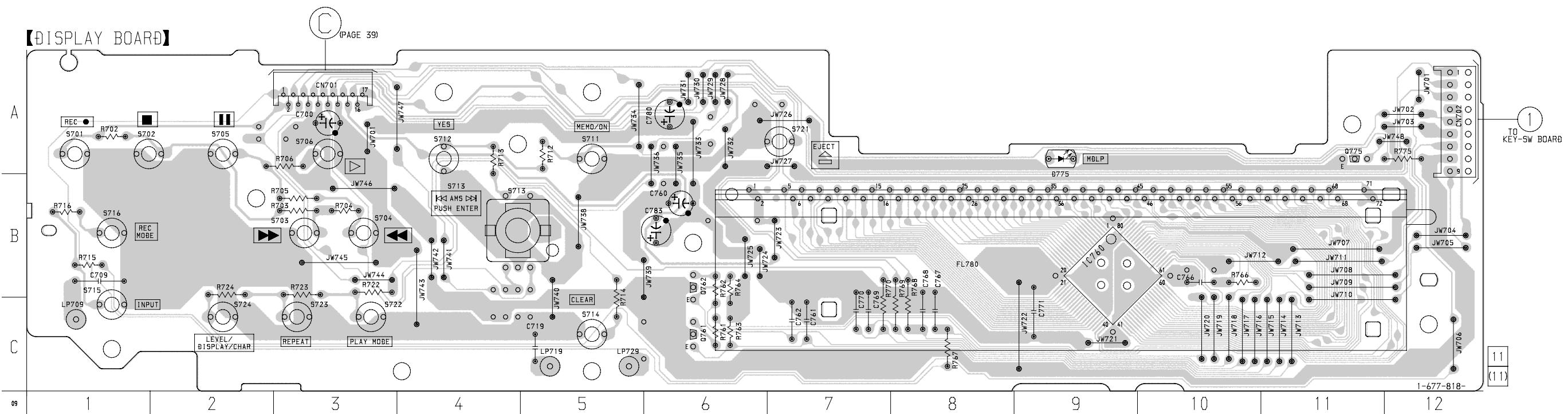
Note:
The components identified by mark or dotted line with mark are critical for safety.
Replace only with part number specified.

Note:
Les composants identifiés par une marque sont critiques pour la sécurité.
Ne les remplacer que par une pièce portant le numéro spécifié.

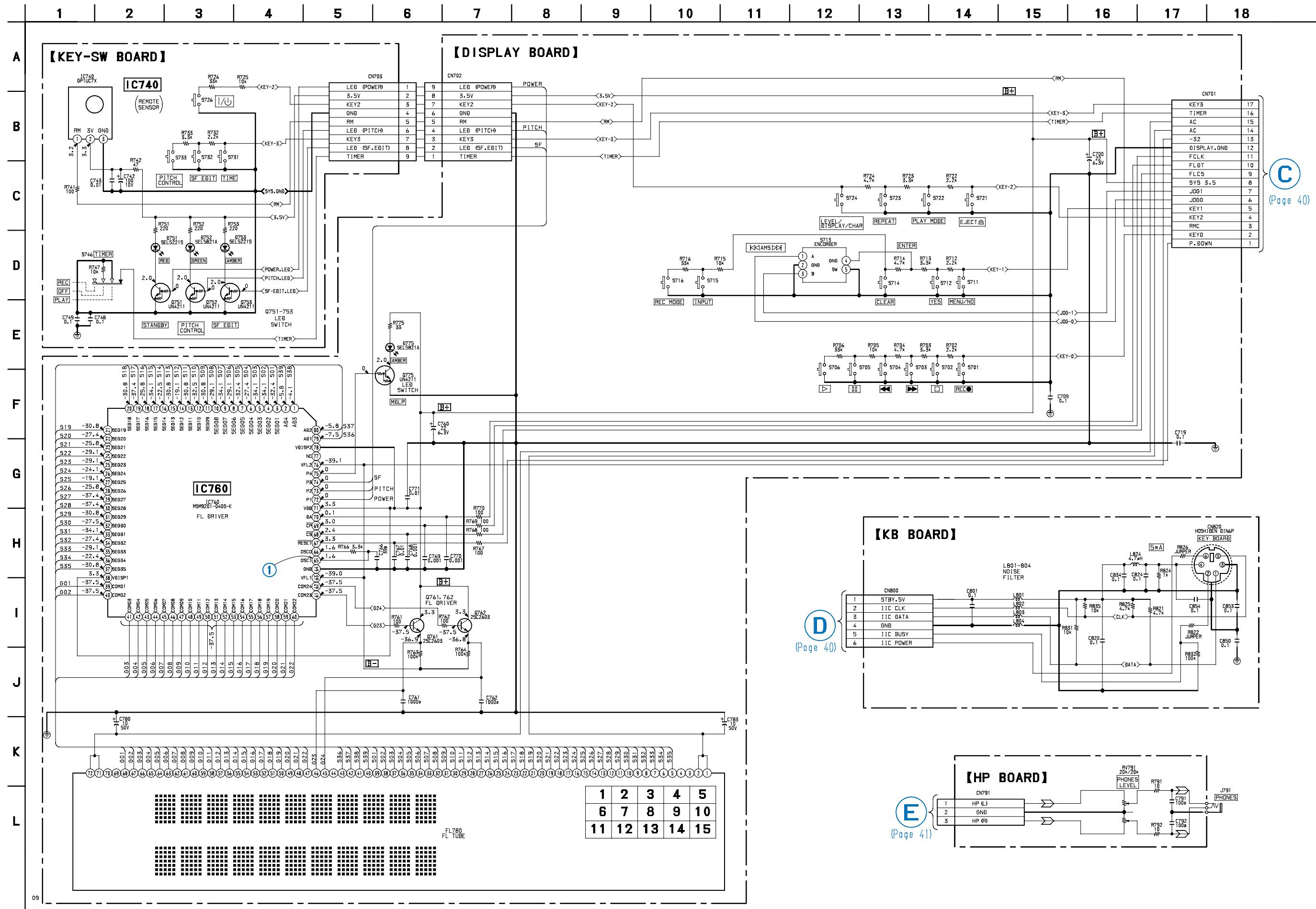
6-11. PRINTED WIRING BOARD – POWER SECTION –



6-12. PRINTED WIRING BOARD – DISPLAY SECTION –

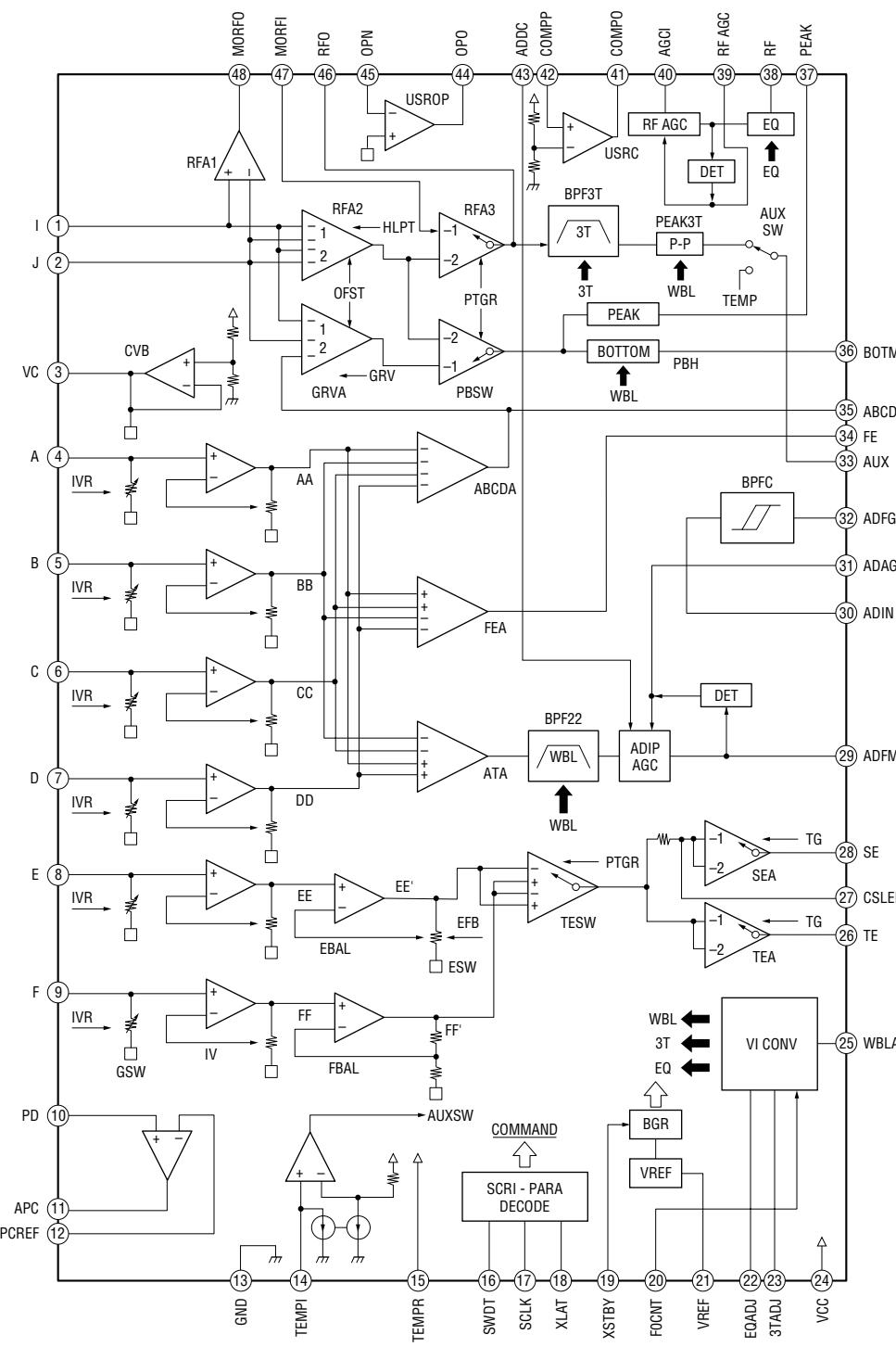


6-13. SCHEMATIC DIAGRAM – DISPLAY SECTION – • See page 34 for Waveforms.

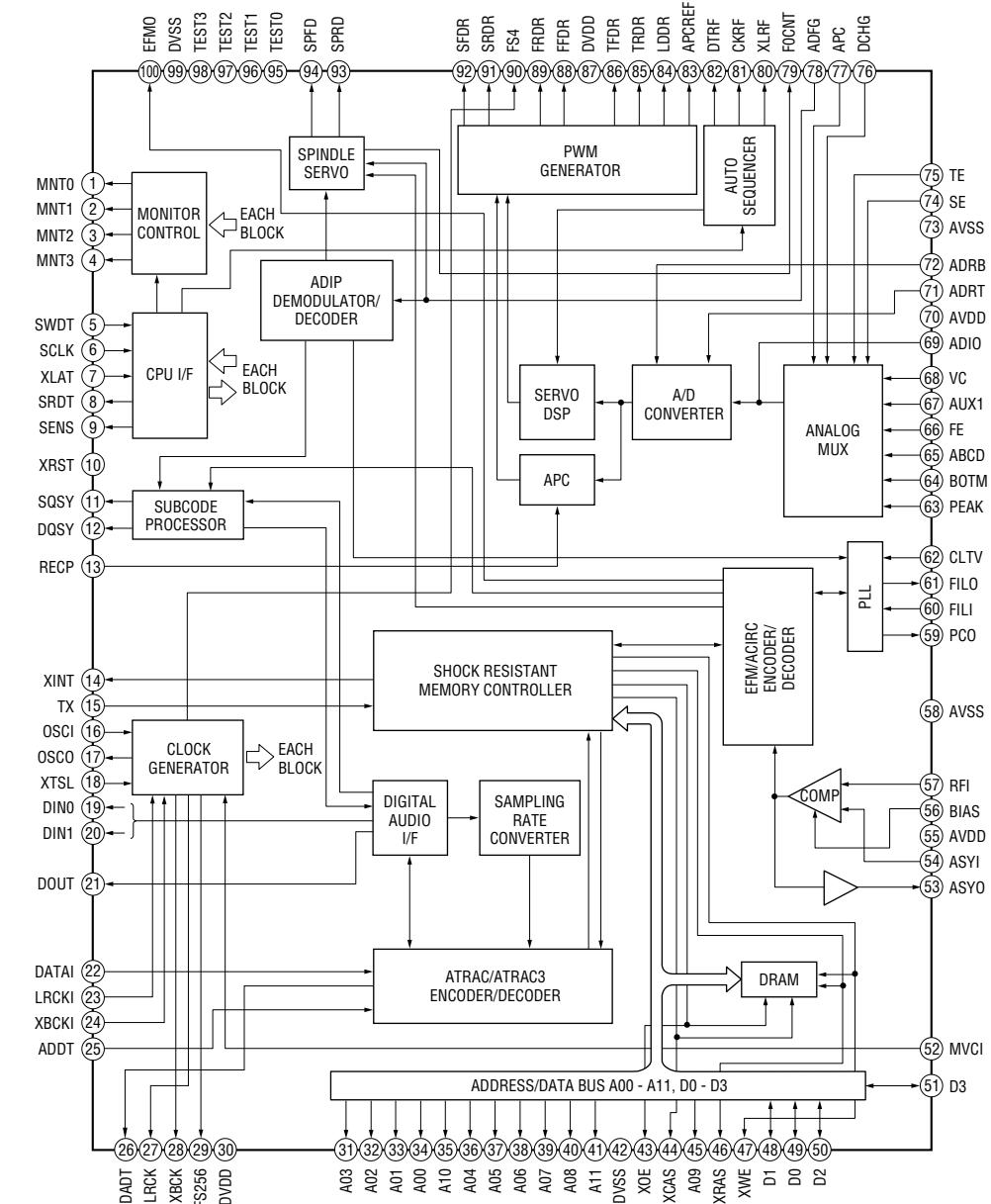


6-14. IC BLOCK DIAGRAMS

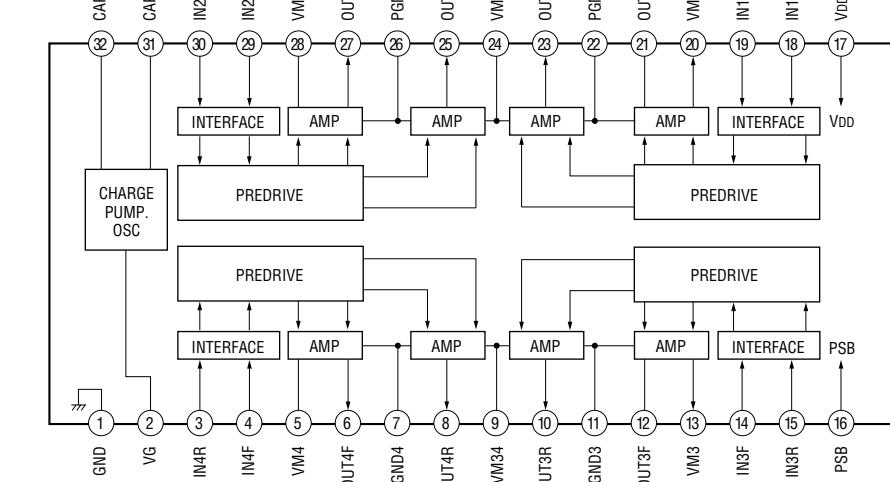
IC101 CXA2523AR (BD BOARD)



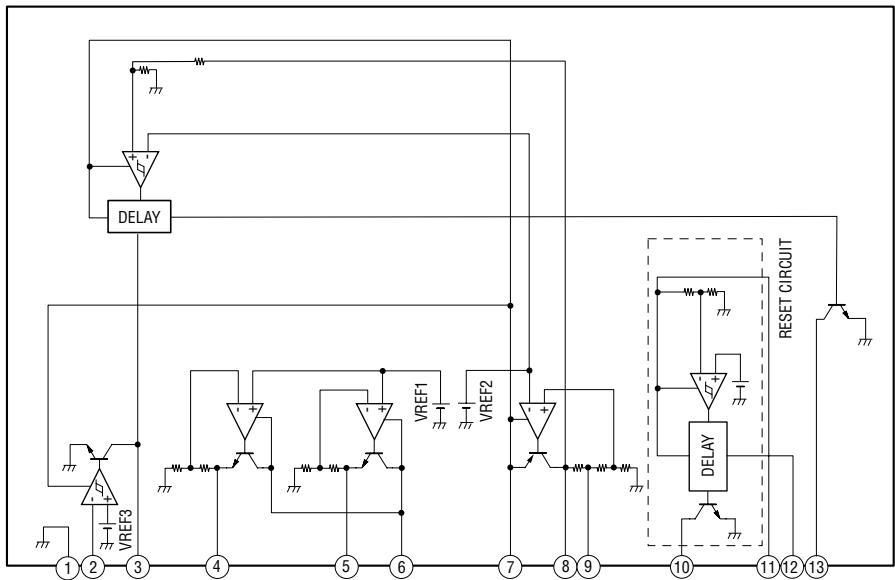
IC151 CXD2662R (BD BOARD)



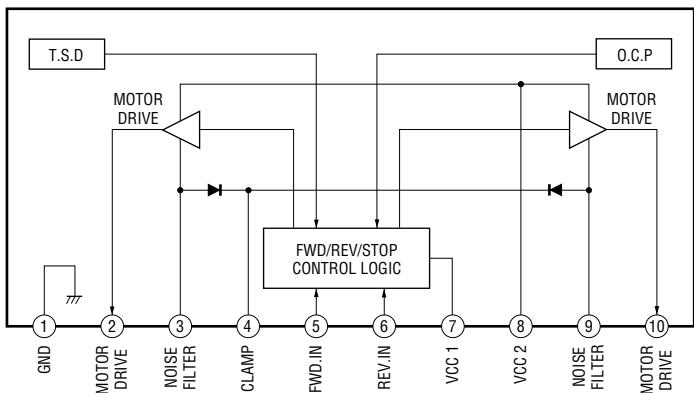
IC141 BH6511FS (BD BOARD)



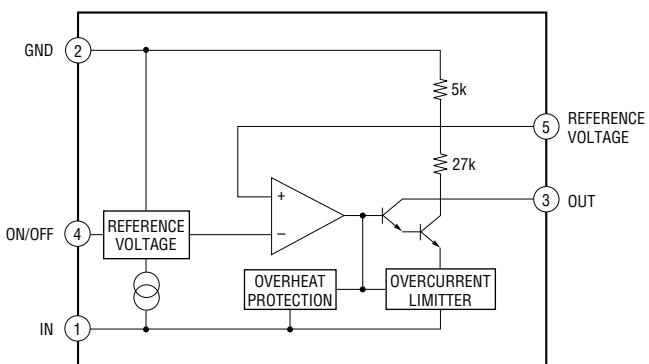
IC400 LA5643 (MAIN BOARD)



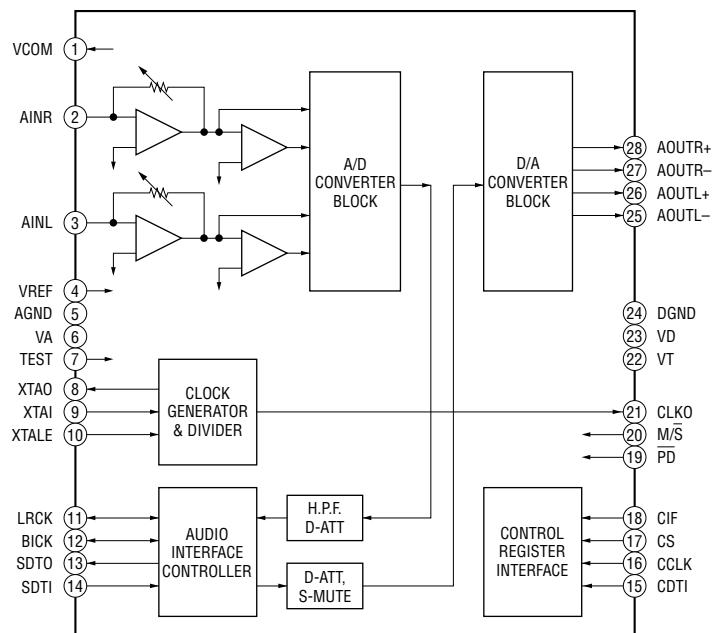
IC440 LB1641 (MAIN BOARD)



IC480 M5293L (MAIN BOARD)



IC500 AK4524-TP (MAIN BOARD)



6-15. IC PIN FUNCTIONS

• IC101 CXA2523AR RF Amplifier (BD BOARD)

Pin No.	Pin Name	I/O	Function
1	I	I	I-V converted RF signal I input
2	J	I	I-V converted RF signal J input
3	VC	O	Middle point voltage (+1.5V) generation output
4 to 9	A to F	I	Signal input from the optical pick-up detector
10	PD	I	Light amount monitor input
11	APC	O	Laser APC output
12	APCREF	I	Reference voltage input for setting laser power
13	GND	—	Ground
14	TEMPI	I	Temperature sensor connection
15	TEMPR	O	Reference voltage output for the temperature sensor
16	SWDT	I	Serial data input from the CXD2662R
17	SCLK	I	Serial clock input from the CXD2662R
18	XLAT	I	Latch signal input from the CXD2662R “L”: Latch
19	XSTBY	I	Stand by signal input “L”: Stand by
20	F0CNT	I	Center frequency control voltage input of BPF22, BPF3T, EQ from the CXD2662R
21	VREF	O	Reference voltage output (Not used)
22	EQADJ	I/O	Center frequency setting pin for the internal circuit EQ
23	3TADJ	I/O	Center frequency setting pin for the internal circuit BPF3T
24	Vcc	—	+3V power supply
25	WBLADJ	I/O	Center frequency setting pin for the internal circuit BPF22
26	TE	O	Tracking error signal output to the CXD2662R
27	CSLED	—	External capacitor connection pin for the sled error signal LPF
28	SE	O	Sled error signal output to the CXD2662R
29	ADFM	O	FM signal output of ADIP
30	ADIN	I	ADIP signal comparator input ADFM is connected with AC coupling
31	ADAGC	—	External capacitor connection pin for AGC of ADIP
32	ADFG	O	ADIP duplex signal output to the CXD2662R
33	AUX	O	I ₃ signal/temperature signal output to the CXD2662R (Switching with a serial command)
34	FE	O	Focus error signal output to the CXD2662R
35	ABCD	O	Light amount signal output to the CXD2662R
36	BOTM	O	RF/ABCD bottom hold signal output to the CXD2662R
37	PEAK	O	RF/ABCD peak hold signal output to the CXD2662R
38	RF	O	RF equalizer output to the CXD2662R
39	RFAGC	—	External capacitor connection pin for the RF AGC circuit
40	AGCI	I	Input to the RF AGC circuit The RF amplifier output is input with AC coupling
41	COMPO	O	User comparator output (Not used)
42	COMPP	I	User comparator input (Fixed at “L”)
43	ADDC	I/O	External capacitor pin for cutting the low band of the ADIP amplifier
44	OPO	O	User operation amplifier output (Not used)
45	OPN	I	User operation amplifier inversion input (Fixed at “L”)
46	RFO	O	RF amplifier output
47	MORFI	I	Groove RF signal is input with AC coupling
48	MORFO	O	Groove RF signal output

• Abbreviation

APC: Auto Power Control
AGC: Auto Gain Control

• IC151 CXD2662R Digital Signal Processor, Digital Servo Signal Processor (BD BOARD)

Pin No.	Pin Name	I/O	Function
1	MNT0 (FOK)	O	FOK signal output to the system control (monitor output) “H” is output when focus is on
2	MNT1 (SHCK)	O	Track jump detection signal output to the system control (monitor output)
3	MNT2 (XBUSY)	O	Monitor 2 output to the system control (monitor output)
4	MNT3 (SLOC)	O	Monitor 3 output to the system control (monitor output)
5	SWDT	I	Writing data signal input from the system control
6	SCLK	I (S)	Serial clock signal input from the system control
7	XLAT	I (S)	Serial latch signal input from the system control
8	SRDT	O (3)	Reading data signal output to the system control
9	SENS	O (3)	Internal status (SENSE) output to the system control
10	XRST	I (S)	Reset signal input from the system control “L”: Reset
11	SQSY	O	Subcode Q sync (SCOR) output to the system control “L” is output every 13.3 msec. Almost all, “H” is output
12	DQSY	O	Digital In U-bit CD format or MD format subcode Q sync (SCOR) output to the system control
13	RECP	I	Laser power switching input from the system control “H”: Recording, “L”: Playback
14	XINT	O	Interrupt status output to the system control
15	TX	I	Recording data output enable input from the system control
16	OSCI	I	System clock input (512Fs=22.5792 MHz)
17	OSCO	O	System clock output (512Fs=22.5792 MHz) (Not used)
18	XTSL	I	System clock frequency setting “L”: 45.1584 MHz, “H”: 22.5792 MHz (Fixed at “H”)
19	DIN0	I	Digital audio input (Optical input)
20	DIN1	I	Digital audio input (Optical input)
21	DOUT	O	Digital audio output (Optical output)
22	DADTI	I	Serial data input
23	LRCKI	I	LR clock input “H” : Lch, “L” : R ch
24	XBCKI	I	Serial data clock input
25	ADDT	I	Data input from the A/D converter
26	DADT	O	Data output to the D/A converter
27	LRCK	O	LR clock output for the A/D and D/A converter (44.1 kHz)
28	XBCK	O	Bit clock output to the A/D and D/A converter (2.8224 MHz)
29	FS256	O	11.2896 MHz clock output (Not used)
30	DVDD	—	+3V power supply (Digital)
31 to 34	A03 to A00	O	DRAM address output
35	A10	O	DRAM address output (Not used)
36 to 40	A04 to A08	O	DRAM address output
41	A11	O	DRAM address output (Not used)
42	DVSS	—	Ground (Digital)
43	XOE	O	Output enable output for DRAM
44	XCAS	O	CAS signal output for DRAM
45	A09	O	Address output for DRAM
46	XRAS	O	\overline{RAS} signal output for DRAM
47	XWE	O	Write enable signal output for DRAM

* I (S) stands for Schmidt input, I (A) for analog input, O (3) for 3-state output, and O (A) for analog output in the column I/O

Pin No.	Pin Name	I/O	Function
48	D1	I/O	
49	D0	I/O	Data input/output for DRAM
50, 51	D2, D3	I/O	
52	MVCI	I (S)	Clock input from an external VCO (Fixed at "L")
53	ASYO	O	Playback EFM duplex signal output
54	ASYI	I (A)	Playback EFM comparator slice level input
55	AVDD	—	+3V power supply (Analog)
56	BIAS	I (A)	Playback EFM comparator bias current input
57	RFI	I (A)	Playback EFM RF signal input
58	AVSS	—	Ground (Analog)
59	PCO	O (3)	Phase comparison output for the recording/playback EFM master PLL
60	FILI	I (A)	Filter input for the recording/playback EFM master PLL
61	FILO	O (A)	Filter output for the recording/playback EFM master PLL
62	CLTV	I (A)	Internal VCO control voltage input for the recording/playback EFM master PLL
63	PEAK	I (A)	Light amount signal peak hold input from the CXA2523AR
64	BOTM	I (A)	Light amount signal bottom hold input from the CXA2523AR
65	ABCD	I (A)	Light amount signal input from the CXA2523AR
66	FE	I (A)	Focus error signal input from the CXA2523AR
67	AUX1	I (A)	Auxiliary A/D input
68	VC	I (A)	Middle point voltage (+1.5V) input from the CXA2523AR
69	ADIO	O (A)	Monitor output of the A/D converter input signal (Not used)
70	AVDD	—	+3V power supply (Analog)
71	ADRT	I (A)	A/D converter operational range upper limit voltage input (Fixed at "H")
72	ADRB	I (A)	A/D converter operational range lower limit voltage input (Fixed at "L")
73	AVSS	—	Ground (Analog)
74	SE	I (A)	Sled error signal input from the CXA2523AR
75	TE	I (A)	Tracking error signal input from the CXA2523AR
76	DCHG	I (A)	Connected to +3V power supply
77	APC	I (A)	Error signal input for the laser digital APC (Fixed at "L")
78	ADFG	I (S)	ADIP duplex FM signal input from the CXA2523AR (22.05 ± 1 kHz)
79	F0CNT	O	Filter f0 control output to the CXA2523AR
80	XLRF	O	Control latch output to the CXA2523AR
81	CKRF	O	Control clock output to the CXA2523AR
82	DTRF	O	Control data output to the CXA2523AR
83	APCREF	O	Reference PWM output for the laser APC
84	TEST0	O	PWM output for the laser digital APC (Not used)
85	TRDR	O	Tracking servo drive PWM output (-)

• Abbreviation

EFM: Eight to Fourteen Modulation

PLL : Phase Locked Loop

VCO: Voltage Controlled Oscillator

Pin No.	Pin Name	I/O	Function
86	TFDR	O	Tracking servo drive PWM output (+)
87	DVDD	—	+3V power supply (Digital)
88	FFDR	O	Focus servo drive PWM output (+)
89	FRDR	O	Focus servo drive PWM output (-)
90	FS4	O	176.4 kHz clock signal output (X'tal) (Not used)
91	SRDR	O	Sled servo drive PWM output (-)
92	SFDR	O	Sled servo drive PWM output (+)
93	SPRD	O	Spindle servo drive PWM output (-)
94	SPFD	O	Spindle servo drive PWM output (+)
95	FGIN	I (S)	Test input (Fixed at "L")
96 to 98	TEST1 to TEST3	I	
99	DVSS	—	Ground (Digital)
100	EFMO	O	EFM output when recording

- Abbreviation

EFM: Eight to Fourteen Modulation

• IC1 M30805SGP SYSTEM CONTROL (MAIN BOARD)

Pin No.	Pin Name	I/O	Function
1	DATA(FL)	O	Serial data signal output to the display driver.
2	CLK(FL)	O	Serial clock signal output to the display driver. L: Active
3	A1-IN	I	A1 Control input. (Fixed at L)
4	SIRCS	I	Remote control input.
5 to 7	NC	—	Not used.
8	MUTE	O	Line out muting output. L: Mute
9	AD/DA RESET	O	Reset signal output to the AK4524. L: Active
10	AD/DA LATCH	O	Latch signal output to the AK4524. L: Active
11	LD-LOW	O	Loading motor voltage control output L: High voltage H: Low voltage
12	LDIN	I	Loading motor control input. H: IN
13	LDOUT	O	Loading motor control output. H: OUT
14	MOD	O	Laser modulation switching signal output. L: OFF H: ON
15	BYTE	I	Data bus changed input. (Connected to ground.)
16	CNVSS	—	Ground.
17	XIN-T	O	Not used .
18	XOUT-T	O	Not used .
19	RESET	I	System rest input. L : ON
20	XOUT	O	Main clock output. (10MHz)
21	VSS	—	Ground.
22	XIN	I	Main clock input. (10MHz)
23	VCC	—	Power supply. (+3.3V)
24	NMI	I	Fixed at H. (Pull-up)
25	DQSY	I	Digital in sync input. (Record system)
26	P.DOWN	I	Power down detection input. L: Power down
27	SQSY	I	ADIP (MO) sync or subcode Q (PIT) sync input from CXD2662R.(Playback system)
28	K.B-CLK	I	Keyboard clock input.
29	LDON	O	Laser ON/OFF control output. H: Laser ON
30	LIMIT-IN	I	Detection input from the limit switch. L: Sled limit-In H: Sled limit-Out
31	A1 OUT	O	A1 Control output.
32	XINIT	I	Interrupt status input from CXD2662R.
33	BEEP	O	Beep output.
34	LRCKI	I	LR clock input.
35	WR PWR	O	Write power ON/OFF output. L: OFF H: ON
36	IIC CLK	I/O	IIC serial clock input/output.
37	IIC DATA	I/O	IIC serial data input/output.
38	SWDT	O	Writing data signal output to the serial bus.
39	VCC	—	Power supply. (+3.3V)
40	SRDT	I	Reading data signal input from the serial bus.
41	VSS	—	Ground.
42	SCLK	O	Clock signal output to the serial bus.
43	REC-SW	I	Detection signal input from the recording position detection switch. L: REC
44	CLIP DATA	O	CLIP serial data output.
45	RX0(CLIP)	I	CLIP serial data input.
46	CLIP CLK	O	CLIP serial clock output.
47	DIG-RST	O	Digital rest signal output to the CXD2662R and motor driver. L: Reset
48	SENS	I	Internal status (SENSE) input from the CXD2662R.
49	PLAY-SW	I	Detection signal input from the playback position detection switch. L: PLAY
50	XLATCH	O	Latch signal output to the serial bus.
51	OUT-SW	I	Detection signal input from the loading out detection switch.
52	RDY	I	Fixed at H. (Pull-up)
53	ALE/RAS	O	Microprocessor mode output. (Not used.)
54	HOLD	I	Fixed at H. (Pull-up)

Pin No.	Pin Name	I/O	Function
55	HLDA/ALE	O	Microprocessor mode output. (Not used.)
56	MNT2 (XBUSY)	I	In the state of executive command from the CXD2662R
57	VSS	—	Ground.
58	(MINT1) SHCK	I	Track jump signal input from the CXD2662R
59	VCC	—	Power supply. (+3.3V)
60	EEP-WP	O	EEP-ROM write protect signal output. L: write possibility
61	SDA	I/O	Data signal input/output pin with the EEP-ROM.
62	BUS CLK	O	Not used.
63	OE	O	Read signal output.
64	BHE CASH	O	Not used.
65	WE R/W	O	Write signal output.
66	SCL	O	Clock signal output to the EEP-ROM.
67	REFLECT-SW	I	Disk reflection rate detection input from the reflect detection switch. H: Disk with low reflection rate
68	PROTECT-SW	I	Recording-protection claw detection input from the protection detection switch. H: Protect
69	CS0	O	Chip select signal output to the Flash ROM.
70	CS1	O	Not used.
71	CS2	O	Not used.
72	A20	O	Not used.
73	A19	O	Address bus signal output to Flash ROM.
74	VCC	—	Power supply. (+3.3V)
75	A18	O	Address bus signal output to Flash ROM.
76	VSS	—	Ground
77 to 85	A17 to A9	O	Address bus signal output to Flash ROM.
86 to 89	MODEL SEL 1 to 4	O	Not used.
90	WP	O	Write protect signal to the Flash ROM.
91	VCC	—	Power supply. (+3.3V)
92	A8	O	Address bus signal output to Flash ROM.
93	VCC	—	Power supply. (+3.3V)
94 to 101	A7 to A0 LB	O	Address bus signal output to Flash ROM.
102 to 113	D15 to D4	I/O	Data bus signal input/output to the Flash ROM.
114	K.B-CLK-CTRL	O	Keyboard clock ON/OFF signal output. L: OFF H: ON
115	IIC BUSY	O	IIC cable connect check. L: Active
116	K.B-DATA	O	Keyboard data output.
117, 118	REC-VOL B, A	O	Not used.
119 to 122	D3 to D0	I/O	Data bus signal input/output to the Flash ROM.
123, 124	JOG1, JOG0	I	Jog dial pulse input from the rotary encoder.
125	LATCH(DA)	O	Not used.
126	REC	O	Mute signal output when Beep Rec.
127	NC	O	Not used.
128	CS(FL)	O	Chip select signal output to the display driver.
129	POWER(IIC)	O	Media commucator start-up check.
130	VSS	—	Ground.
131	STB	O	Strobe signal output to the power supply circuit. H: Power supply ON: L: standby
132	VCC	—	Power supply. (+3.3V)
133	IOP	I	Optical Pick-up voltage (current) detect signal input.
134	(A/D-6)	I	Model discrimination.
135	(A/D-5)	I	Model discrimination.
136	TIMER/BEEP SW	I	Timer mode select signal input.
137 to 139	KEY 3 to KEY 1	I	Key input pin (A/D input)
140	AVSS	—	Ground. (Analog)
141	KEY0	I	A/D reference voltage.
142	VREF	—	Power supply. (+3.3V)
143	AVCC	—	Power supply. (+3.3V)
144	NC	I	Not used.

SECTION 7 EXPLODED VIEWS

NOTE:

- XX, -X mean standardized parts, so they may have some differences from the original one.
- Items marked "*" are not stocked since they are seldom required for routine service. Some delay should be anticipated when ordering these items.
- The mechanical parts with no reference number in the exploded views are not supplied.
- Hardware (# mark) list and accessories and packing materials are given in the last of this parts list.

- Color Indication of Appearance Parts Example:
KNOB, BALANCE (WHITE)

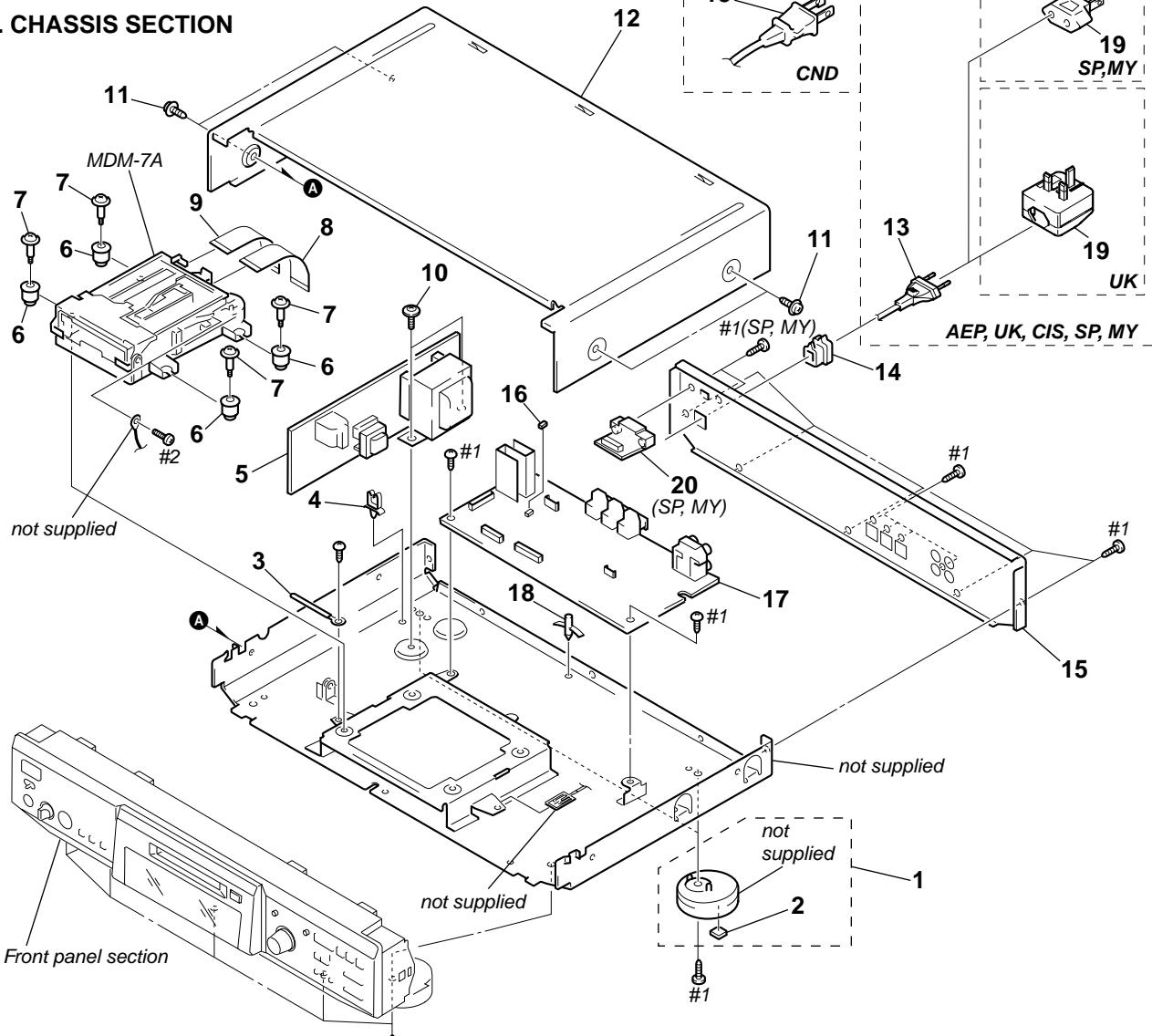
↑
Parts color

- Abbreviation
CND : Canadian model
SP : Singapore model
MY : Malaysia model

The components identified by mark \triangle or dotted line with mark \triangle are critical for safety. Replace only with part number specified.

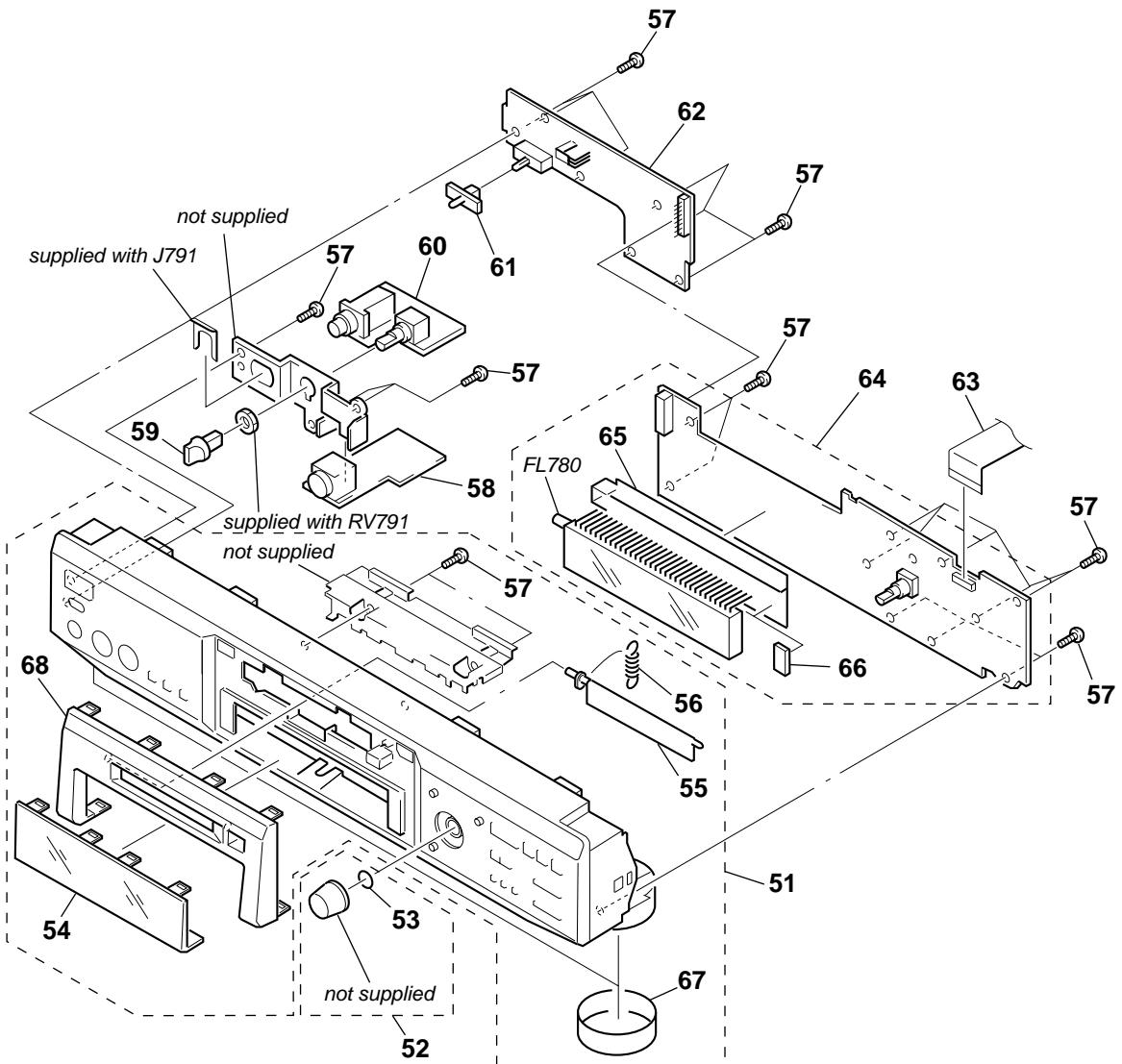
Les composants identifiés par une marque \triangle sont critiques pour la sécurité.
Ne les remplacer que par une pièce portant le numéro spécifié.

7-1. CHASSIS SECTION



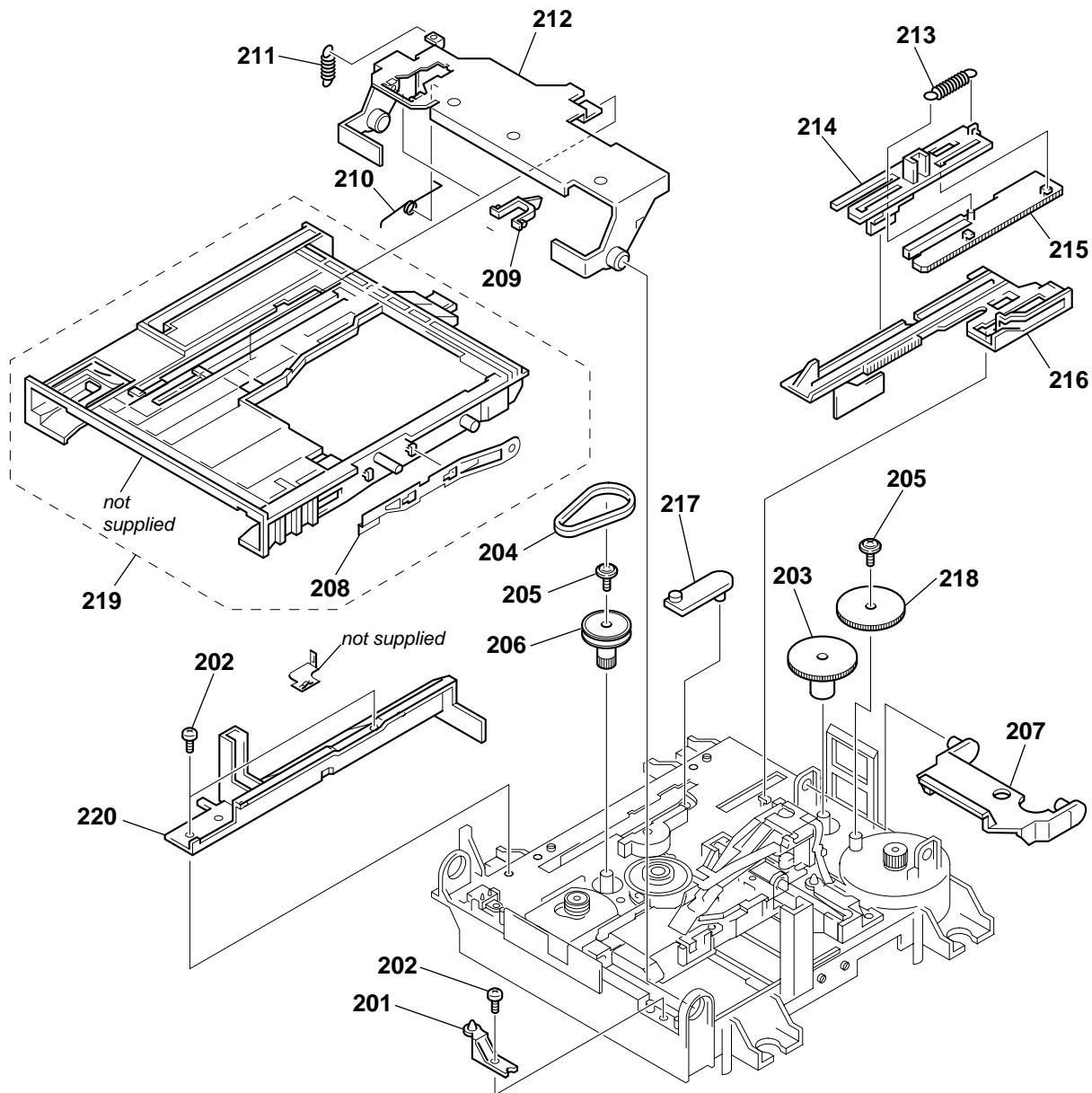
Ref. No.	Part No.	Description	Remarks	Ref. No.	Part No.	Description	Remarks
1	X-4947-390-3	FOOT ASSY (F50150S) (BLACK)		△13	1-777-071-61	CORD, POWER (AEP,UK,CIS,SP,MY)	
1	X-4952-299-1	FOOT ASSY (F50150S) (SILVER)		△13	1-783-531-31	CORD, POWER (CND)	
2	4-983-762-02	CUSHION		14	4-966-267-12	BUSHING (FBS001), CORD	
* 3	3-703-150-11	CLAMP		15	4-228-638-01	PANEL, BACK (AEP,UK,CIS)	
* 4	3-644-407-00	CLIP, AC WIRE E		15	4-228-638-31	PANEL, BACK (CND)	
5	1-677-820-11	PT BOARD		15	4-228-638-41	PANEL, BACK (SP,MY)	
6	4-228-689-01	INSULATOR		16	1-569-972-21	SOCKET, SHORT 2P	
7	4-228-643-01	SCREW (+BVTWH M3), STEP		17	A-4725-416-A	MAIN BOARD, COMPLETE (CND)	
8	1-792-812-11	WIRE (FLAT TYPE) (27 CORE)		17	A-4725-422-A	MAIN BOARD, COMPLETE (AEP,UK,CIS)	
9	1-792-811-11	WIRE (FLAT TYPE) (23 CORE)		17	A-4725-429-A	MAIN BOARD, COMPLETE (SP,MY)	
10	4-221-887-01	SCREW, +PTTWH (M3) (S) TITE		18	3-531-576-41	RIVET (DIA. 3), NYLON	
11	4-210-291-01	SCREW (CASE 3 TP2) (BLACK)		△19	1-569-008-21	ADAPTOR, CONVERSION 2P (SP,MY)	
11	4-210-291-11	SCREW (CASE 3 TP2) (SILVER)		△19	1-770-019-11	ADAPTOR, CONVERSION PLUG 3P (UK)	
12	4-983-661-01	UPPER CASE (408226) (BLACK)		20	1-677-823-11	VOL-SEL BOARD (SP,MY)	
12	4-983-661-41	UPPER CASE (408226) (SILVER)					

7-2. FRONT PANEL SECTION



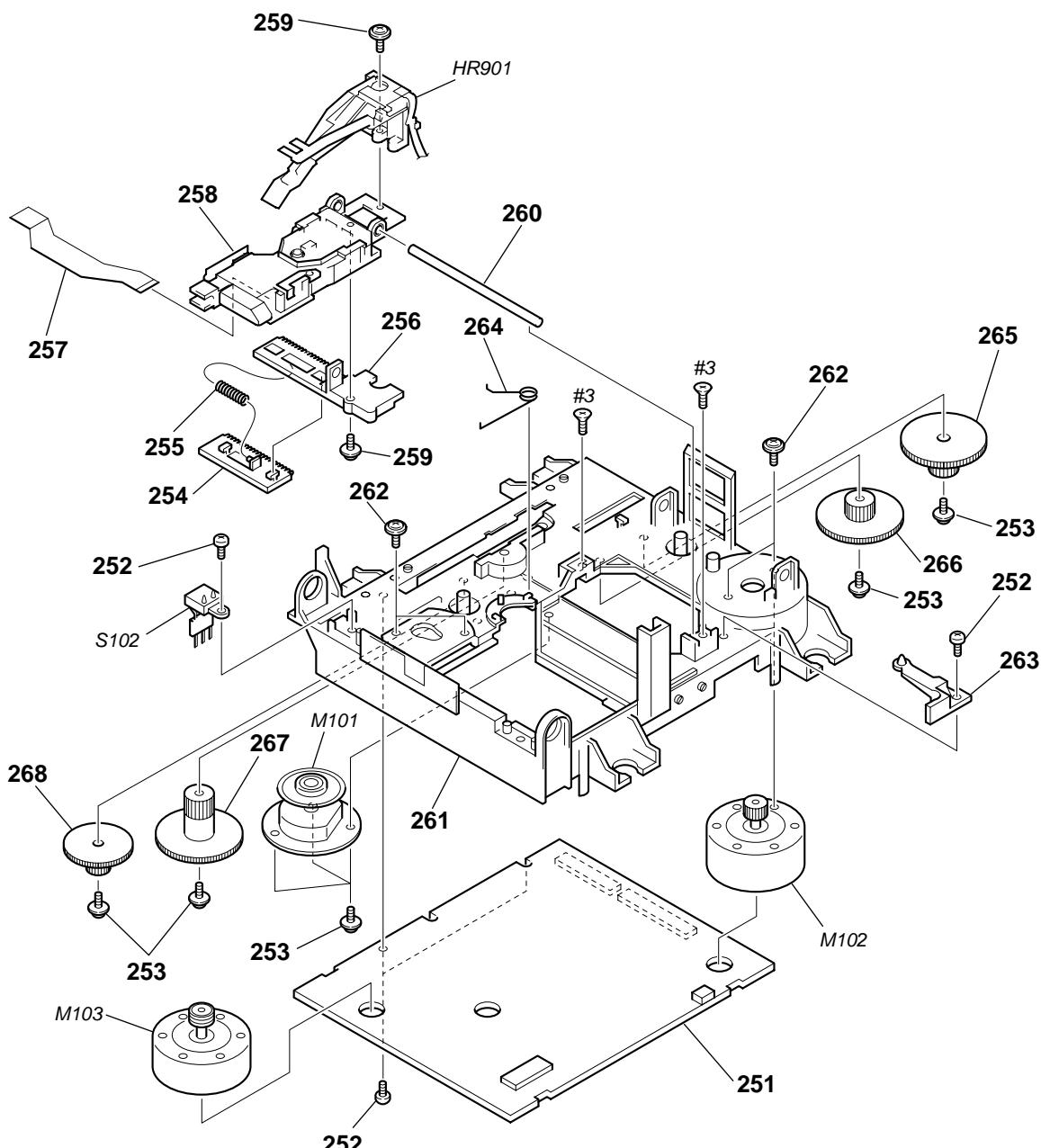
<u>Ref. No.</u>	<u>Part No.</u>	<u>Description</u>	<u>Remarks</u>	<u>Ref. No.</u>	<u>Part No.</u>	<u>Description</u>	<u>Remarks</u>
51	X-4952-917-1	PANEL ASSY, FRONT (BLACK) (AEP,UK,CIS,SP,MY)		60	1-677-821-11	HP BOARD	
51	X-4952-918-1	PANEL ASSY, FRONT (SILVER)		61	3-917-216-11	KNOB (TIMER) (BLACK)	
51	X-4952-920-1	PANEL ASSY, FRONT (BLACK) (CND)		61	3-917-216-71	KNOB (TIMER) (SILVER)	
52	A-4672-928-A	KNOB (AMS) ASSY (BLACK)		62	1-677-819-11	KEY-SW BOARD	
52	A-4672-929-A	KNOB (AMS) ASSY (SILVER)		63	1-792-814-11	WIRE (FLAT TYPE) (17 CORE)	
53	3-354-981-11	SPRING (SUS), RING		64	A-4725-412-A	DISPLAY BOARD, COMPLETE (CND)	
54	4-228-622-01	WINDOW (FL)		64	A-4725-418-A	DISPLAY BOARD, COMPLETE (AEP,UK,CIS)	
55	4-228-629-01	LID(MD) (BLACK)		64	A-4725-424-A	DISPLAY BOARD, COMPLETE (SP,MY)	
55	4-228-629-21	LID(MD) (SILVER)		* 65	4-996-686-11	HOLDER (FL)	
56	4-228-630-01	SPRING (LID), TENSION COIL		* 66	4-949-935-51	CUSHION (FL)	
57	4-951-620-01	SCREW (2.6X8), +BVTP		67	4-977-593-11	RING(DIA. 50), ORNAMENTAL (AEP,UK,CIS,SP,MY)	
58	1-677-822-11	KB BOARD		68	X-4952-923-1	ESCUOTCHEON (MD) ASSY (BLACK)	
59	4-950-189-01	KNOB (A) (VOL) (BLACK)		68	X-4952-925-1	ESCUOTCHEON (MD) ASSY (SILVER)	
59	4-950-189-71	KNOB (A) (VOL) (SILVER)		FL780	1-517-987-11	INDICATOR TUBE, FLUORESCENT	

7-3. MECHANISM SECTION-1 (MDM-7A)



<u>Ref. No.</u>	<u>Part No.</u>	<u>Description</u>	<u>Remarks</u>	<u>Ref. No.</u>	<u>Part No.</u>	<u>Description</u>	<u>Remarks</u>
* 201	4-996-267-01	BASE (BU-D)		211	4-227-012-01	SPRING (HOLDER), TENSION	
202	4-908-618-21	SCREW (+BTP) (2X6)		212	4-227-019-01	PLATE (HOLDER), RETAINER	
203	4-227-007-01	GEAR (SB)		213	4-227-013-01	SPRING (EJ), TENSION	
204	4-227-025-01	BELT (LOADING)		214	4-226-995-01	SLIDER (EJ)	
205	3-372-761-01	SCREW (M1.7), TAPPING		215	4-226-996-01	LIMITTER (EJ)	
206	4-227-002-01	GEAR, PULLEY		216	4-226-997-01	SLIDER	
207	4-226-999-01	LEVER (HEAD)		217	4-226-998-01	LEVER (CHG)	
208	X-4952-665-1	SPRING (SHT) ASSY, LEAF		218	4-227-006-01	GEAR (SA)	
209	4-228-923-01	LOCK (HOLDER)		219	A-4672-973-D	HOLDER ASSY	
210	4-229-533-01	SPRING (STOPPER), TORSION		220	4-226-994-01	GUIDE (L)	

**7-4. MECHANISM SECTION-2
(MDM-7A)**



The components identified by mark \triangle or dotted line with mark \triangle are critical for safety.
Replace only with part number specified.

Les composants identifiés par une marque \triangle sont critiques pour la sécurité.
Ne les remplacer que par une pièce portant le numéro spécifié.

Ref. No.	Part No.	Description	Remarks	Ref. No.	Part No.	Description	Remarks
251	A-4725-054-A	BD BOARD,COMPLETE		263	4-226-990-01	BASE (BU-A)	
252	4-908-618-21	SCREW (+BTP) (2X6)		264	4-227-023-01	SPRING (SPINDLE), TORSION	
253	3-372-761-01	SCREW (M1.7), TAPPING		265	4-227-004-01	GEAR (LC)	
254	4-226-993-01	RACK		266	4-227-005-01	GEAR (LD)	
255	4-227-014-01	SPRING (RACK), COMPRESSION		267	4-227-009-01	GEAR (SD)	
256	4-226-992-01	BASE, SL		268	4-227-008-01	GEAR (SC)	
257	1-678-514-11	FLEXIBLE BOARD		HR901	1-500-670-11	HEAD, OVER LIGHT	
\triangle 258	A-4672-541-A	OPTICAL PICK-UP KMS-260B/J1N		M101	A-4672-898-A	MOTOR ASSY, SPINDLE	
259	4-988-560-01	SCREW (+P 1.7X6)		M102	A-4672-900-A	MOTOR ASSY, SLED	
260	4-996-265-01	SHAFT, MAIN		M103	A-4672-975-A	MOTOR ASSY, LOADING	
261	4-226-989-01	CHASSIS		S102	1-771-957-11	SWITCH, PUSH (2 KEY) (REFLECT/PROTECT SW)	
262	4-211-036-01	SCREW (1.7X2.5), +PWH					

SECTION 8

ELECTRICAL PARTS LIST

NOTE:

- Due to standardization, replacements in the parts list may be different from the parts specified in the diagrams or the components used on the set.
- -XX, -X mean standardized parts, so they may have some difference from the original one.
- Items marked “*” are not stocked since they are seldom required for routine service. Some delay should be anticipated when ordering these items.
- CAPACITORS:
uF: μ F
- RESISTORS

All resistors are in ohms.

METAL: metal-film resistor

METAL OXIDE: Metal Oxide-film resistor

F: nonflammable

<ul style="list-style-type: none"> • COILS uH: μH • SEMICONDUCTORS In each case, u: μ, for example: uA...: μA..., uPA..., μPA..., uPB..., μPB..., uPC..., μPC..., uPD..., μPD... • Abbreviation CND : Canadian model SP : Singapore model MY : Malaysia model 	<p>When indicating parts by reference number, please include the board name.</p> <p>The components identified by mark \triangle or dotted line with mark \triangle are critical for safety. Replace only with part number specified.</p> <p>Les composants identifiés par une marque \triangle sont critiques pour la sécurité. Ne les remplacer que par une pièce portant le numéro spécifié.</p>
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Ref. No.	Part No.	Description			Remarks	Ref. No.	Part No.	Description			Remarks
	A-4725-054-A	BD BOARD, COMPLETE				C158	1-162-927-11	CERAMIC CHIP	100PF	5%	50V
		*****				C159	1-162-927-11	CERAMIC CHIP	100PF	5%	50V
		< CAPACITOR >				C160	1-162-927-11	CERAMIC CHIP	100PF	5%	50V
C101	1-135-259-11	TANTAL. CHIP	10uF	20%	6.3V	C161	1-162-970-11	CERAMIC CHIP	0.01uF	10%	25V
C102	1-135-259-11	TANTAL. CHIP	10uF	20%	6.3V	C162	1-162-970-11	CERAMIC CHIP	0.01uF	10%	25V
C103	1-162-970-11	CERAMIC CHIP	0.01uF	10%	25V	C163	1-125-891-11	CERAMIC CHIP	0.47uF	10%	10V
C104	1-164-227-11	CERAMIC CHIP	0.022uF	10%	25V	C164	1-162-927-11	CERAMIC CHIP	100PF	5%	50V
C105	1-115-416-11	CERAMIC CHIP	1000PF	5%	25V	C165	1-162-968-11	CERAMIC CHIP	0.0047uF	10%	50V
C106	1-162-970-11	CERAMIC CHIP	0.01uF	10%	25V	C166	1-125-891-11	CERAMIC CHIP	0.47uF	10%	10V
C107	1-162-970-11	CERAMIC CHIP	0.01uF	10%	25V	C167	1-164-245-11	CERAMIC CHIP	0.015uF	10%	25V
C108	1-162-969-11	CERAMIC CHIP	0.0068uF	10%	25V	C169	1-164-156-11	CERAMIC CHIP	0.1uF		25V
C109	1-164-677-11	CERAMIC CHIP	0.033uF	10%	16V	C171	1-164-156-11	CERAMIC CHIP	0.1uF		25V
C110	1-163-038-91	CERAMIC CHIP	0.1uF		25V	C172	1-164-156-11	CERAMIC CHIP	0.1uF		25V
C111	1-117-720-11	CERAMIC CHIP	4.7uF		10V	C180	1-117-370-11	CERAMIC CHIP	10uF		10V
C112	1-110-563-11	CERAMIC CHIP	0.068uF	10%	16V	C181	1-126-206-11	ELECT CHIP	100uF	20%	6.3V
C113	1-162-968-11	CERAMIC CHIP	0.0047uF	10%	50V	C182	1-163-038-91	CERAMIC CHIP	0.1uF		25V
C114	1-125-837-91	CERAMIC CHIP	1uF	10%	6.3V	C183	1-164-156-11	CERAMIC CHIP	0.1uF		25V
C115	1-162-966-11	CERAMIC CHIP	0.0022uF	10%	50V	C184	1-117-970-11	ELECT CHIP	22uF	20%	10V
C116	1-164-227-11	CERAMIC CHIP	0.022uF	10%	25V	C185	1-131-872-91	CERAMIC CHIP	1000PF	10%	630V
C117	1-162-970-11	CERAMIC CHIP	0.01uF	10%	25V	C191	1-126-206-11	ELECT CHIP	100uF	20%	6.3V
C118	1-165-176-11	CERAMIC CHIP	0.047uF	10%	16V	C192	1-164-156-11	CERAMIC CHIP	0.1uF		25V
C119	1-165-176-11	CERAMIC CHIP	0.047uF	10%	16V	C193	1-126-206-11	ELECT CHIP	100uF	20%	6.3V
C120	1-164-156-11	CERAMIC CHIP	0.1uF		25V	C194	1-164-156-11	CERAMIC CHIP	0.1uF		25V
C121	1-164-156-11	CERAMIC CHIP	0.1uF		25V	C195	1-164-156-11	CERAMIC CHIP	0.1uF		25V
C125	1-117-720-11	CERAMIC CHIP	4.7uF		10V	C196	1-164-156-11	CERAMIC CHIP	0.1uF		25V
C128	1-164-156-11	CERAMIC CHIP	0.1uF		25V	C1401	1-117-720-11	CERAMIC CHIP	4.7uF		10V
C131	1-117-720-11	CERAMIC CHIP	4.7uF		10V	< CONNECTOR >					
C132	1-164-156-11	CERAMIC CHIP	0.1uF		25V	CN101	1-766-833-21	CONNECTOR, FFC/FPC (ZIF) 21P			
C133	1-164-156-11	CERAMIC CHIP	0.1uF		25V	CN102	1-784-835-21	CONNECTOR, FFC (LIF(NON-ZIF)) 27P			
C141	1-126-206-11	ELECT CHIP	100uF	20%	6.3V	CN103	1-784-834-21	CONNECTOR, FFC (LIF(NON-ZIF)) 23P			
C142	1-164-156-11	CERAMIC CHIP	0.1uF		25V	* CN104	1-580-055-21	PIN, CONNECTOR (SMD) 2P			
C143	1-164-156-11	CERAMIC CHIP	0.1uF		25V	CN105	1-784-859-21	CONNECTOR, FFC (LIF(NON-ZIF)) 7P			
C144	1-162-970-11	CERAMIC CHIP	0.01uF	10%	25V	< DIODE >					
C145	1-164-156-11	CERAMIC CHIP	0.1uF		25V	D101	8-719-988-61	DIODE 1SS355TE-17			
C146	1-117-720-11	CERAMIC CHIP	4.7uF		10V	D181	8-719-080-81	DIODE FS1J6			
C147	1-117-720-11	CERAMIC CHIP	4.7uF		10V	D183	8-719-080-81	DIODE FS1J6			
C151	1-117-370-11	CERAMIC CHIP	10uF		10V	< IC >					
C152	1-164-156-11	CERAMIC CHIP	0.1uF		25V	IC101	8-752-080-95	IC CXA2523AR			
C153	1-164-156-11	CERAMIC CHIP	0.1uF		25V	IC102	8-759-473-51	IC TLV2361CDBV			
C154	1-126-206-11	ELECT CHIP	100uF	20%	6.3V	IC141	8-759-430-25	IC BH6511FS			
C155	1-164-156-11	CERAMIC CHIP	0.1uF		25V	IC151	8-752-404-64	IC CXD2662R			
C156	1-164-156-11	CERAMIC CHIP	0.1uF		25V						
C157	1-164-156-11	CERAMIC CHIP	0.1uF		25V						

Ref. No.	Part No.	Description			Remarks	Ref. No.	Part No.	Description			Remarks
IC153	8-759-671-27	IC MSM51V4400E-70TS-K				R111	1-216-833-91	RES-CHIP	10K	5%	1/16W
IC171	8-759-096-87	IC TC7WU04FU(TE12R)				R112	1-216-829-11	METAL CHIP	4.7K	5%	1/16W
IC181	8-759-481-17	IC MC74ACT08DTR2				R113	1-216-833-91	RES-CHIP	10K	5%	1/16W
IC190	8-759-460-72	IC BA033FP-E2				R114	1-216-827-11	METAL CHIP	3.3K	5%	1/16W
IC195	8-759-640-41	IC BR24C08F-E2				R115	1-216-833-91	RES-CHIP	10K	5%	1/16W
< JUMPER RESISTOR >						R116	1-216-839-11	METAL CHIP	33K	5%	1/16W
JW201	1-216-295-91	SHORT	0			R117	1-216-837-11	METAL CHIP	22K	5%	1/16W
JW202	1-216-295-91	SHORT	0			R118	1-218-855-11	METAL CHIP	2.2K	0.5%	1/16W
JW203	1-216-295-91	SHORT	0			R119	1-218-863-11	METAL CHIP	4.7K	0.5%	1/16W
JW903	1-216-295-91	SHORT	0			R120	1-218-889-11	METAL CHIP	56K	0.5%	1/16W
JW904	1-216-295-91	SHORT	0			R121	1-218-863-11	METAL CHIP	4.7K	0.5%	1/16W
< COIL >						R122	1-218-855-11	METAL CHIP	2.2K	0.5%	1/16W
L101	1-500-245-11	INDUCTOR CHIP	0uH			R123	1-216-819-11	METAL CHIP	680	5%	1/16W
L102	1-500-245-11	INDUCTOR CHIP	0uH			R124	1-216-809-11	METAL CHIP	100	5%	1/16W
L103	1-500-245-11	INDUCTOR CHIP	0uH			R125	1-216-815-11	METAL CHIP	330	5%	1/16W
L105	1-414-235-22	INDUCTOR CHIP	0uH			R126	1-216-819-11	METAL CHIP	680	5%	1/16W
L106	1-500-245-11	INDUCTOR CHIP	0uH			R127	1-216-845-11	METAL CHIP	100K	5%	1/16W
L121	1-500-245-11	INDUCTOR CHIP	0uH			R128	1-219-724-11	METAL CHIP	1	1%	1/4W
L122	1-500-245-11	INDUCTOR CHIP	0uH			R129	1-216-298-00	METAL CHIP	2.2	5%	1/10W
L131	1-500-245-11	INDUCTOR CHIP	0uH			R130	1-216-829-11	METAL CHIP	4.7K	5%	1/16W
L141	1-412-029-11	INDUCTOR CHIP	10uH			R131	1-216-833-91	RES-CHIP	10K	5%	1/16W
L142	1-412-032-11	INDUCTOR CHIP	100uH			R132	1-216-841-11	METAL CHIP	47K	5%	1/16W
L143	1-412-029-11	INDUCTOR CHIP	10uH			R133	1-216-821-11	METAL CHIP	1K	5%	1/16W
L144	1-412-032-11	INDUCTOR CHIP	100uH			R134	1-216-821-11	METAL CHIP	1K	5%	1/16W
L145	1-412-032-11	INDUCTOR CHIP	100uH			R135	1-216-821-11	METAL CHIP	1K	5%	1/16W
L146	1-469-855-21	FERRITE	0uH			R136	1-216-295-91	SHORT	0		
L147	1-469-855-21	FERRITE	0uH			R138	1-216-833-91	RES-CHIP	10K	5%	1/16W
L161	1-500-245-11	INDUCTOR CHIP	0uH			R150	1-216-833-91	RES-CHIP	10K	5%	1/16W
L171	1-500-245-11	INDUCTOR CHIP	0uH			R151	1-216-833-91	RES-CHIP	10K	5%	1/16W
L180	1-469-855-21	FERRITE	0uH			R154	1-216-833-91	RES-CHIP	10K	5%	1/16W
L181	1-469-855-21	FERRITE	0uH			R155	1-216-864-11	METAL CHIP	0	5%	1/16W
L182	1-500-245-11	INDUCTOR CHIP	0uH			R156	1-216-864-11	METAL CHIP	0	5%	1/16W
L183	1-216-296-91	SHORT	0			R157	1-216-809-11	METAL CHIP	100	5%	1/16W
L184	1-216-296-91	SHORT	0			R158	1-216-809-11	METAL CHIP	100	5%	1/16W
< TRANSISTOR >						R159	1-216-833-91	RES-CHIP	10K	5%	1/16W
Q101	8-729-403-35	TRANSISTOR UN5113-TX				R160	1-216-833-91	RES-CHIP	10K	5%	1/16W
Q121	8-729-403-35	TRANSISTOR UN5113-TX				R161	1-216-833-91	RES-CHIP	10K	5%	1/16W
Q122	8-729-101-07	TRANSISTOR 2SB798-T1DK				R163	1-216-809-11	METAL CHIP	100	5%	1/16W
Q131	8-729-026-53	TRANSISTOR 2SA1576A-T106-QR				R164	1-216-809-11	METAL CHIP	100	5%	1/16W
Q132	8-729-903-10	TRANSISTOR FMW1-T-148				R165	1-216-809-11	METAL CHIP	100	5%	1/16W
Q133	8-729-402-93	TRANSISTOR UN5214-TX				R167	1-216-833-91	RES-CHIP	10K	5%	1/16W
Q134	8-729-402-93	TRANSISTOR UN5214-TX				R168	1-216-845-11	METAL CHIP	100K	5%	1/16W
Q181	8-729-018-75	TRANSISTOR 2SJ278MYTR				R169	1-216-855-11	METAL CHIP	680K	5%	1/16W
Q182	8-729-017-65	TRANSISTOR 2SK1764KYTR				R170	1-216-827-11	METAL CHIP	3.3K	5%	1/16W
< RESISTOR >						R171	1-216-821-11	METAL CHIP	1K	5%	1/16W
R101	1-216-829-11	METAL CHIP	4.7K	5%	1/16W	R173	1-216-821-11	METAL CHIP	1K	5%	1/16W
R102	1-216-853-11	METAL CHIP	470K	5%	1/16W	R174	1-216-811-11	METAL CHIP	150	5%	1/16W
R103	1-216-863-11	RES-CHIP	3.3M	5%	1/16W	R175	1-216-857-11	METAL CHIP	1M	5%	1/16W
R104	1-216-853-11	METAL CHIP	470K	5%	1/16W	R176	1-216-809-11	METAL CHIP	100	5%	1/16W
R105	1-216-825-11	METAL CHIP	2.2K	5%	1/16W	R179	1-216-295-91	SHORT	0		
R106	1-216-825-11	METAL CHIP	2.2K	5%	1/16W	R181	1-216-841-11	METAL CHIP	47K	5%	1/16W
R107	1-216-825-11	METAL CHIP	2.2K	5%	1/16W	R182	1-216-841-11	METAL CHIP	47K	5%	1/16W
R108	1-216-833-91	RES-CHIP	10K	5%	1/16W	R183	1-216-841-11	METAL CHIP	47K	5%	1/16W
R109	1-216-845-11	METAL CHIP	100K	5%	1/16W	R184	1-220-942-11	METAL CHIP	3.3	1%	1/4W
R110	1-216-845-11	METAL CHIP	100K	5%	1/16W	R185	1-220-942-11	METAL CHIP	3.3	1%	1/4W
						R195	1-216-833-91	RES-CHIP	10K	5%	1/16W
						R196	1-216-833-91	RES-CHIP	10K	5%	1/16W
						R197	1-216-833-91	RES-CHIP	10K	5%	1/16W
						R218	1-216-864-11	METAL CHIP	0	5%	1/16W

BD

DISPLAY

HP

Ref. No.	Part No.	Description	Remarks		Ref. No.	Part No.	Description	Remarks		
< SWITCH >										
S101	1-762-596-21	SWITCH, PUSH (1 KEY) (LIMIT SW)	R713	1-247-843-11	CARBON	3.3K	5%	1/4W		
S103	1-771-956-21	SWITCH, PUSH (1 KEY) (OUT SW)	R714	1-249-425-11	CARBON	4.7K	5%	1/4W	F	
S104	1-771-955-21	SWITCH, PUSH (1 KEY) (PLAY SW)	R715	1-249-429-11	CARBON	10K	5%	1/4W		
S105	1-771-955-21	SWITCH, PUSH (1 KEY) (REC SW)	R716	1-249-435-11	CARBON	33K	5%	1/4W		

A-4725-412-A			R722	1-249-421-11	CARBON	2.2K	5%	1/4W	F	
DISPLAY BOARD, COMPLETE (CND)										

A-4725-418-A			R723	1-247-843-11	CARBON	3.3K	5%	1/4W		
DISPLAY BOARD, COMPLETE (AEP,UK,CIS)										

A-4725-424-A			R724	1-249-425-11	CARBON	4.7K	5%	1/4W	F	
DISPLAY BOARD, COMPLETE (SP,MY)			R761	1-247-807-31	CARBON	100	5%	1/4W		
*****			R762	1-247-807-31	CARBON	100	5%	1/4W		
*****			R763	1-249-441-11	CARBON	100K	5%	1/4W		
*			R764	1-249-441-11	CARBON	100K	5%	1/4W		
*			R766	1-247-843-11	CARBON	3.3K	5%	1/4W		
*			R767	1-247-807-31	CARBON	100	5%	1/4W		
*			R768	1-247-807-31	CARBON	100	5%	1/4W		
*			R769	1-247-807-31	CARBON	100	5%	1/4W		
*			R770	1-247-807-31	CARBON	100	5%	1/4W		
*			R775	1-249-399-11	CARBON	33	5%	1/4W	F	
< CAPACITOR >										
< SWITCH >										
C700	1-126-153-11	ELECT	22uF	20%	6.3V	S701	1-762-875-21	SWITCH, KEYBOARD (REC ●)		
C709	1-164-159-11	CERAMIC	0.1uF		50V	S702	1-762-875-21	SWITCH, KEYBOARD (■)		
C719	1-164-159-11	CERAMIC	0.1uF		50V	S703	1-762-875-21	SWITCH, KEYBOARD (▶)		
C760	1-126-153-11	ELECT	22uF	20%	6.3V	S704	1-762-875-21	SWITCH, KEYBOARD (◀)		
C761	1-162-294-31	CERAMIC	0.001uF	10%	50V	S705	1-762-875-21	SWITCH, KEYBOARD (II)		
C762	1-162-294-31	CERAMIC	0.001uF	10%	50V	S706	1-762-875-21	SWITCH, KEYBOARD (▷)		
C766	1-162-213-31	CERAMIC	39PF	5%	50V	S711	1-762-875-21	SWITCH, KEYBOARD (MENU/NO)		
C767	1-162-306-11	CERAMIC	0.01uF	30%	16V	S712	1-762-875-21	SWITCH, KEYBOARD (YES)		
C768	1-162-294-31	CERAMIC	0.001uF	10%	50V	S713	1-475-235-21	ENCODER, ROTARY (I<<< AMS >>>I)		
C769	1-162-294-31	CERAMIC	0.001uF	10%	50V	S714	1-762-875-21	SWITCH, KEYBOARD (CLEAR)		
C770	1-162-294-31	CERAMIC	0.001uF	10%	50V	S715	1-762-875-21	SWITCH, KEYBOARD (INPUT)		
C771	1-162-306-11	CERAMIC	0.01uF	30%	16V	S716	1-762-875-21	SWITCH, KEYBOARD (REC MODE)		
C780	1-124-261-00	ELECT	10uF	20%	50V	S721	1-762-875-21	SWITCH, KEYBOARD (EJECT ▲)		
C783	1-124-261-00	ELECT	10uF	20%	50V	S722	1-762-875-21	SWITCH, KEYBOARD (PLAY MODE)		
< CONNECTOR >										
CN701	1-779-554-21	CONNECTOR, FFC (LIF(NON-ZIF)) 17P	S723	1-762-875-21	SWITCH, KEYBOARD (REPEAT)					
CN702	1-778-716-11	HOUSING, CONNECTOR 9P	S724	1-762-875-21	SWITCH, KEYBOARD (LEVEL/DISPLAY/CHAR)					

< LED >										
D775	8-719-046-39	LED SEL5821A-TP15 (MDLP)	1-677-821-11 HP BOARD					*****		
< FLUORESCENT INDICATOR TUBE >										
FL780	1-517-987-11	INDICATOR TUBE, FLUORESCENT	< CAPACITOR >					*****		
< IC >										
IC760	8-759-680-17	IC MSM9201-04GS-K	C791	1-162-282-31	CERAMIC	100PF	10%	50V		
< TRANSISTOR >			C792	1-162-282-31	CERAMIC	100PF	10%	50V		
< RESISTOR >			< JACK >					*****		
Q761	8-729-620-05	TRANSISTOR 2SC2603TP-EF	J791	1-770-306-11	JACK (LARGE TYPE) (PHONES)					
Q762	8-729-620-05	TRANSISTOR 2SC2603TP-EF	< RESISTOR >					*****		
Q775	8-729-900-80	TRANSISTOR UN4211-TA	R791	1-249-393-11	CARBON	10	5%	1/4W	F	
< VARIABLE RESISTOR >			R792	1-249-393-11	CARBON	10	5%	1/4W	F	
RV791 1-225-590-11 RES, VAR, CARBON 20K/20K (LEVEL)										

R702	1-249-421-11	CARBON	2.2K	5%	1/4W	F				
R703	1-247-843-11	CARBON	3.3K	5%	1/4W					
R704	1-249-425-11	CARBON	4.7K	5%	1/4W	F				
R705	1-249-429-11	CARBON	10K	5%	1/4W					
R706	1-249-435-11	CARBON	33K	5%	1/4W					
R712	1-249-421-11	CARBON	2.2K	5%	1/4W	F				

MAIN

Ref. No.	Part No.	Description		Remarks	Ref. No.	Part No.	Description		Remarks	
C351	1-126-933-11	ELECT	100uF	20%	16V	C623	1-162-970-11	CERAMIC CHIP	0.01uF	10% 25V (CND,SP,MY)
C356	1-126-933-11	ELECT	100uF	20%	16V	C631	1-164-156-11	CERAMIC CHIP	0.1uF	25V (AEP,UK,CIS)
C357	1-164-156-11	CERAMIC CHIP	0.1uF		25V	C661	1-164-156-11	CERAMIC CHIP	0.1uF	25V
C358	1-164-156-11	CERAMIC CHIP	0.1uF		25V	C662	1-126-963-11	ELECT	4.7uF	20% 50V
C359	1-164-156-11	CERAMIC CHIP	0.1uF		25V	C827	1-164-156-11	CERAMIC CHIP	0.1uF	25V
C360	1-164-156-11	CERAMIC CHIP	0.1uF		25V	C828	1-164-156-11	CERAMIC CHIP	0.1uF	25V
C361	1-126-933-11	ELECT	100uF	20%	16V	C829	1-104-665-11	ELECT	100uF	20% 10V
C366	1-126-933-11	ELECT	100uF	20%	16V	C851	1-164-156-11	CERAMIC CHIP	0.1uF	25V
C391	1-126-933-11	ELECT	100uF	20%	16V	C852	1-164-156-11	CERAMIC CHIP	0.1uF	25V
C396	1-126-933-11	ELECT	100uF	20%	16V	C853	1-164-156-11	CERAMIC CHIP	0.1uF	25V
C400	1-126-936-11	ELECT	3300uF	20%	16V	C854	1-164-156-11	CERAMIC CHIP	0.1uF	25V
C403	1-126-963-11	ELECT	4.7uF	20%	50V	C855	1-164-156-11	CERAMIC CHIP	0.1uF	25V
C404	1-126-934-11	ELECT	220uF	20%	10V	C925	1-164-156-11	CERAMIC CHIP	0.1uF	25V
C405	1-126-916-11	ELECT	1000uF	20%	6.3V	C926	1-164-156-11	CERAMIC CHIP	0.1uF	25V
C406	1-164-156-11	CERAMIC CHIP	0.1uF		25V	C955	1-164-156-11	CERAMIC CHIP	0.1uF	25V
C407	1-164-156-11	CERAMIC CHIP	0.1uF		25V	C956	1-164-156-11	CERAMIC CHIP	0.1uF	25V
C408	1-104-665-11	ELECT	100uF	20%	10V				< CONNECTOR >	
C410	1-162-964-11	CERAMIC CHIP	0.001uF	10%	50V	CN1	1-784-384-11	CONNECTOR, FFC/FPC 27P		
C411	1-164-156-11	CERAMIC CHIP	0.1uF		25V	CN390	1-506-468-11	PIN, CONNECTOR 3P		
C412	1-126-963-11	ELECT	4.7uF	20%	50V	CN400	1-793-991-11	CONNECTOR, FFC/FPC 23P		
C413	1-162-964-11	CERAMIC CHIP	0.001uF	10%	50V	CN420	1-568-683-11	PIN, CONNECTOR (PC BOARD) 2P		
C431	1-104-663-11	ELECT	33uF	20%	25V	CN490	1-794-481-21	CONNECTOR, FFC 17P		
C443	1-162-970-11	CERAMIC CHIP	0.01uF	10%	25V					
C447	1-126-933-11	ELECT	100uF	20%	16V					
C461	1-126-939-11	ELECT	10000uF	20%	16V					
C471	1-126-935-11	ELECT	470uF	20%	16V					
C476	1-126-935-11	ELECT	470uF	20%	16V					
C481	1-165-319-11	CERAMIC CHIP	0.1uF		50V					
C482	1-165-319-11	CERAMIC CHIP	0.1uF		50V					
C483	1-128-576-11	ELECT	100uF	20%	63V					
C484	1-165-319-11	CERAMIC CHIP	0.1uF		50V	D155	8-719-016-74	DIODE 1SS352-TPH3		
C485	1-126-967-11	ELECT	47uF	20%	50V	D156	8-719-016-74	DIODE 1SS352-TPH3		
C490	1-126-965-11	ELECT	22uF	20%	50V	D255	8-719-016-74	DIODE 1SS352-TPH3		
C500	1-126-934-11	ELECT	220uF	20%	10V	D256	8-719-016-74	DIODE 1SS352-TPH3		
C501	1-164-156-11	CERAMIC CHIP	0.1uF		25V	D401	8-719-081-08	DIODE EP05Q04-TE8L3		
C502	1-137-366-11	MYLAR	0.0022uF	5%	50V	D402	8-719-081-08	DIODE EP05Q04-TE8L3		
C503	1-137-366-11	MYLAR	0.0022uF	5%	50V	D403	8-719-081-08	DIODE EP05Q04-TE8L3		
C504	1-104-665-11	ELECT	100uF	20%	10V	D404	8-719-081-08	DIODE EP05Q04-TE8L3		
C505	1-164-156-11	CERAMIC CHIP	0.1uF		25V	D412	8-719-820-05	DIODE 1SS181-TE85L		
C515	1-162-927-11	CERAMIC CHIP	100PF	5%	50V	D421	8-719-016-74	DIODE 1SS352-TPH3		
C516	1-162-927-11	CERAMIC CHIP	100PF	5%	50V	D422	8-719-074-34	DIODE RB495D-T146		
C517	1-162-927-11	CERAMIC CHIP	100PF	5%	50V	D431	8-719-016-74	DIODE 1SS352-TPH3		
C519	1-162-964-11	CERAMIC CHIP	0.001uF	10%	50V	D432	8-719-016-74	DIODE 1SS352-TPH3		
C520	1-126-934-11	ELECT	220uF	20%	10V	D461	8-719-200-82	DIODE 11ES2-TB5		
C522	1-164-156-11	CERAMIC CHIP	0.1uF		25V	D462	8-719-200-82	DIODE 11ES2-TB5		
C523	1-104-665-11	ELECT	100uF	20%	10V	D471	8-719-200-82	DIODE 11ES2-TB5		
C524	1-164-156-11	CERAMIC CHIP	0.1uF		25V	D472	8-719-200-82	DIODE 11ES2-TB5		
C550	1-104-665-11	ELECT	100uF	20%	10V	D476	8-719-200-82	DIODE 11ES2-TB5		
C551	1-164-156-11	CERAMIC CHIP	0.1uF		25V	D477	8-719-200-82	DIODE 11ES2-TB5		
C552	1-162-912-11	CERAMIC CHIP	7PF	0.5PF	50V	D481	8-719-200-82	DIODE 11ES2-TB5		
C553	1-162-912-11	CERAMIC CHIP	7PF	0.5PF	50V	D482	8-719-422-23	DIODE MA8047-TX		
C554	1-164-156-11	CERAMIC CHIP	0.1uF		25V	D851	8-719-016-74	DIODE 1SS352-TPH3		
C601	1-164-156-11	CERAMIC CHIP	0.1uF		25V				< IC >	
C611	1-164-156-11	CERAMIC CHIP	0.1uF		25V	IC1	8-759-677-81	IC M30805SGP		
C612	1-126-963-11	ELECT	4.7uF	20%	50V	IC2	8-759-685-93	IC MT28F800B3WG-10T-640		
C613	1-162-970-11	CERAMIC CHIP	0.01uF	10%	25V	IC2	8-759-688-24	IC MT28F800B3WG-10T		
C621	1-164-156-11	CERAMIC CHIP	0.1uF		25V (CND,SP,MY)	IC160	8-759-636-55	IC M5218AFP-T1		
C622	1-126-963-11	ELECT	4.7uF	20%	50V (CND,SP,MY)	IC260	8-759-636-55	IC M5218AFP-T1		
						IC350	8-759-636-55	IC M5218AFP-T1		

Ref. No.	Part No.	Description		Remarks		Ref. No.	Part No.	Description		Remarks	
IC390	8-759-636-55	IC M5218AFP-T1				R42	1-216-864-11	METAL CHIP	0	5%	1/16W
IC400	8-759-678-77	IC LA5643				R43	1-216-833-91	RES-CHIP	10K	5%	1/16W
IC440	8-759-822-09	IC LB1641				R44	1-216-864-11	METAL CHIP	0	5%	1/16W
IC480	8-759-633-42	IC M5293L				R45	1-216-833-91	RES-CHIP	10K	5%	1/16W
IC500	8-759-579-68	IC AK4524-TP				R49	1-216-833-91	RES-CHIP	10K	5%	1/16W
IC550	8-759-548-87	IC SN74LVU04ANSR				R50	1-216-864-11	METAL CHIP	0	5%	1/16W
IC600	8-759-548-87	IC SN74LVU04ANSR				R51	1-216-833-91	RES-CHIP	10K	5%	1/16W
IC611	8-749-012-70	IC GP1F38R (DIGITAL OPTICAL IN1)				R52	1-216-833-91	RES-CHIP	10K	5%	1/16W
IC621	8-749-012-70	IC GP1F38R (DIGITAL OPTICAL IN2) (CND,SP,MY)				R54	1-216-833-91	RES-CHIP	10K	5%	1/16W
IC661	8-749-012-69	IC GP1F38T (DIGITAL OPTICAL OUT) < JACK >				R67	1-216-833-91	RES-CHIP	10K	5%	1/16W
J150	1-784-429-11	JACK, PIN 4P (ANALOG IN/OUT)				R68	1-216-833-91	RES-CHIP	10K	5%	1/16W
J631	1-784-431-11	JACK, PIN 1P (DIGITAL COAXIAL IN) (AEP,UK,CIS)				R69	1-216-833-91	RES-CHIP	10K	5%	1/16W
J851	1-779-655-21	JACK (SMALL TYPE) (2 GANG) (CONTROL A1II) < COIL >				R70	1-216-833-91	RES-CHIP	10K	5%	1/16W
L349	1-216-296-91	SHORT	0			R90	1-216-845-11	METAL CHIP	100K	5%	1/16W
L390	1-216-296-91	SHORT	0			R114	1-216-845-11	METAL CHIP	100K	5%	1/16W
L490	1-216-296-91	SHORT	0			R115	1-216-845-11	METAL CHIP	100K	5%	1/16W
L506	1-414-265-21	INDUCTOR	4.7uH			R116	1-216-833-91	RES-CHIP	10K	5%	1/16W
L522	1-414-265-21	INDUCTOR	4.7uH			R123	1-216-833-91	RES-CHIP	10K	5%	1/16W
L523	1-216-296-91	SHORT	0			R124	1-216-833-91	RES-CHIP	10K	5%	1/16W
L524	1-216-296-91	SHORT	0			R129	1-216-833-91	RES-CHIP	10K	5%	1/16W
L550	1-414-265-21	INDUCTOR	4.7uH			R134	1-216-845-91	METAL CHIP	100K	5%	1/16W (EXCEPT CND)
L551	1-216-296-91	SHORT	0			R137	1-216-833-91	RES-CHIP	10K	5%	1/16W
L611	1-414-267-11	INDUCTOR	10uH			R138	1-216-833-91	RES-CHIP	10K	5%	1/16W
L661	1-414-267-11	INDUCTOR	10uH			R139	1-216-833-91	RES-CHIP	10K	5%	1/16W
L828	1-414-267-11	INDUCTOR	10uH			R141	1-216-833-91	RES-CHIP	10K	5%	1/16W
L829	1-414-267-11	INDUCTOR	10uH			R144	1-216-833-91	RES-CHIP	10K	5%	1/16W
		< TRANSISTOR >				R151	1-216-839-11	METAL CHIP	33K	5%	1/16W
Q1	8-729-421-22	TRANSISTOR UN2211-TX				R152	1-216-835-11	METAL CHIP	15K	5%	1/16W
Q2	8-729-120-28	TRANSISTOR 2SC1623-T1L5				R153	1-216-849-11	METAL CHIP	220K	5%	1/16W
Q3	8-729-421-22	TRANSISTOR UN2211-TX				R155	1-216-805-11	METAL CHIP	47	5%	1/16W
Q4	8-729-120-28	TRANSISTOR 2SC1623-T1L5				R161	1-216-833-91	RES-CHIP	10K	5%	1/16W
Q5	8-729-421-22	TRANSISTOR UN2211-TX				R162	1-216-833-91	RES-CHIP	10K	5%	1/16W
Q180	8-729-046-97	TRANSISTOR 2SD1938(F)-T(TX).SO				R163	1-216-833-91	RES-CHIP	10K	5%	1/16W
Q190	8-729-046-97	TRANSISTOR 2SD1938(F)-T(TX).SO				R164	1-216-833-91	RES-CHIP	10K	5%	1/16W
Q281	8-729-046-97	TRANSISTOR 2SD1938(F)-T(TX).SO				R165	1-216-837-11	METAL CHIP	22K	5%	1/16W
Q290	8-729-046-97	TRANSISTOR 2SD1938(F)-T(TX).SO				R166	1-216-837-11	METAL CHIP	22K	5%	1/16W
Q356	8-729-194-57	TRANSISTOR 2SC945TP-QP				R171	1-216-823-11	METAL CHIP	1.5K	5%	1/16W
Q380	8-729-424-08	TRANSISTOR UN2111-TX				R172	1-216-823-11	METAL CHIP	1.5K	5%	1/16W
Q440	8-729-421-22	TRANSISTOR UN2211-TX				R176	1-216-819-11	METAL CHIP	680	5%	1/16W
Q444	8-729-026-53	TRANSISTOR 2SA1576A-T106-QR				R177	1-216-845-11	METAL CHIP	100K	5%	1/16W
Q851	8-729-120-28	TRANSISTOR 2SC1623-T1L5				R178	1-216-815-11	METAL CHIP	330	5%	1/16W
Q910	8-729-119-78	TRANSISTOR 2SC2785TP-E				R181	1-216-833-91	RES-CHIP	10K	5%	1/16W
		< RESISTOR >				R190	1-216-833-91	RES-CHIP	10K	5%	1/16W
R1	1-216-833-91	RES-CHIP	10K	5%	1/16W	R191	1-216-805-11	METAL CHIP	47	5%	1/16W
R2	1-216-864-11	METAL CHIP	0	5%	1/16W	R192	1-216-805-11	METAL CHIP	47	5%	1/16W
R3	1-216-809-11	METAL CHIP	100	5%	1/16W	R251	1-216-839-11	METAL CHIP	33K	5%	1/16W
R4	1-216-864-11	METAL CHIP	0	5%	1/16W	R252	1-216-835-11	METAL CHIP	15K	5%	1/16W
R10	1-216-864-11	METAL CHIP	0	5%	1/16W	R253	1-216-849-11	METAL CHIP	220K	5%	1/16W
R24	1-216-833-91	RES-CHIP	10K	5%	1/16W	R255	1-216-805-11	METAL CHIP	47	5%	1/16W
R28	1-216-833-91	RES-CHIP	10K	5%	1/16W	R261	1-216-833-91	RES-CHIP	10K	5%	1/16W
R30	1-216-833-91	RES-CHIP	10K	5%	1/16W	R262	1-216-833-91	RES-CHIP	10K	5%	1/16W
R33	1-216-864-11	METAL CHIP	0	5%	1/16W	R263	1-216-833-91	RES-CHIP	10K	5%	1/16W
R38	1-216-864-11	METAL CHIP	0	5%	1/16W	R264	1-216-833-91	RES-CHIP	10K	5%	1/16W
		< RESISTOR >				R265	1-216-837-11	METAL CHIP	22K	5%	1/16W
		< RESISTOR >				R266	1-216-837-11	METAL CHIP	22K	5%	1/16W
		< RESISTOR >				R271	1-216-823-11	METAL CHIP	1.5K	5%	1/16W
		< RESISTOR >				R272	1-216-823-11	METAL CHIP	1.5K	5%	1/16W
		< RESISTOR >				R276	1-216-819-11	METAL CHIP	680	5%	1/16W
		< RESISTOR >				R277	1-216-845-11	METAL CHIP	100K	5%	1/16W

Ref. No.	Part No.	Description	Remarks	Ref. No.	Part No.	Description	Remarks
R278	1-216-815-11	METAL CHIP	330 5% 1/16W	R1034	1-216-833-91	RES-CHIP	10K 5% 1/16W
R280	1-216-833-91	RES-CHIP	10K 5% 1/16W	R1035	1-216-833-91	RES-CHIP	10K 5% 1/16W
R290	1-216-833-91	RES-CHIP	10K 5% 1/16W	R1036	1-216-833-91	RES-CHIP	10K 5% 1/16W
R291	1-216-805-11	METAL CHIP	47 5% 1/16W				< COMPOSITION CIRCUIT BLOCK >
R292	1-216-805-11	METAL CHIP	47 5% 1/16W				
△R301	1-219-786-11	FUSIBLE	22 5% 1/4W	RB102	1-236-908-11	NETWORK RESISTOR (CHIP) 10K	
△R306	1-219-786-11	FUSIBLE	22 5% 1/4W	RB106	1-236-908-11	NETWORK RESISTOR (CHIP) 10K	
R356	1-216-815-11	METAL CHIP	330 5% 1/16W	RB110	1-236-908-11	NETWORK RESISTOR (CHIP) 10K	
R357	1-216-822-11	METAL CHIP	1.2K 5% 1/16W	RB119	1-236-908-11	NETWORK RESISTOR (CHIP) 10K	
R380	1-216-845-11	METAL CHIP	100K 5% 1/16W				
R381	1-216-847-11	METAL CHIP	150K 5% 1/16W				< VIBRATOR >
R410	1-216-833-91	RES-CHIP	10K 5% 1/16W	X22	1-781-174-21	VIBRATOR, CERAMIC (10MHz)	
R413	1-216-833-91	RES-CHIP	10K 5% 1/16W	X550	1-781-998-11	VIBRATOR, CRYSTAL (45.1584MHz)	
R421	1-216-813-11	METAL CHIP	220 5% 1/16W				*****
R431	1-216-809-11	METAL CHIP	100 5% 1/16W				
R432	1-216-817-11	METAL CHIP	470 5% 1/16W		1-677-820-11	PT BOARD	
R433	1-216-816-11	METAL CHIP	390 5% 1/16W				*****
R441	1-216-837-11	METAL CHIP	22K 5% 1/16W				
R442	1-216-833-91	RES-CHIP	10K 5% 1/16W				< CAPACITOR >
R443	1-216-837-11	METAL CHIP	22K 5% 1/16W	△C900	1-113-920-11	CERAMIC	0.0022uF 20% 250V
R481	1-216-864-11	METAL CHIP	0 5% 1/16W	△C901	1-113-920-11	CERAMIC	0.0022uF 20% 250V
R483	1-216-813-11	METAL CHIP	220 5% 1/16W	△C910	1-113-920-11	CERAMIC	0.0022uF 20% 250V
R484	1-216-813-11	METAL CHIP	220 5% 1/16W	C920	1-164-159-11	CERAMIC	0.1uF 50V
R485	1-216-845-11	METAL CHIP	100K 5% 1/16W	C921	1-164-159-11	CERAMIC	0.1uF 50V
R486	1-216-837-11	METAL CHIP	22K 5% 1/16W	C922	1-164-159-11	CERAMIC	0.1uF 50V
R508	1-216-845-11	METAL CHIP	100K 5% 1/16W	C923	1-164-159-11	CERAMIC	0.1uF 50V
R511	1-216-805-11	METAL CHIP	47 5% 1/16W	C924	1-164-159-11	CERAMIC	0.1uF 50V
R512	1-216-805-11	METAL CHIP	47 5% 1/16W	C950	1-164-159-11	CERAMIC	0.1uF 50V
R513	1-216-805-11	METAL CHIP	47 5% 1/16W	C951	1-164-159-11	CERAMIC	0.1uF 50V
R514	1-216-805-11	METAL CHIP	47 5% 1/16W	C952	1-164-159-11	CERAMIC	0.1uF 50V
R515	1-216-809-11	METAL CHIP	100 5% 1/16W				< CONNECTOR >
R516	1-216-809-11	METAL CHIP	100 5% 1/16W	* CN900	1-580-230-11	PIN, CONNECTOR (PC BOARD) 2P	
R517	1-216-809-11	METAL CHIP	100 5% 1/16W				
R551	1-216-828-11	METAL CHIP	3.9K 5% 1/16W				
R552	1-216-817-11	METAL CHIP	470 5% 1/16W				< DIODE >
R553	1-216-815-11	METAL CHIP	330 5% 1/16W	D910	8-719-911-19	DIODE 1SS133T-72	
R613	1-216-853-11	METAL CHIP	470K 5% 1/16W				< LINE FILTER >
R614	1-216-841-11	METAL CHIP	47K 5% 1/16W	△LF900	1-424-485-11	FILTER, LINE	
R623	1-216-853-11	METAL CHIP	470K 5% 1/16W				
R624	1-216-841-11	METAL CHIP	47K 5% 1/16W				
R626	1-216-864-11	METAL CHIP	0 5% 1/16W				< RELAY >
R631	1-218-285-11	RES-CHIP	75 5% 1/16W	△RY910	1-755-356-11	RELAY	
R632	1-216-821-11	METAL CHIP	1K 5% 1/16W				
R821	1-216-833-91	RES-CHIP	10K 5% 1/16W				< POWER TRANSFORMER >
R822	1-216-833-91	RES-CHIP	10K 5% 1/16W	△TR900	1-435-540-11	TRANSFORMER, POWER (CND)	
R823	1-216-821-11	METAL CHIP	1K 5% 1/16W	△TR900	1-435-541-11	TRANSFORMER, POWER (AEP,UK,CIS)	
R824	1-216-821-11	METAL CHIP	1K 5% 1/16W	△TR900	1-435-542-11	TRANSFORMER, POWER (SP,MY)	
R825	1-216-829-11	METAL CHIP	4.7K 5% 1/16W	△TR950	1-435-547-11	TRANSFORMER, POWER (CND)	
R826	1-216-829-11	METAL CHIP	4.7K 5% 1/16W	△TR950	1-435-548-11	TRANSFORMER, POWER (AEP,UK,CIS)	
R851	1-216-830-11	METAL CHIP	5.6K 5% 1/16W	△TR950	1-435-549-11	TRANSFORMER, POWER (SP,MY)	
R852	1-216-829-11	METAL CHIP	4.7K 5% 1/16W				*****
R853	1-216-833-91	RES-CHIP	10K 5% 1/16W				
R854	1-216-797-11	METAL CHIP	10 5% 1/16W				
R855	1-216-864-11	METAL CHIP	0 5% 1/16W				
R856	1-216-864-11	METAL CHIP	0 5% 1/16W				
R911	1-216-829-11	METAL CHIP	4.7K 5% 1/16W				
R912	1-216-841-11	METAL CHIP	47K 5% 1/16W				
R1016	1-216-833-11	RES-CHIP	10K 5% 1/16W				

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<u>Ref. No.</u>	<u>Part No.</u>	<u>Description</u>	<u>Remarks</u>	<u>Ref. No.</u>	<u>Part No.</u>	<u>Description</u>	<u>Remarks</u>
	1-677-823-11	VOL-SEL BOARD (SP,MY)	*****			ACCESSORIES & PACKING MATERIALS	*****
		< CONNECTOR >				1-476-057-11 REMOTE COMMANDER (RM-D47M)	
* CN951	1-573-565-11	PIN, CONNECTOR 5P (SP,MY)				1-574-264-11 CORD, OPTICAL PLUG (AUDIO 60cm)	
		< SWITCH >				1-776-263-51 CORD, CONNECTION (AUDIO 100cm)	
△ S951	1-771-474-11	SWITCH, POWER (VOLTAGE SELECTOR)	(SP,MY)			1-777-172-11 CORD, CONNECTION (AUDIO 100cm)(CND)	
		*****				4-229-412-11 MANUAL, INSTRUCTION (SPANISH) (AEP)	
		MISCELLANEOUS	*****			4-229-412-21 MANUAL, INSTRUCTION (SWEDISH,DANISH,FINNISH) (AEP)	
8	1-792-812-11	WIRE (FLAT TYPE) (27 CORE)				4-229-412-31 MANUAL, INSTRUCTION (ITALIAN) (AEP)	
9	1-792-811-11	WIRE (FLAT TYPE) (23 CORE)				4-229-412-41 MANUAL, INSTRUCTION (PORTUGUESE) (AEP)	
△ 13	1-777-071-61	CORD, POWER (AEP,UK,CIS,SP,MY)				4-229-586-11 MANUAL, INSTRUCTION (ENGLISH) (CND,UK,CIS,SP,MY)	
△ 13	1-783-531-31	CORD, POWER (CND)				4-229-586-21 MANUAL, INSTRUCTION (FRENCH,GERMAN,DUTCH) (CND,AEP,SP,MY)	
16	1-569-972-21	SOCKET, SHORT 2P				4-229-586-31 MANUAL, INSTRUCTION (CHINESE) (SP,MY)	
△ 19	1-569-008-21	ADAPTOR, CONVERSION 2P (SP,MY)				4-229-586-41 MANUAL, INSTRUCTION (SPANISH) (SP,MY)	
△ 19	1-770-019-11	ADAPTOR, CONVERSION PLUG 3P (UK)				4-229-586-51 MANUAL, INSTRUCTION (POLISH,RUSSIAN) (CIS)	
63	1-792-814-11	WIRE (FLAT TYPE) (17 CORE)				4-229-724-01 CARD (KEYBOARD CHART LIST)	
257	1-678-514-11	FLEXIBLE BOARD				4-981-643-11 COVER, BATTERY (FOR RM-D47M)	
△ 258	A-4672-541-A	OPTICAL PICK-UP KMS-260B/J1N				*****	
FL780	1-517-987-11	INDICATOR TUBE, FLUORESCENT				HARDWARE LIST	*****
HR901	1-500-670-11	HEAD, OVER LIGHT			#1	7-685-646-79 SCREW +BVTP 3X8 TYPE2 TT(B)	
M101	A-4672-898-A	MOTOR ASSY, SPINDLE			#2	7-685-850-04 SCREW +BVTT 2X3 (S)	
M102	A-4672-900-A	MOTOR ASSY, SLED			#3	7-685-204-19 SCREW +KTP 2X6 TYPE2 NON-SLIT	
M103	A-4672-975-A	MOTOR ASSY, LOADING					
S102	1-771-957-11	SWITCH, PUSH (2 KEY)					
		(REFLECT/PROTECT SW)	*****				

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